

# MF1S50YYX\_V1

MIFARE Classic EV1 1K - Mainstream contactless smart card IC for fast and easy solution development

Rev. 3.2 — 23 May 2018  
279232

Product data sheet  
COMPANY PUBLIC

## 1 General description

NXP Semiconductors has developed the MIFARE Classic EV1 contactless IC MF1S50yyX/V1 to be used in a contactless smart card according to ISO/IEC 14443 Type A.

The MIFARE Classic EV1 with 1K memory MF1S50yyX/V1 IC is used in applications like public transport ticketing and can also be used for various other applications.

### 1.1 Anticollision

An intelligent anticollision function allows to operate more than one card in the field simultaneously. The anticollision algorithm selects each card individually and ensures that the execution of a transaction with a selected card is performed correctly without interference from another card in the field.

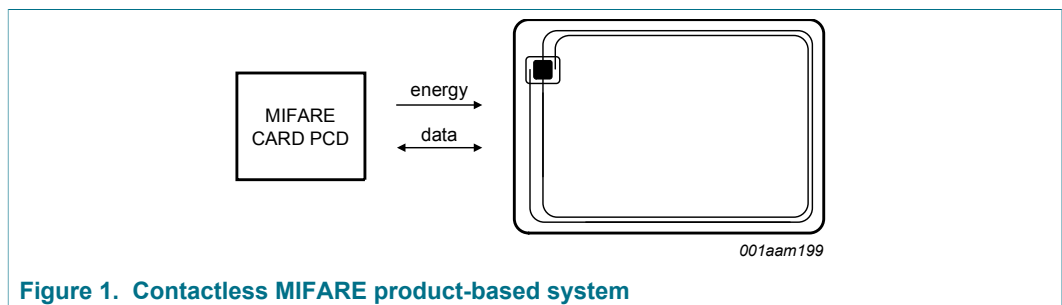


Figure 1. Contactless MIFARE product-based system

### 1.2 Simple integration and user convenience

The MF1S50yyX/V1 is designed for simple integration and user convenience which allows complete ticketing transactions to be handled in less than 100 ms.

### 1.3 Security and privacy

- Manufacturer programmed 7-byte UID or 4-byte NUID identifier for each device
- Random ID support
- Mutual three pass authentication (ISO/IEC DIS 9798-2)
- Individual set of two keys per sector to support multi-application with key hierarchy

### 1.4 Delivery options

- 7-byte UID, 4-byte NUID
- Bumped die on sawn wafer



# MF3ICDx21\_41\_81

## MIFARE DESFire EV1 contactless multi-application IC

Rev. 3.2 — 9 December 2015  
145632

Product short data sheet  
COMPANY PUBLIC

### 1. General description

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MIFARE DESFire EV1 (MF3ICD(H) 21/41/81), a Common Criteria (EAL4+) certified product, is ideal for service providers wanting to use secure multi-application smart cards in public transport schemes, access management or closed-loop e-payment applications. It fully complies with the requirements for fast and highly secure data transmission, flexible memory organization and interoperability with existing infrastructure.

MIFARE DESFire EV1 is based on open global standards for both air interface and cryptographic methods. It is compliant to all 4 levels of ISO/IEC 14443A and uses optional ISO/IEC 7816-4 commands.

Featuring an on-chip backup management system and the mutual three-pass authentication, a MIFARE DESFire EV1 card can hold up to 28 different applications and 32 files per application. The size of each file is defined at the moment of its creation, making MIFARE DESFire EV1 a truly flexible and convenient product.

Additionally, an automatic anti-tear mechanism is available for all file types, which guarantees transaction-oriented data integrity. With MIFARE DESFire EV1, data transfer rates up to 848 kbit/s can be achieved, allowing fast data transmission.

The main characteristics of this device are denoted by its name “DESFire”: DES indicates the high level of security using a 3DES or AES hardware cryptographic engine for enciphering transmission data and Fire indicates its outstanding position as a fast, innovative, reliable and secure IC in the contactless proximity transaction market. Hence, MIFARE DESFire EV1 brings many benefits to end users. Cardholders can experience convenient contactless ticketing while also having the possibility to use the same device for related applications such as payment at vending machines, access control or event ticketing. In other words, the MIFARE DESFire EV1 silicon solution offers enhanced consumer-friendly system design, in combination with security and reliability.

MIFARE DESFire EV1 delivers the perfect balance of speed, performance and cost efficiency. Its open concept allows future seamless integration of other ticketing media such as smart paper tickets, key fobs, and mobile ticketing based on Near Field Communication (NFC) technology. It is also fully compatible with the existing MIFARE reader hardware platform. MIFARE DESFire EV1 is your ticket to contactless systems worldwide.



## 2. Features and benefits

### 2.1 RF interface: ISO/IEC 14443 Type A

- Contactless transmission of data and powered by the RF-field (no battery needed)
- Operating distance: up to 100 mm (depending on power provided by the PCD and antenna geometry)
- Operating frequency: 13.56 MHz
- Fast data transfer: 106 kbit/s, 212 kbit/s, 424 kbit/s, 848 kbit/s
- High data integrity: 16/32 bit CRC, parity, bit coding, bit counting
- True deterministic anticollision
- 7 bytes unique identifier (cascade level 2 according to ISO/IEC 14443-3 and option for random ID)
- Uses ISO/IEC 14443-4 protocol

### 2.2 ISO/IEC 7816 compatibility

- Supports ISO/IEC 7816-3 APDU message structure
- Supports ISO/IEC 7816-4 INS code 'A4' for SELECT FILE
- Supports ISO/IEC 7816-4 INS code 'B0' for READ BINARY
- Supports ISO/IEC 7816-4 INS code 'D6' for UPDATE BINARY
- Supports ISO/IEC 7816-4 INS code 'B2' for READ RECORDS
- Supports ISO/IEC 7816-4 INS code 'E2' for APPEND RECORD
- Supports ISO/IEC 7816-4 INS code '84' for GET CHALLENGE
- Supports ISO/IEC 7816-4 INS code '88' for INTERNAL AUTHENTICATE
- Supports ISO/IEC 7816-4 INS code '82' for EXTERNAL AUTHENTICATE

### 2.3 Non-volatile memory

- 2 kB or 4 kB or 8 kB NV-Memory
- Data retention of 10 years
- Write endurance typical 500 000 cycles

### 2.4 NV-memory organization

- Flexible file system
- Up to 28 applications simultaneously on one PICC
- Up to 32 files in each application (standard data file, back-up data file, value file, linear record file and cyclic record file)
- File size is determined during creation

### 2.5 Security

- Common Criteria Certification: EAL4+ (Hardware and Software)
- Unique 7 bytes serial number for each device
- Optional "RANDOM" ID for enhance security and privacy
- Mutual three-pass authentication
- Mutual authentication according to ISO/IEC 7816-4

- 1 card master key and up to 14 keys per application
- Hardware DES using 56/112/168 bit keys featuring key version, data authenticity by 8 byte CMAC
- Hardware AES using 128-bit keys featuring key version, data authenticity by 8 byte CMAC
- Data encryption on RF-channel
- Authentication on application level
- Hardware exception sensors
- Self-securing file system
- Backward compatibility to MF3ICD40: 4 byte MAC, CRC 16

## 2.6 Special features

- Transaction-oriented automatic anti-tear mechanism
- Configurable ATS information for card personalization
- Backward compatibility mode to MF3ICD40
- Optional high input capacitance (70 pF) for small form factor design (MF3ICDH 21/41/81)

## 3. Applications

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- Advanced public transportation schema
- Highly secure access management
- Closed-loop e-payment scheme
- Event ticketing
- eGovernment applications

## 4. Quick reference data

Table 1. Quick reference data [1][2]

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$f_i$	input frequency		-	13.56	-	MHz
$C_i$	input capacitance for MF3ICD21/41/81	$T_{amb} = 22\text{ °C}$ ; $f_i = 13.56\text{ MHz}$ ; 2.8 V RMS	[3] 14.96	17.0	19.04	pF
	input capacitance for MF3ICDH21/41/81		64	69	74	pF
<b>EEPROM characteristics</b>						
$t_{ret}$	retention time	$T_{amb} = 22\text{ °C}$	10	-	-	year
$N_{endu(W)}$	write endurance	$T_{amb} = 22\text{ °C}$	200000	500000	-	cycle
$t_{cy(W)}$	write cycle time	$T_{amb} = 22\text{ °C}$	-	2.9	-	ms

[1] Stresses above one or more of the values may cause permanent damage to the device.

[2] Exposure to limiting values for extended periods may affect device reliability.

[3] Measured with LCR meter.

## 5. Ordering information

Table 2. Ordering information

Type number	Package		Version
	Name	Description	
MF3ICD8101DUD/05	FFC	8 inch wafer (sawn; 120 $\mu\text{m}$ thickness, on film frame carrier; electronic fail die marking according to SECSII format); see <a href="#">Ref. 4</a> , 8K EEPROM, 17pF input capacitance	-
MF3ICD4101DUD/05	FFC	8 inch wafer (sawn; 120 $\mu\text{m}$ thickness, on film frame carrier; electronic fail die marking according to SECSII format); see <a href="#">Ref. 4</a> , 4K EEPROM, 17pF input capacitance	-
MF3ICD2101DUD/05	FFC	8 inch wafer (sawn; 120 $\mu\text{m}$ thickness, on film frame carrier; electronic fail die marking according to SECSII format); see <a href="#">Ref. 4</a> , 2K EEPROM, 17pF input capacitance	-
MF3ICDH8101DUD/05	FFC	8 inch wafer (sawn; 120 $\mu\text{m}$ thickness, on film frame carrier; electronic fail die marking according to SECSII format); see <a href="#">Ref. 5</a> , 8K EEPROM, 70pF input capacitance	-
MF3ICDH4101DUD/05	FFC	8 inch wafer (sawn; 120 $\mu\text{m}$ thickness, on film frame carrier; electronic fail die marking according to SECSII format); see <a href="#">Ref. 5</a> , 4K EEPROM, 70pF input capacitance	-
MF3ICDH2101DUD/05	FFC	8 inch wafer (sawn; 120 $\mu\text{m}$ thickness, on film frame carrier; electronic fail die marking according to SECSII format); see <a href="#">Ref. 5</a> , 2K EEPROM, 70pF input capacitance	-
MF3MOD8101DA4/05	PLLMC[1]	plastic leadless module carrier package; 35 mm wide tape; see <a href="#">Ref. 6</a> , 8K EEPROM, 17pF input capacitance	SOT500-2
MF3MOD4101DA4/05	PLLMC[1]	plastic leadless module carrier package; 35 mm wide tape; see <a href="#">Ref. 6</a> , 4K EEPROM, 17pF input capacitance	SOT500-2
MF3MOD2101DA4/05	PLLMC[1]	plastic leadless module carrier package; 35 mm wide tape; see <a href="#">Ref. 6</a> , 2K EEPROM, 17pF input capacitance	SOT500-2
MF3MODH8101DA4/05	PLLMC[1]	plastic leadless module carrier package; 35 mm wide tape; see <a href="#">Ref. 6</a> , 8K EEPROM, 70pF input capacitance	SOT500-2

Table 2. Ordering information *?continued*

Type number	Package		Version
	Name	Description	
MF3MODH4101DA4/05	PLLMC <sup>[1]</sup>	plastic leadless module carrier package; 35 mm wide tape; see <a href="#">Ref. 6</a> , 4K EEPROM, 70pF input capacitance	SOT500-2
MF3MODH2101DA4/05	PLLMC <sup>[1]</sup>	plastic leadless module carrier package; 35 mm wide tape; see <a href="#">Ref. 6</a> , 2K EEPROM, 70pF input capacitance	SOT500-2
MF3MOD8101DA8/05	PLLMC <sup>[2]</sup>	plastic leadless module carrier package; 35 mm wide tape; see <a href="#">Ref. 6</a> , 8K EEPROM, 17pF input capacitance	SOT500-4
MF3MOD4101DA8/05	PLLMC <sup>[2]</sup>	plastic leadless module carrier package; 35 mm wide tape; see <a href="#">Ref. 6</a> , 4K EEPROM, 17pF input capacitance	SOT500-4
MF3MOD2101DA8/05	PLLMC <sup>[2]</sup>	plastic leadless module carrier package; 35 mm wide tape; see <a href="#">Ref. 6</a> , 2K EEPROM, 17pF input capacitance	SOT500-4
MF3MODH8101DA8/05	PLLMC <sup>[2]</sup>	plastic leadless module carrier package; 35 mm wide tape; see <a href="#">Ref. 6</a> , 8K EEPROM, 70pF input capacitance	SOT500-4
MF3MODH4101DA8/05	PLLMC <sup>[2]</sup>	plastic leadless module carrier package; 35 mm wide tape; see <a href="#">Ref. 6</a> , 4K EEPROM, 70pF input capacitance	SOT500-4
MF3MODH2101DA8/05	PLLMC <sup>[2]</sup>	plastic leadless module carrier package; 35 mm wide tape; see <a href="#">Ref. 6</a> , 2K EEPROM, 70pF input capacitance	SOT500-4

- [1] This package is also known as MOA4.
- [2] This package is also known as MOA8

## 6. Block diagram

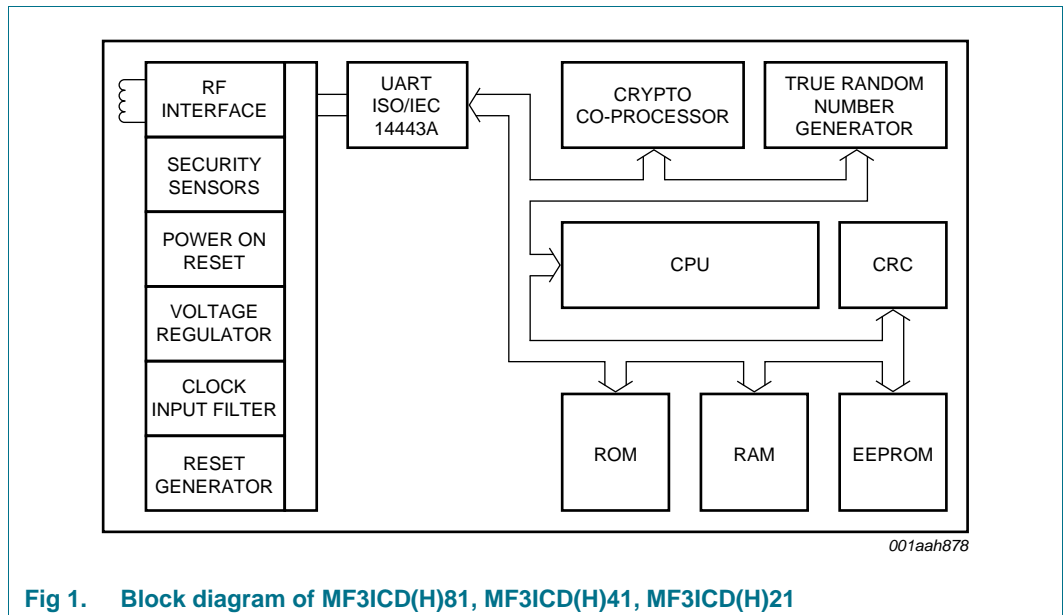


Fig 1. Block diagram of MF3ICD(H)81, MF3ICD(H)41, MF3ICD(H)21

## 7. Limiting values

**Table 3. Limiting values** [\[1\]](#)[\[2\]](#)

*In accordance with the Absolute Maximum Rating System (IEC 60134).*

Symbol	Parameter	Conditions	Min	Max	Unit
$I_I$	input current		-	30	mA
$P_{tot}/pack$	total power dissipation per package		-	200	mW
$T_{stg}$	storage temperature		-55	125	°C
$T_{amb}$	ambient temperature		-25	70	°C
$V_{ESD}$	electrostatic discharge voltage		<a href="#">[3]</a> 2	-	kV
$I_{lu}$	latch-up current		±100	-	mA

[1] Stresses above one or more of the limiting values may cause permanent damage to the device.

[2] Exposure to limiting values for extended periods may affect device reliability.

[3] MIL Standard 883-C method 3015; human body model: C = 100 pF, R = 1.5 kΩ.

## 8. Functional description

### 8.1 Contactless energy and data transfer

In the MIFARE system, the MIFARE DESFire EV1 is connected to a coil consisting of a few turns embedded in a standard ISO/IEC smart card (see [Ref. 8](#)). A battery is not needed. When the card is positioned in the proximity of the PCD antenna, the high-speed RF communication interface allows data to be transmitted up to 848 kbit/s.

### 8.2 Anti-collision

An intelligent anti-collision mechanism allows more than one MIFARE DESFire EV1 in the field to be handled simultaneously. The anti-collision algorithm selects each MIFARE DESFire EV1 individually and ensures that the execution of a transaction with a selected MIFARE DESFire EV1 is performed correctly without data corruption resulting from other MIFARE DESFire EV1s in the field.

### 8.3 UID/serial number

The unique 7 byte (UID) is programmed into a locked part of the NV memory which is reserved for the manufacturer. Due to security and system requirements these bytes are write-protected after being programmed by the IC manufacturer at production time. According to ISO/IEC 14443-3 (see [Ref. 12](#)) during the first anti-collision loop the cascade tag returns a value of 88h and also the first 3 bytes of the UID, UID0 to UID2 and BCC. The second anti-collision loop returns bytes UID3 to UID6 and BCC.

UID0 holds the manufacturer ID for NXP (04h) according to ISO/IEC 14443-3 and ISO/IEC 7816-6 AMD 1.

MIFARE DESFire EV1 also allows Random ID to be used. In this case MIFARE DESFire EV1 only uses a single anti-collision loop. The 3 byte random number is generated after RF reset of the MIFARE DESFire EV1.

### 8.4 Memory organization

The 2/4/8 KB NV memory is organized using a flexible file system. This file system allows a maximum of 28 different applications on one MIFARE DESFire EV1. Each application provides up to 32 files. Every application is represented by its 3 bytes Application Identifier (AID).

Five different file types are supported; see [Section 8.5](#).

A guideline to assign MIFARE DESFire AIDs can be found in the application note *MIFARE Application Directory (MAD)*; see [Ref. 9](#).

Each file can be created either at MIFARE DESFire EV1 initialization (card production/card printing), at MIFARE DESFire EV1 personalization (vending machine) or in the field.

If a file or application becomes obsolete in operation, it can be permanently invalidated.

Commands which have impact on the file structure itself (e.g. creation or deletion of applications, change of keys) activate an automatic rollback mechanism, which protects the file structure from being corrupted.



If this rollback is necessary, it is done without user interaction before carrying out further commands. To ensure data integrity on application level, a transaction-oriented backup is implemented for all file types with backup. It is possible to mix file types with and without backup within one application.

As the commands are the same for MF3ICD(H)81, MF3ICD(H)41 and MF3ICD(H)21, the command details are available in [Ref. 1](#). Only the memory size and input capacitance are different between the devices.

## 8.5 Available file types

The files within an application can be any of the following types:

- Standard data files
- Backup data files
- Value files with backup
- Linear record files with backup
- Cyclic record files with backup

## 8.6 Security

The 7 byte UID is fixed, programmed into each device during production. It cannot be altered and ensures the uniqueness of each device.

The UID may be used to derive diversified keys for each ticket. Diversified MIFARE DESFire EV1 keys contribute to gain an effective anti-cloning mechanism and increase the security of the original key; see [Ref. 7](#).

Prior to data transmission a mutual three-pass authentication can be done between MIFARE DESFire EV1 and PCD depending on the configuration employing either 56-bit DES (single DES, DES), 112-bit 3DES (triple DES, 2K3DES), 168-bit 3DES (3 key triple DES, 3K3DES) or AES. During the authentication the level of security of all further commands during the session is set. In addition, the communication settings of the file/application result in the following options of secure communication between MIFARE DESFire EV1 and PCD:

- Plain data transfer (only possible within the backwards-compatible mode to MF3ICD40)
- Plain data transfer with cryptographic checksum (MAC): Authentication with backwards-compatible mode to MF3ICD40: 4 byte MAC, all other authentications based on DES/3DES/AES: 8 byte CMAC
- Encrypted data transfer (secured by CRC before encryption): Authentication with backwards-compatible mode to MF3ICD40: A 16-bit CRC is calculated over the stream and attached. The resulting stream is encrypted using the chosen cryptographic method. All other authentications-based DES/3DES/AES: A 32-bit CRC is calculated over the stream and attached. The resulting stream is encrypted using the chosen cryptographic method.

Find more information on the security concept of the product in [Ref. 1](#). Be aware not all levels of security are recommended. The recommended secure handling of the product can be seen in [Ref. 2](#) and in [Ref. 11](#).

## 9. DESFire command set

A detailed description of all commands is provided in [Ref. 1](#).

### 9.1 ISO/IEC 14443-3

Table 4. ISO/IEC 14443-3

Command	Description
REQA	REQA and ATQA are implemented fully according to ISO/IEC 14443-3
WUPA	WUPA is implemented fully according to ISO/IEC 14443-3
ANTICOLLISION/SELECT Cascade Level 1	ANTICOLLISION and SELECT commands are implemented fully according to ISO/IEC 14443-3; the response is part 1 of the UID
ANTICOLLISION/SELECT Cascade Level 2	ANTICOLLISION and SELECT commands are implemented fully according to ISO/IEC 14443-3; the response is part 2 of the UID
HALT	brings MIFARE DESFire EV1 to the HALT state

### 9.2 ISO/IEC 14443-4

Table 5. ISO/IEC 14443-4

Command	Description
RATS	identifies the MIFARE DESFire EV1 type to the PCD
PPS	allows individual selection of the communication baud rate between PCD and MIFARE DESFire EV1; for DESFire it is possible to set different communication baud rates for each direction i.e. DESFire allows a non-symmetrical information interchange speed.
WTX	if the MIFARE DESFire EV1 needs more time than the defined FWT to respond to a PCD command it requests a Waiting Time eXtension (WTX)
DESELECT	allows MIFARE DESFire EV1 to be brought to the HALT state

### 9.3 MIFARE DESFire EV1 command set overview – security related commands

Table 6. Security related commands

Command	Description
Authenticate	MIFARE DESFire EV1 and the reader device show in an encrypted way that they possess the same secret which especially means the same key; this not only confirms that both entities are permitted to perform operations on each other but also creates a session key which can be used to keep the further communication path secure; as the name “session key” implicitly indicates, each time a new authentication procedure is successfully completed a new key for further cryptographic operations is generated
Change KeySettings	changes the master key settings on MIFARE DESFire EV1 and application level
Set Configuration	configures the card and pre-personalizes the card with a key, defines if the UID or the random ID is sent back during communication setup and configures the ATS string
Change Key	changes any key stored on the MIFARE DESFire EV1
Get Key Version	reads out the current key version of any key stored on the MIFARE DESFire EV1

**Remark:** All command and data frames are exchanged between MIFARE DESFire EV1 and PCD by using block format as defined in ISO/IEC 14443-4.

### 9.4 MIFARE DESFire EV1 command set overview – MIFARE DESFire EV1 level commands

Table 7. Level commands

Command	Description
Create Application	creates new applications on the MIFARE DESFire EV1
Delete Application	permanently deactivates applications on the MIFARE DESFire EV1
Get Applications IDs	returns the Application IDentifiers of all applications on a MIFARE DESFire EV1
Free Memory	returns the free memory available on the card
GetDFNames	returns the DF names
Get KeySettings	gets information on the MIFARE DESFire EV1 and application master key settings; in addition it returns the maximum number of keys which are configured for the selected application
Select Application	selects one specific application for further access
FormatMF3ICD81	releases the MF3ICD81 user memory
Get Version	returns manufacturing related data of the MIFARE DESFire EV1
GetCardUID	returns the UID

**Remark:** All command and data frames are exchanged between MIFARE DESFire EV1 and PCD by using block format as defined in ISO/IEC 14443-4.

### 9.5 MIFARE DESFire EV1 command set overview – application level commands

Table 8. Application level commands

Command	Description
Get FileIDs	returns the File IDentifiers of all active files within the currently selected application
Get FileSettings	gets information on the properties of a specific file
Change FileSettings	changes the access parameters of an existing file
Create StdDataFile	creates files for the storage of plain unformatted user data within an existing application on the MIFARE DESFire EV1
Create BackupDataFile	creates files for the storage of plain unformatted user data within an existing application on the MIFARE DESFire EV1, additionally supporting the feature of an integrated backup mechanism
Create ValueFile	creates files for the storage and manipulation of 32-bit signed integer values within an existing application on the MIFARE DESFire EV1
Create LinearRecordFile	creates files for multiple storage of similar structural data, for example, loyalty programs within an existing application on the MIFARE DESFire EV1; once the file is filled completely with data records, further writing to the file is not possible unless it is cleared
Create CyclicRecordFile	creates files for multiple storage of similar structural data, for example, logging transactions within an existing application on the MIFARE DESFire EV1; once the file is filled completely with data records, the MIFARE DESFire EV1 automatically overwrites the oldest record with the latest written one (this wrap is fully transparent for the PCD)
DeleteFile	permanently deactivates a file within the file directory of the currently selected application

**Remark:** All command and data frames are exchanged between MIFARE DESFire EV1 and PCD by using block format as defined in ISO/IEC 14443-4.

### 9.6 MIFARE DESFire EV1 command set overview – data manipulation commands

Table 9. Data manipulation commands

Command	Description
Read Data	reads data from Standard Data files or Backup Data files
Write Data	writes data to Standard Data files or Backup Data files
Get Value	reads the currently stored value from Value files
Credit	increases a value stored in a Value file
Debit	decreases a value stored in a Value file
Limited Credit	allows a limited increase of a value stored in a Value file without having full Credit permissions to the file
Write Record	writes data to a record in a Cyclic or Linear Record file
Read Records	reads out a set of complete records from a Cyclic or Linear Record file

Table 9. Data manipulation commands *?continued*

Command	Description
Clear RecordFile	resets a Cyclic or Linear Record file to empty state
Commit Transaction	validates all previous write accesses on Backup Data files, Value files and Record files within one application
Abort Transaction	invalidates all previous write accesses on Backup Data files, Value files and Record files within one application

**Remark:** All command and data frames are exchanged between MIFARE DESFire EV1 and PCD by using block format as defined in ISO/IEC 14443-4.

## 9.7 MIFARE DESFire EV1 command set - ISO/IEC 7816 APDU commands

The MIFARE DESFire EV1 provides the following commands according to ISO/IEC 7816-4:

- INS code 'A4' SELECT
- INS code 'B0' READ BINARY
- INS code 'D6' UPDATE BINARY
- INS code 'B2' READ RECORDS
- INS code 'E2' APPEND RECORD
- INS code '84' GET CHALLENGE
- INS code '88' INTERNAL AUTHENTICATE
- INS code '82' EXTERNAL AUTHENTICATE

### 9.7.1 ISO/IEC 7816-4 APDU message structure

MIFARE DESFire EV1 supports the APDU message structure according to ISO/IEC 7816-4 for:

- an optional wrapping of the native MIFARE DESFire EV1 APDU format
- additionally implemented ISO/IEC 7816-4 commands

Find more information on the ISO/IEC 7816-4 commands in [Ref. 1](#).

## 10. Abbreviations

Table 10. Abbreviations

Acronym	Description
AES	Advanced Encryption Standard
AID	Application Identifier
APDU	Application Protocol Data Unit
ATS	Answer to Select
CC	Common Criteria
CMAC	Cryptic Message Authentication Code
CRC	Cyclic Redundancy Check
DES	Digital Encryption Standard
DF	Dedicated File
EAL	Evaluation Assurance Level
EEPROM	Electrically Erasable Programmable Read-Only Memory
FWT	Frame Waiting Time
ID	Identifier
INS	Instructions
LCR	inductance, Capacitance, Resistance
MAC	Message Authentication Code
MAD	MIFARE Application Directory
NV	Non-Volatile Memory
PCD	Proximity Coupling Device
PPS	Protocol Parameter Selection
RATS	Request Answer To Select
REQA	Request Answer
RF	Radio Frequency
UID	Unique Identifier
WTX	Waiting Time eXtension
WUPA	Wake Up Protocol A

## 11. References

- [1] **Data sheet** — *MF3ICD81 MIFARE DESFire EV1*, document number: 13403\*\*1.
- [2] **Data sheet** — *MF3ICD81 Guidance, Delivery and Operation Manual*, document number: 1469\*\*.
- [3] **Data sheet** — *Specification addendum MF3ICD81*, document number: 1673\*\*.
- [4] **Data sheet** — *MF3ICD8101 Sawn bumped 120 μm wafer addendum*, document number: 1318\*\*.
- [5] **Data sheet** — *MF3ICDH8101 Sawn bumped 120 μm wafer addendum*, document number: 1970\*\*.
- [6] **Data sheet** — *MF3MODx21\_41\_81 Contactless chip card module*, document number: 1439\*\*.
- [7] **Application note** — *MIFARE DESFire - Implementation hints and examples*, document number: 0945\*\*.
- [8] **Application note** — *Card Coil Design Notes for MIFARE DESFire EV1*, document number: 1713\*\*.
- [9] **Application note** — *MIFARE Application Directory*, document number: 0018\*\*.
- [10] **Application note** — *MIFARE ISO/IEC 14443 PICC Selection*, document number: 1308\*\*.
- [11] **Application note** — *End to end system security risk considerations for implementing contactless cards*, document number: 1550\*\*.
- [12] **ISO/IEC Standard** — *ISO/IEC 14443 Identification cards - Contactless integrated circuit cards - Proximity cards*.

1. \*\* ... BU-ID document version number

## 12. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
MF3ICDX21_41_81_SDS v3.2	20151209	Product short data sheet	-	MF3ICDX21_41_81_SDS v3.1
Modifications:	<ul style="list-style-type: none"> <li>• <a href="#">Section 5</a>: MOA8 types added</li> </ul>			
MF3ICDX21_41_81_SDS v3.1	20101221	Product short data sheet	-	MF3ICD21_41_81_SDS_2
Modifications:	<ul style="list-style-type: none"> <li>• Data sheet title updated</li> <li>• <a href="#">Section 1</a>, <a href="#">Section 2</a>, <a href="#">Section 3</a>, <a href="#">Section 11</a>, <a href="#">Section 13</a>: updated</li> <li>• <a href="#">Section 5</a>: type number MF3ICD801DUD/04 changed to MF3ICD8101DUD/05</li> </ul>			
MF3ICD21_41_81_SDS_2	20090306	Product short data sheet	-	MF3ICD8101_SDS_N_1
Modifications:	<ul style="list-style-type: none"> <li>• Section 5 "Ordering information": type number MF3ICD8101DUD/01 changed to MF3ICD8101DUD/04</li> <li>• Section 5 "Ordering information": added root type numbers MF3ICD41 and MF3ICD21</li> <li>• Section 1 "General description", Section 2 "Features and benefits" and Section 3 "Applications": updated</li> <li>• Section 11 "References": added</li> </ul>			
MF3ICD8101_SDS_N_1	20071213	Objective short data sheet	-	-



## 13. Legal information

### 13.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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Please be aware that important notices concerning this document and the product(s) described herein, have been included in section 'Legal information'.

- MOA4 and MOA8 contactless module

## 2 Features and benefits

- Contactless transmission of data and energy supply
- Operating frequency of 13.56 MHz
- Data integrity of 16-bit CRC, parity, bit coding, bit counting
- Typical ticketing transaction time of < 100 ms (including backup management)
- Random ID support (7 Byte UID version)
- Operating distance up to 100 mm depending on antenna geometry and reader configuration
- Data transfer of 106 kbit/s
- Anticollision
- 7 Byte UID or 4 Byte NUID
- NXP Originality Check support

### 2.1 EEPROM

- 1 kB, organized in 16 sectors of 4 blocks (one block consists of 16 byte)
- Data retention time of 10 years
- User definable access conditions for each memory block
- Write endurance 200000 cycles

## 3 Applications

- Public transportation
- Electronic toll collection
- School and campus cards
- Internet cafés
- Access management
- Car parking
- Employee cards
- Loyalty

## 4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
C <sub>i</sub>	input capacitance		[1]	14.9	16.9	19.0	pF
f <sub>i</sub>	input frequency			-	13.56	-	MHz
<b>EEPROM characteristics</b>							
t <sub>ret</sub>	retention time	T <sub>amb</sub> = 22 °C		10	-	-	year
N <sub>endu(W)</sub>	write endurance	T <sub>amb</sub> = 22 °C		100000	200000	-	cycle

[1] T<sub>amb</sub>=22°C, f=13,56Mhz, V<sub>LdLb</sub> = 1,5 V RMS

## 5 Ordering information

Table 2. Ordering information

Type number	Package		Version
	Name	Description	
MF1S5001XDUD/V1	FFC Bump	8 inch wafer, 120 µm thickness, on film frame carrier, electronic fail die marking according to SECS-II format), Au bumps, 7-byte UID	-
MF1S5001XDUD2/V1	FFC Bump	12 inch wafer, 120 µm thickness, on film frame carrier, electronic fail die marking according to SECS-II format), Au bumps, 7-byte UID	-
MF1S5001XDUF/V1	FFC Bump	8 inch wafer, 75 µm thickness, on film frame carrier, electronic fail die marking according to SECS-II format), Au bumps, 7-byte UID	-
MF1S5000XDA4/V1	MOA4	plastic leadless module carrier package; 35 mm wide tape, 7-byte UID	SOT500-2
MF1S5000XDA8/V1	MOA8	plastic leadless module carrier package; 35 mm wide tape, 7-byte UID	SOT500-4
MF1S5031XDUD/V1	FFC Bump	8 inch wafer, 120 µm thickness, on film frame carrier, electronic fail die marking according to SECS-II format), Au bumps, 4-byte non-unique ID	-
MF1S5031XDUD2/V1	FFC Bump	12 inch wafer, 120 µm thickness, on film frame carrier, electronic fail die marking according to SECS-II format), Au bumps, 4-byte non-unique ID	-
MF1S5031XDUF/V1	FFC Bump	8 inch wafer, 75 µm thickness, on film frame carrier, electronic fail die marking according to SECS-II format), Au bumps, 4-byte non-unique ID	-
MF1S5030XDA4/V1	MOA4	plastic leadless module carrier package; 35 mm wide tape, 4-byte non-unique ID	SOT500-2
MF1S5030XDA8/V1	MOA8	plastic leadless module carrier package; 35 mm wide tape, 4-byte non-unique ID	SOT500-4

## 6 Block diagram

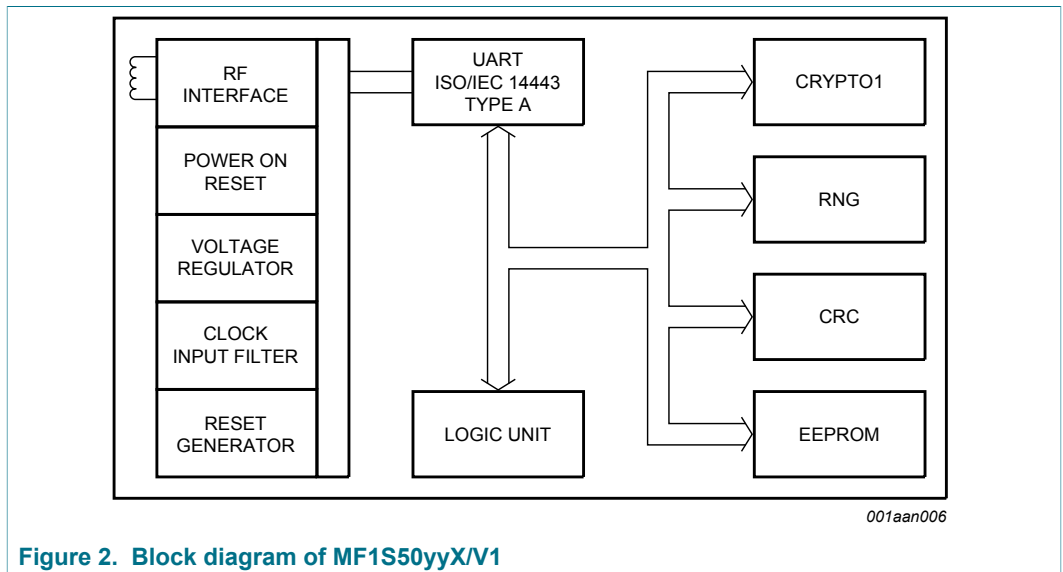


Figure 2. Block diagram of MF1S50yyX/V1

## 7 Pinning information

### 7.1 Pinning

The pinning for the MF1S50yyX/V1DAx is shown as an example in [Figure 3](#) for the MOA4 contactless module. For the contactless module MOA8, the pinning is analogous and not explicitly shown.

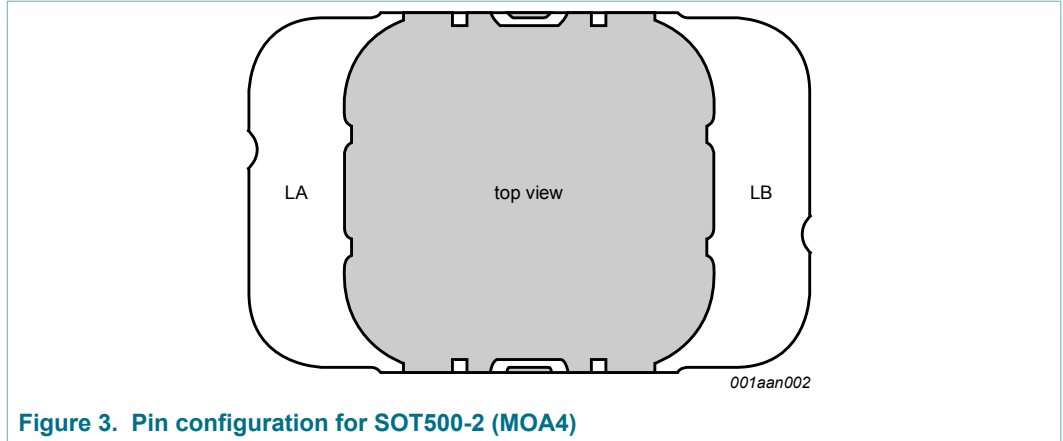


Figure 3. Pin configuration for SOT500-2 (MOA4)

Table 3. Pin allocation table

Pin	Symbol	
LA	LA	Antenna coil connection LA
LB	LB	Antenna coil connection LB

## 8 Functional description

### 8.1 Block description

The MF1S50yyX/V1 chip consists of a 1 kB EEPROM, RF interface and Digital Control Unit. Energy and data are transferred via an antenna consisting of a coil with a small number of turns which is directly connected to the MF1S50yyX/V1. No further external components are necessary. Refer to the document [Ref. 1](#) for details on antenna design.

- RF interface:
  - Modulator/demodulator
  - Rectifier
  - Clock regenerator
  - Power-On Reset (POR)
  - Voltage regulator
- Anticollision: Multiple cards in the field may be selected and managed in sequence
- Authentication: Preceding any memory operation the authentication procedure ensures that access to a block is only possible via the two keys specified for each block

- Control and Arithmetic Logic Unit: Values are stored in a special redundant format and can be incremented and decremented
- EEPROM interface
- Crypto unit: The CRYPTO1 stream cipher of the MF1S50yyX/V1 is used for authentication and encryption of data exchange.
- EEPROM: 1 kB is organized in 16 sectors of 4 blocks. One block contains 16 bytes. The last block of each sector is called "trailer", which contains two secret keys and programmable access conditions for each block in this sector.

## 8.2 Communication principle

The commands are initiated by the reader and controlled by the Digital Control Unit of the MF1S50yyX/V1. The command response is depending on the state of the IC and for memory operations also on the access conditions valid for the corresponding sector.

### 8.2.1 Request standard / all

After Power-On Reset (POR) the card answers to a request REQA or wakeup WUPA command with the answer to request code (see [Section 9.4](#), ATQA according to ISO/IEC 14443A).

### 8.2.2 Anticollision loop

In the anticollision loop the identifier of a card is read. If there are several cards in the operating field of the reader, they can be distinguished by their identifier and one can be selected (select card) for further transactions. The unselected cards return to the idle state and wait for a new request command. If the 7-byte UID is used for anticollision and selection, two cascade levels need to be processed as defined in ISO/IEC 14443-3.

**Remark:** For the 4-byte non-unique ID product versions, the identifier retrieved from the card is not defined to be unique. For further information regarding handling of non-unique identifiers see [Ref. 6](#).

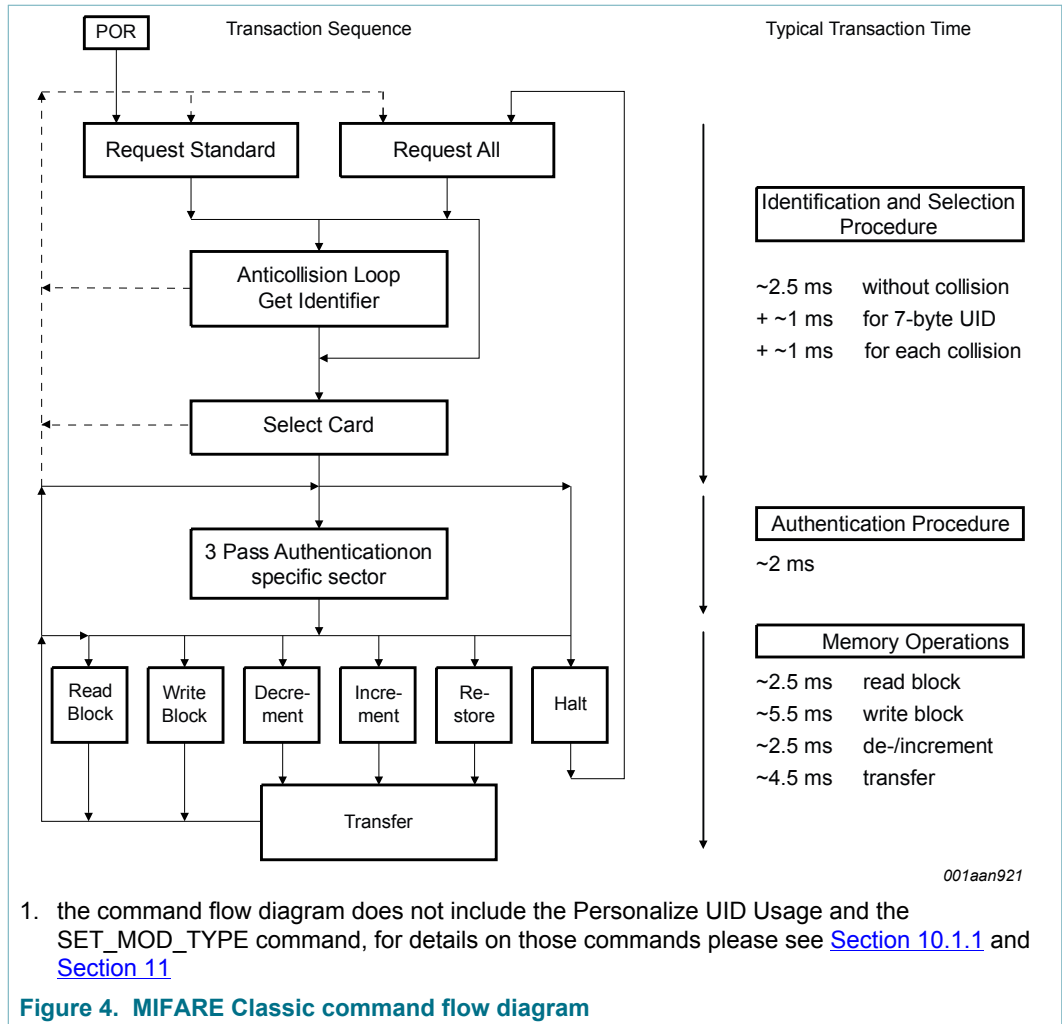
### 8.2.3 Select card

With the select card command the reader selects one individual card for authentication and memory related operations. The card returns the Select Acknowledge (SAK) code which determines the type of the selected card, see [Section 9.4](#). For further details refer to the document [Ref. 2](#).

### 8.2.4 Three pass authentication

After selection of a card the reader specifies the memory location of the following memory access and uses the corresponding key for the three pass authentication procedure. After a successful authentication all commands and responses are encrypted.

**Remark:** The HLTA command needs to be sent encrypted to the PICC after a successful authentication in order to be accepted.



### 8.2.5 Memory operations

After authentication any of the following operations may be performed:

- Read block
- Write block
- Decrement: Decrements the contents of a block and stores the result in the internal Transfer Buffer
- Increment: Increments the contents of a block and stores the result in the internal Transfer Buffer
- Restore: Moves the contents of a block into the internal Transfer Buffer
- Transfer: Writes the contents of the internal Transfer Buffer to a value block

### 8.3 Data integrity

Following mechanisms are implemented in the contactless communication link between reader and card to ensure very reliable data transmission:

- 16 bits CRC per block
- Parity bits for each byte



- Bit count checking
- Bit coding to distinguish between "1", "0" and "no information"
- Channel monitoring (protocol sequence and bit stream analysis)

#### 8.4 Three pass authentication sequence

1. The reader specifies the sector to be accessed and chooses key A or B.
2. The card reads the secret key and the access conditions from the sector trailer. Then the card sends a number as the challenge to the reader (pass one).
3. The reader calculates the response using the secret key and additional input. The response, together with a random challenge from the reader, is then transmitted to the card (pass two).
4. The card verifies the response of the reader by comparing it with its own challenge and then it calculates the response to the challenge and transmits it (pass three).
5. The reader verifies the response of the card by comparing it to its own challenge.

After transmission of the first random challenge the communication between card and reader is encrypted.

#### 8.5 RF interface

The RF-interface is according to the standard for contactless smart cards ISO/IEC 14443A.

For operation, the carrier field from the reader always needs to be present (with short pauses when transmitting), as it is used for the power supply of the card.

For both directions of data communication there is only one start bit at the beginning of each frame. Each byte is transmitted with a parity bit (odd parity) at the end. The LSB of the byte with the lowest address of the selected block is transmitted first. The maximum frame length is 163 bits (16 data bytes + 2 CRC bytes =  $16 \times 9 + 2 \times 9 + 1$  start bit).

#### 8.6 Memory organization

The  $1024 \times 8$  bit EEPROM memory is organized in 16 sectors of 4 blocks. One block contains 16 bytes.

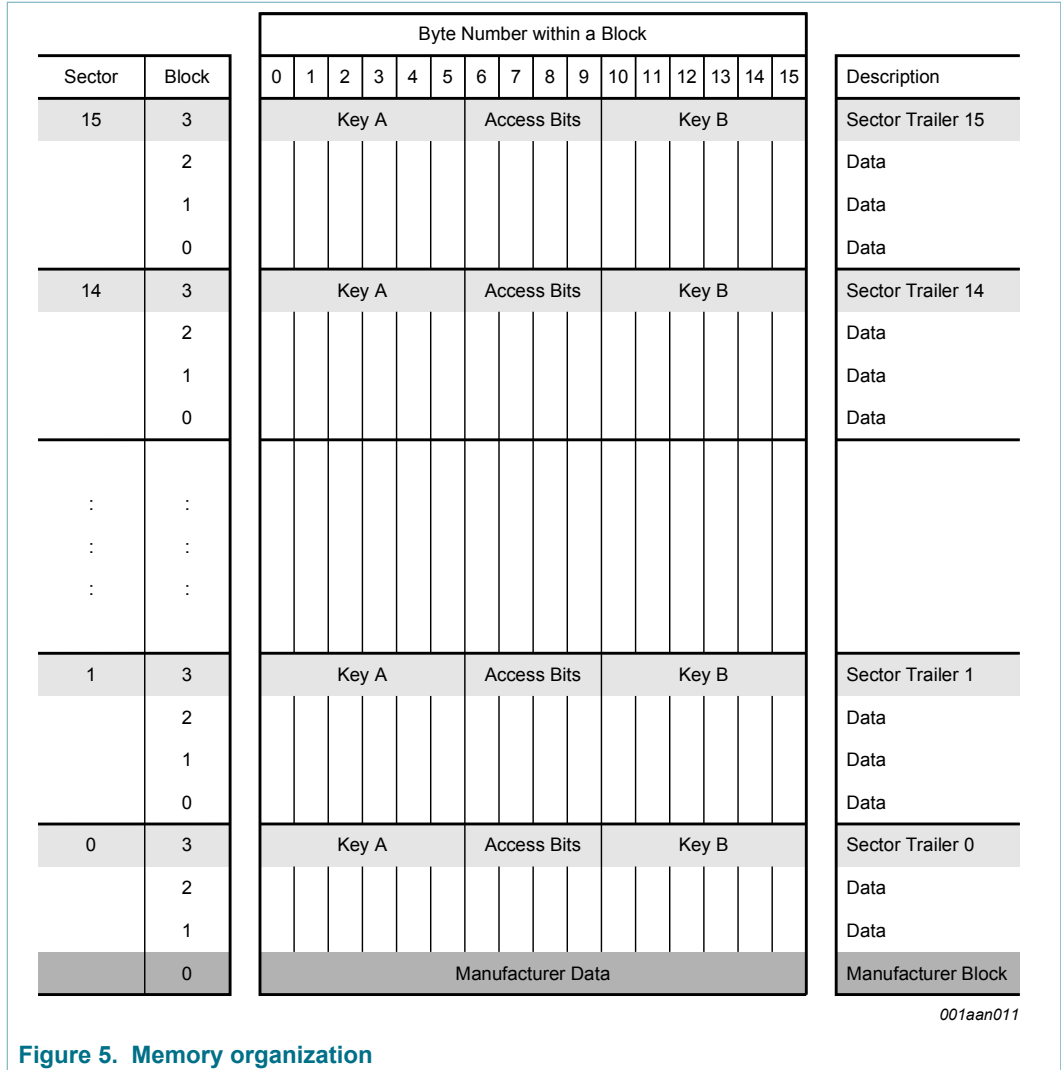


Figure 5. Memory organization

8.6.1 Manufacturer block

This is the first data block (block 0) of the first sector (sector 0). It contains the IC manufacturer data. This block is programmed and write protected in the production test. The manufacturer block is shown in Figure 6 and Figure 7 for the 4-byte NUID and 7-byte UID version respectively.

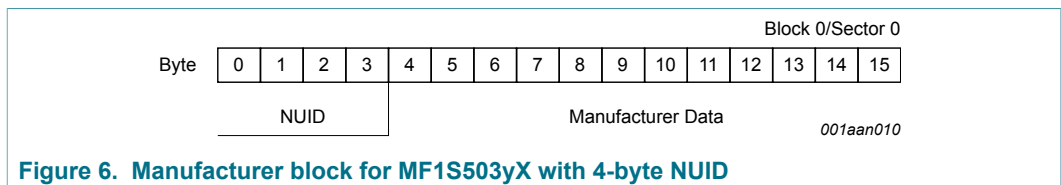


Figure 6. Manufacturer block for MF1S503yX with 4-byte NUID

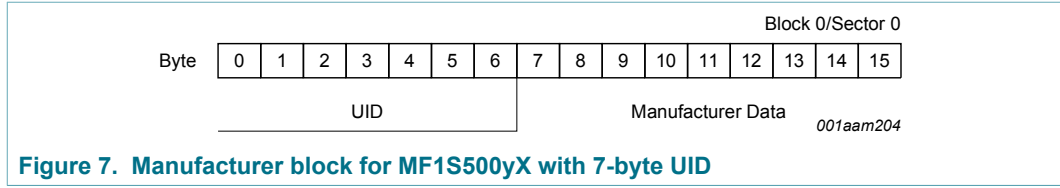


Figure 7. Manufacturer block for MF1S500yX with 7-byte UID

8.6.2 Data blocks

All sectors contain 3 blocks of 16 bytes for storing data (Sector 0 contains only two data blocks and the read-only manufacturer block).

The data blocks can be configured by the access bits as

- read/write blocks
- value blocks

Value blocks can be used for e.g. electronic purse applications, where additional commands like increment and decrement for direct control of the stored value are provided

A successful authentication has to be performed to allow any memory operation.

**Remark:** The default content of the data blocks at delivery is not defined.

8.6.2.1 Value blocks

Value blocks allow performing electronic purse functions (valid commands are: read, write, increment, decrement, restore, transfer). Value blocks have a fixed data format which permits error detection and correction and a backup management.

A value block can only be generated through a write operation in value block format:

- Value: Signifies a signed 4-byte value. The lowest significant byte of a value is stored in the lowest address byte. Negative values are stored in standard 2’s complement format. For reasons of data integrity and security, a value is stored three times, twice non-inverted and once inverted.
- Adr: Signifies a 1-byte address, which can be used to save the storage address of a block, when implementing a powerful backup management. The address byte is stored four times, twice inverted and non-inverted. During increment, decrement, restore and transfer operations the address remains unchanged. It can only be altered via a write command.

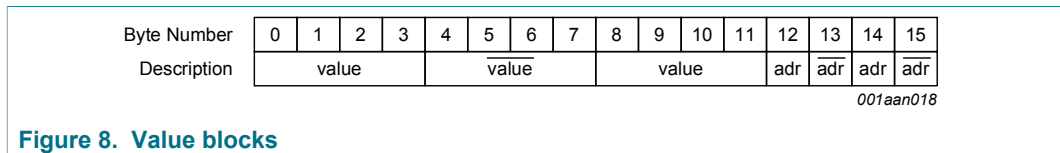


Figure 8. Value blocks

An example of a valid value block format for the decimal value 1234567d and the block address 17d is shown in Table 4. First, the decimal value has to be converted to the hexadecimal representation of 0012D687h. The LSByte of the hexadecimal value is stored in Byte 0, the MSByte in Byte 3. The bit inverted hexadecimal representation of the value is FFED2978h where the LSByte is stored in Byte 4 and the MSByte in Byte 7.

The hexadecimal value of the address in the example is 11h, the bit inverted hexadecimal value is EEh.

Table 4. Value block format example

Byte Number	0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15
Description	value				value				value				adr	adr	adr	adr
Values [hex]	87	D6	12	00	78	29	ED	FF	87	D6	12	00	11	EE	11	EE

### 8.6.3 Sector trailer

The sector trailer is the last block (block 3) in one sector. Each sector has a sector trailer containing the

- secret keys A (mandatory) and B (optional), which return logical "0"s when read and
- the access conditions for the blocks of that sector, which are stored in bytes 6...9. The access bits also specify the type (data or value) of the data blocks.

If key B is not needed, the last 6 bytes of the sector trailer can be used as data bytes. The access bits for the sector trailer have to be configured accordingly, see [Section 8.7.2](#).

Byte 9 of the sector trailer is available for user data. For this byte the same access rights as for byte 6, 7 and 8 apply.

When the sector trailer is read, the key bytes are blanked out by returning logical zeros. If key B is configured to be readable, the data stored in bytes 10 to 15 is returned, see [Section 8.7.2](#).

All keys are set to FFFF FFFF FFFFh at chip delivery and the bytes 6, 7 and 8 are set to FF0780h.

Byte Number	0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15
Description	Key A					Access Bits			Key B (optional)							

*001aan013*

Figure 9. Sector trailer

## 8.7 Memory access

Before any memory operation can be done, the card has to be selected and authenticated as described in [Section 8.2](#). The possible memory operations for an addressed block depend on the key used during authentication and the access conditions stored in the associated sector trailer.

Table 5. Memory operations

Operation	Description	Valid for Block Type
Read	reads one memory block	read/write, value and sector trailer
Write	writes one memory block	read/write, value and sector trailer
Increment	increments the contents of a block and stores the result in the internal Transfer Buffer	value
Decrement	decrements the contents of a block and stores the result in the internal Transfer Buffer	value

Operation	Description	Valid for Block Type
Transfer	writes the contents of the internal Transfer Buffer to a block	value and read/write
Restore	reads the contents of a block into the internal Transfer Buffer	value

8.7.1 Access conditions

The access conditions for every data block and sector trailer are defined by 3 bits, which are stored non-inverted and inverted in the sector trailer of the specified sector.

The access bits control the rights of memory access using the secret keys A and B. The access conditions may be altered, provided one knows the relevant key and the current access condition allows this operation.

**Remark:** With each memory access the internal logic verifies the format of the access conditions. If it detects a format violation the whole sector is irreversibly blocked.

**Remark:** In the following description the access bits are mentioned in the non-inverted mode only.

The internal logic of the MF1S50yyX/V1 ensures that the commands are executed only after a successful authentication.

Table 6. Access conditions

Access Bits	Valid Commands		Block	Description
C <sub>13</sub> , C <sub>23</sub> , C <sub>33</sub>	read, write	→	3	sector trailer
C <sub>12</sub> , C <sub>22</sub> , C <sub>32</sub>	read, write, increment, decrement, transfer, restore	→	2	data block
C <sub>11</sub> , C <sub>21</sub> , C <sub>31</sub>	read, write, increment, decrement, transfer, restore	→	1	data block
C <sub>10</sub> , C <sub>20</sub> , C <sub>30</sub>	read, write, increment, decrement, transfer, restore	→	0	data block

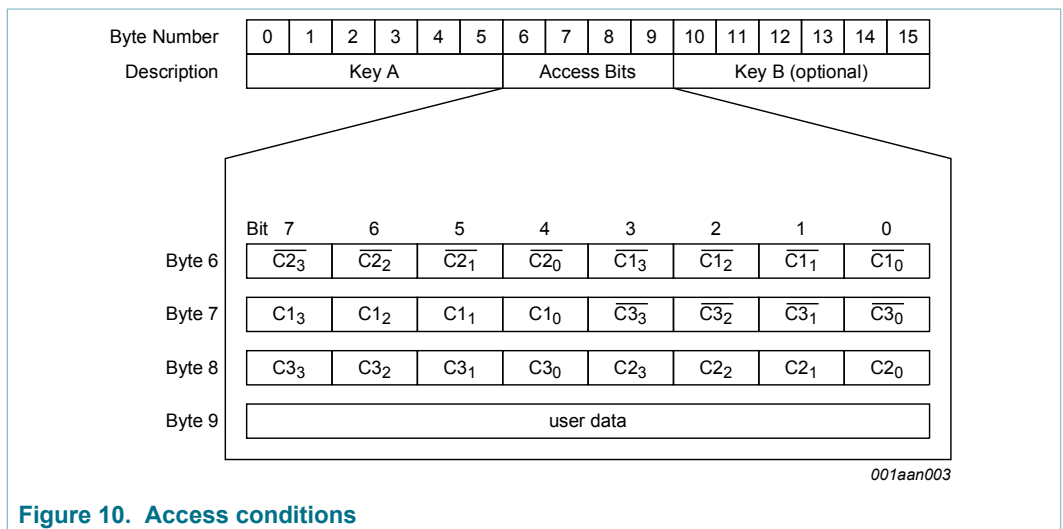


Figure 10. Access conditions

8.7.2 Access conditions for the sector trailer

Depending on the access bits for the sector trailer (block 3) the read/write access to the keys and the access bits is specified as ‘never’, ‘key A’, ‘key B’ or key A|B’ (key A or key B).

On chip delivery the access conditions for the sector trailers and key A are predefined as transport configuration. Since key B may be read in the transport configuration, new cards must be authenticated with key A. Since the access bits themselves can also be blocked, special care has to be taken during the personalization of cards.

Table 7. Access conditions for the sector trailer

Access bits			Access condition for						Remark
			KEYA		Access bits		KEYB		
C1	C2	C3	read	write	read	write	read	write	
0	0	0	never	key A	key A	never	key A	key A	Key B may be read <sup>[1]</sup>
0	1	0	never	never	key A	never	key A	never	Key B may be read <sup>[1]</sup>
1	0	0	never	key B	key A B	never	never	key B	
1	1	0	never	never	key A B	never	never	never	
0	0	1	never	key A	key A	key A	key A	key A	Key B may be read, transport configuration <sup>[1]</sup>
0	1	1	never	key B	key A B	key B	never	key B	
1	0	1	never	never	key A B	key B	never	never	
1	1	1	never	never	key A B	never	never	never	

[1] For this access condition key B is readable and may be used for data

8.7.3 Access conditions for data blocks

Depending on the access bits for data blocks (blocks 0...2) the read/write access is specified as ‘never’, ‘key A’, ‘key B’ or ‘key A|B’ (key A or key B). The setting of the relevant access bits defines the application and the corresponding applicable commands.

- Read/write block: the operations read and write are allowed.
- Value block: Allows the additional value operations increment, decrement, transfer and restore. With access condition ‘001’ only read and decrement are possible which reflects a non-rechargeable card. For access condition ‘110’ recharging is possible by using key B.
- Manufacturer block: the read-only condition is not affected by the access bits setting!
- Key management: in transport configuration key A must be used for authentication

Table 8. Access conditions for data blocks

Access bits			Access condition for				Application
C1	C2	C3	read	write	increment	decrement, transfer, restore	
0	0	0	key A B	key A B	key A B	key A B	transport configuration <sup>[1]</sup>

Access bits			Access condition for				Application
0	1	0	key A B	never	never	never	read/write block <sup>[1]</sup>
1	0	0	key A B	key B	never	never	read/write block <sup>[1]</sup>
1	1	0	key A B	key B	key B	key A B	value block <sup>[1]</sup>
0	0	1	key A B	never	never	key A B	value block <sup>[1]</sup>
0	1	1	key B	key B	never	never	read/write block <sup>[1]</sup>
1	0	1	key B	never	never	never	read/write block <sup>[1]</sup>
1	1	1	never	never	never	never	read/write block

[1] If key B may be read in the corresponding Sector Trailer it cannot serve for authentication (see grey marked lines in [Table 7](#)). As a consequences, if the reader authenticates any block of a sector which uses such access conditions for the Sector Trailer and using key B, the card will refuse any subsequent memory access after authentication.

## 9 Command overview

**Note:** In this document the term „MIFARE Classic card“ refers to a MIFARE Classic IC-based contactless card.

The MIFARE Classic card activation follows the ISO/IEC 14443 Type A. After the MIFARE Classic card has been selected, it can either be deactivated using the ISO/IEC 14443 Halt command, or the MIFARE Classic commands can be performed. For more details about the card activation refer to [Ref. 4](#).

### 9.1 MIFARE Classic command overview

All MIFARE Classic commands typically use the MIFARE Classic using Crypto1 and require an authentication.

All available commands for the MIFARE Classic EV1 with 1K memory are shown in [Table 9](#).

**Table 9. Command overview**

Command	ISO/IEC 14443	Command code (hexadecimal)
Request	REQA	26h (7 bit)
Wake-up	WUPA	52h (7 bit)
Anticollision CL1	Anticollision CL1	93h 20h
Select CL1	Select CL1	93h 70h
Anticollision CL2	Anticollision CL2	95h 20h
Select CL2	Select CL2	95h 70h
Halt	Halt	50h 00h
Authentication with Key A	-	60h
Authentication with Key B	-	61h
Personalize UID Usage	-	40h
SET_MOD_TYPE	-	43h
MIFARE Read	-	30h

Command	ISO/IEC 14443	Command code (hexadecimal)
MIFARE Write	-	A0h
MIFARE Decrement	-	C0h
MIFARE Increment	-	C1h
MIFARE Restore	-	C2h
MIFARE Transfer	-	B0h

All commands use the coding and framing as described in [Ref. 3](#) and [Ref. 4](#) if not otherwise specified.

### 9.2 Timings

The timing shown in this document are not to scale and values are rounded to 1 μs.

All given times refer to the data frames including start of communication and end of communication. A PCD data frame contains the start of communication (1 "start bit") and the end of communication (one logic 0 + 1 bit length of unmodulated carrier). A PICC data frame contains the start of communication (1 "start bit") and the end of communication (1 bit length of no subcarrier).

The minimum command response time is specified according to [Ref. 4](#) as an integer n which specifies the PCD to PICC frame delay time. The frame delay time from PICC to PCD is at least 87 μs. The maximum command response time is specified as a time-out value. Depending on the command, the T<sub>ACK</sub> value specified for command responses defines the PCD to PICC frame delay time. It does it for either the 4-bit ACK value specified in [Section 9.3](#) or for a data frame.

All command timings are according to ISO/IEC 14443-3 frame specification as shown for the Frame Delay Time in [Figure 11](#). For more details refer to [Ref. 3](#) and [Ref. 4](#).

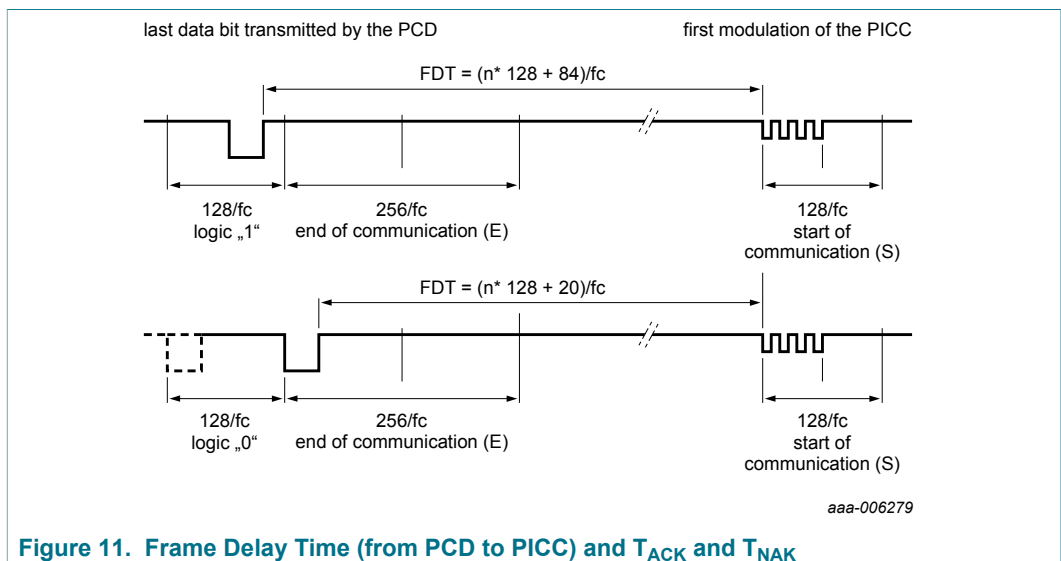


Figure 11. Frame Delay Time (from PCD to PICC) and T<sub>ACK</sub> and T<sub>NAK</sub>

**Remark:** Due to the coding of commands, the measured timings usually excludes (a part of) the end of communication. Consider this factor when comparing the specified with the measured times.



### 9.3 MIFARE Classic ACK and NAK

The MIFARE Classic uses a 4 bit ACK / NAK as shown in [Table 10](#).

**Table 10. MIFARE ACK and NAK**

Code (4-bit)	Transfer Buffer Validity	Description
Ah		Acknowledge (ACK)
0h	valid	invalid operation
1h	valid	parity or CRC error
4h	invalid	invalid operation
5h	invalid	parity or CRC error

### 9.4 ATQA and SAK responses

For details on the type identification procedure please refer to [Ref. 2](#).

The MF1S50yyX/V1 answers to a REQA or WUPA command with the ATQA value shown in [Table 11](#) and to a Select CL1 command (CL2 for the 7-byte UID variant) with the SAK value shown in [Table 12](#).

**Table 11. ATQA response of the MF1S50yyX/V1**

Sales Type	Hex Value	Bit Number															
		16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1
MF1S500yX	00 44h	0	0	0	0	0	0	0	0	0	1	0	0	0	1	0	0
MF1S503yX	00 04h	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	0
MF1S700yX	00 42 <sub>h</sub>	0	0	0	0	0	0	0	0	0	1	0	0	0	0	1	0
MF1S703yX	00 02 <sub>h</sub>	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0

**Table 12. SAK response of the MF1S50yyX/V1**

Sales Type	Hex Value	Bit Number							
		8	7	6	5	4	3	2	1
MF1S50yyX/V1	08h	0	0	0	0	1	0	0	0

**Remark:** The ATQA coding in bits 7 and 8 indicate the UID size according to ISO/IEC 14443 independent from the settings of the UID usage.

**Remark:** The bit numbering in the ISO/IEC 14443 starts with LSBit = bit 1, but not LSBit = bit 0. So one byte counts bit 1 to 8 instead of bit 0 to 7.

## 10 UID Options and Handling

The MF1S50yyX/V1 product family offers two delivery options for the UID which is stored in block 0 of sector 0.

- 7-byte UID
- 4-byte NUID (Non-Unique ID)

This section describes the MIFARE Classic MF1S50yyX/V1 operation when using one of the 2 UID options with respect to card selection, authentication and personalization. See also [Ref. 6](#) for details on how to handle UIDs and NUIDs with MIFARE Classic products.

### 10.1 7-byte UID Operation

All MF1S500yXDyy products are featuring a 7-byte UID. This 7-byte UID is stored in block 0 of sector 0 as shown in [Figure 7](#). The behaviour during anti-collision, selection and authentication can be configured during personalization for this UID variant.

#### 10.1.1 Personalization Options

The 7-byte UID variants of the MF1S50yyX/V1 can be operated with four different functionalities, denoted as UIDFn (UID Functionality n).

1. UIDF0: anti-collision and selection with the double size UID according to ISO/IEC 14443-3
2. UIDF1: anti-collision and selection with the double size UID according to ISO/IEC 14443-3 and optional usage of a selection process shortcut
3. UIDF2: anti-collision and selection with a single size random ID according to ISO/IEC 14443-3
4. UIDF3: anti-collision and selection with a single size NUID according to ISO/IEC 14443-3 where the NUID is calculated out of the 7-byte UID

The anti-collision and selection procedure and the implications on the authentication process are detailed in [Section 10.1.2](#) and [Section 10.1.3](#).

The default configuration at delivery is option 1 which enables the ISO/IEC 14443-3 compliant anti-collision and selection. This configuration can be changed using the 'Personalize UID Usage' command. The execution of this command requires an authentication to sector 0. Once this command has been issued and accepted by the PICC, the configuration is automatically locked. A subsequently issued 'Personalize UID Usage' command is not executed and a NAK is replied by the PICC.

**Remark:** As the configuration is changeable at delivery, it is strongly recommended to send this command at personalization of the card to prevent unwanted changes in the field. This should also be done if the default configuration is used.

**Remark:** The configuration becomes effective only after PICC unselect or PICC field reset.

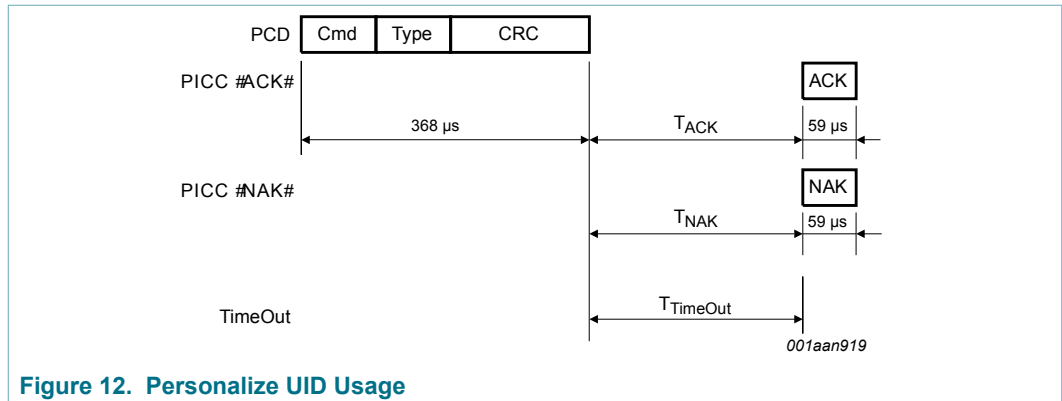


Figure 12. Personalize UID Usage

Table 13. Personalize UID Usage command

Name	Code	Description	Length
Cmd	40h	Set anti-collision, selection and authentication behaviour	1 byte
Type	-	Encoded type of UID usage: UIDF0: 00h UIDF1: 40h UIDF2: 20h UIDF3: 60h	1 byte
CRC	-	CRC according to <a href="#">Ref. 4</a>	2 bytes
ACK, NAK	see <a href="#">Table 10</a>	see <a href="#">Section 9.3</a>	4-bit

Table 14. Personalize UID Usage timing

	T <sub>ACK min</sub>	T <sub>ACK max</sub>	T <sub>NAK min</sub>	T <sub>NAK max</sub>	T <sub>TimeOut</sub>
Personalize UID Usage	n=9	T <sub>TimeOut</sub>	n=9	T <sub>TimeOut</sub>	10 ms

### 10.1.2 Anti-collision and Selection

Depending on the chosen personalization option there are certain possibilities to perform anti-collision and selection. To bring the MIFARE Classic contactless IC into the ACTIVE state according to ISO/IEC 14443-3, the following sequences are available.

Sequence 1: ISO/IEC 14443-3 compliant anti-collision and selection using the cascade level 1 followed by the cascade level 2 SEL command

Sequence 2: using cascade level 1 anti-collision and selection procedure followed by a Read command from block 0

Sequence 3: ISO/IEC 14443-3 compliant anti-collision and selection using the cascade level 1 SEL command

**Remark:** The Read from Block 0 in Sequence 2 does not require a prior authentication to Sector 0 and is transmitted in plain data. For all other sequences, the readout from Block 0 in Sector 0 is encrypted and requires an authentication to that sector.

**Remark:** The settings done with Personalize UID Usage do not change the ATQA coding.

**Table 15. Available activation sequences for 7-byte UID options**

UID Functionality	Available Activation Sequences
UIDF0	Sequence 1
UIDF1	Sequence 1, Sequence 2
UIDF2	Sequence 3
UIDF3	Sequence 3

### 10.1.3 Authentication

During the authentication process, 4-byte of the UID are passed on to the MIFARE Classic Authenticate command of the contactless reader IC. Depending on the activation sequence, those 4-byte are chosen differently. In general, the input parameter to the MIFARE Classic Authenticate command is the set of 4 bytes retrieved during the last cascade level from the ISO/IEC 14443-3 Type A anticollision.

**Table 16. Input parameter to MIFARE Classic Authenticate**

UID Functionality	Input to MIFARE Classic Authenticate Command
Sequence 1	CL2 bytes (UID3...UID6)
Sequence 2	CL1 bytes (CT, UID0...UID2)
Sequence 3	4-byte NUID/RID (UID0...UID3)

## 10.2 4-byte UID Operation

All MF1S503yXDy products are featuring a 4-byte NUID. This 4-byte NUID is stored in block 0 of sector 0 as shown in [Figure 6](#).

### 10.2.1 Anti-collision and Selection

The anti-collision and selection process for the product variants featuring 4-byte NUIDs is done according to ISO/IEC 14443-3 Type A using cascade level 1 only.

### 10.2.2 Authentication

The input parameter to the MIFARE Classic Authenticate command is the full 4-byte UID retrieved during the anti-collision procedure. This is the same as for the activation Sequence 3 in the 7-byte UID variant.

## 11 Load Modulation Strength Option

The MIFARE Classic EV1 with 1K memory features the possibility to set the load modulation strength to high or normal. The default level is set to a high modulation strength and it is recommended for optimal performance to maintain this level and only switch to the low load modulation strength if the contactless system requires it.

**Remark:** The configuration becomes effective only after a PICC unselect or a PICC field reset. The configuration can be changed multiple times by asserting the command.

**Remark:** The MIFARE Classic EV1 with 1K memory needs to be authenticated to sector 0 with Key A to perform the SET\_MOD\_TYPE command. The Access Bits for sector 0 are irrelevant.

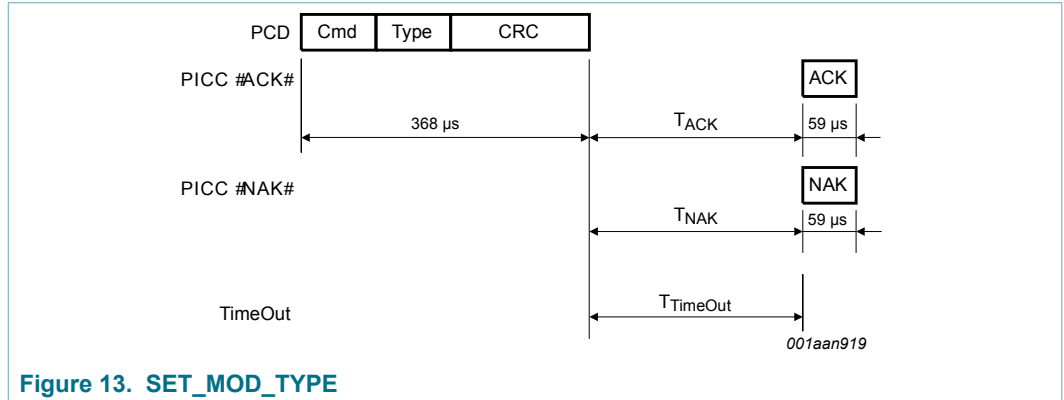


Figure 13. SET\_MOD\_TYPE

Table 17. SET\_MOD\_TYPE command

Name	Code	Description	Length
Cmd	43h	Set load modulation strength	1 byte
Type	-	Encoded load modulation strength: strong modulation: 01h (default) normal modulation: 00h	1 byte
CRC	-	CRC according to <a href="#">Ref. 4</a>	2 bytes
ACK, NAK	see <a href="#">Table 10</a>	see <a href="#">Section 9.3</a>	4-bit

Table 18. SET\_MOD\_TYPE timing

	T <sub>ACK min</sub>	T <sub>ACK max</sub>	T <sub>NAK min</sub>	T <sub>NAK max</sub>	T <sub>TimeOut</sub>
SET_MOD_TYPE	n=9	T <sub>TimeOut</sub>	n=9	T <sub>TimeOut</sub>	5 ms

The configured load modulation is shown in the manufacturer data of block 0 in sector 0. The exact location is shown below in [Figure 14](#) and [Table 19](#).

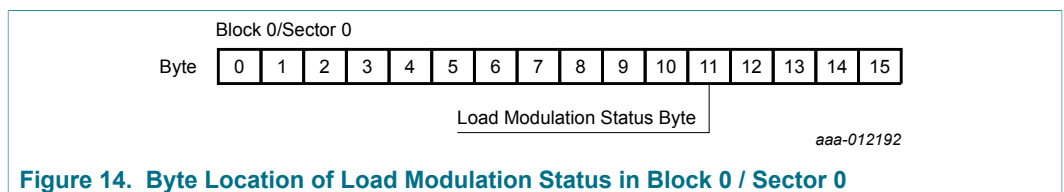


Figure 14. Byte Location of Load Modulation Status in Block 0 / Sector 0

Table 19. Load Modulation Status Indication

Load Modulation Type	Hex Value	Bit Number							
		7	6	5	4	3	2	1	0
strong load modulation	20h (default)	0	0	1	0	0	0	0	0
normal load modulation	00h	0	0	0	0	0	0	0	0

## 12 MIFARE Classic commands

### 12.1 MIFARE Classic Authentication

The MIFARE Classic authentication is a 3-pass mutual authentication which needs two pairs of command-response. These two parts, MIFARE Classic authentication part 1 and part 2 are shown in [Figure 15](#), [Figure 16](#) and [Table 20](#).

[Table 21](#) shows the required timing.

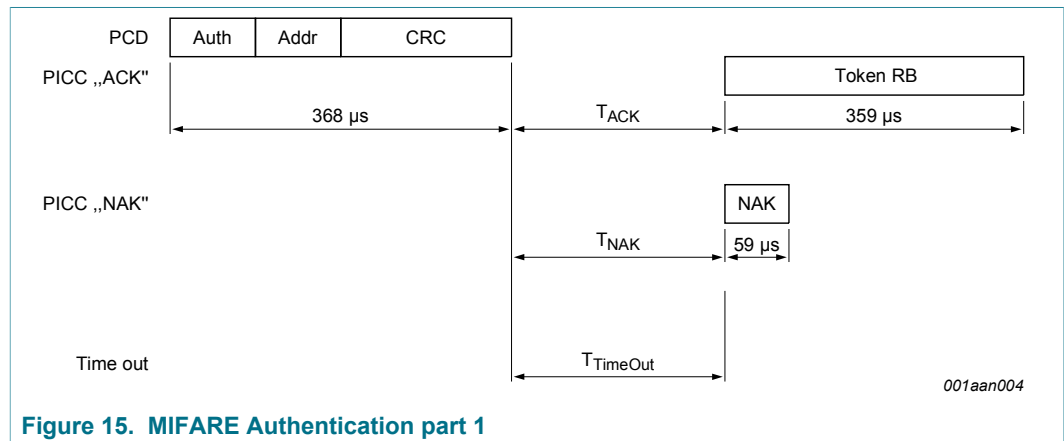


Figure 15. MIFARE Authentication part 1

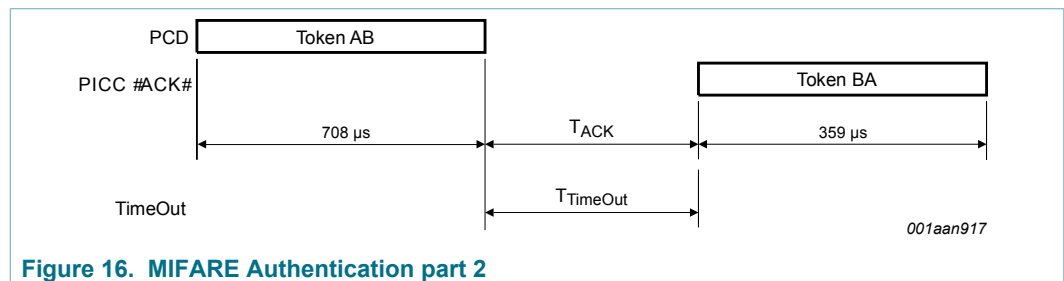


Figure 16. MIFARE Authentication part 2

Table 20. MIFARE Classic authentication command

Name	Code	Description	Length
Auth (with Key A)	60h	Authentication with Key A	1 byte
Auth (with Key B)	61h	Authentication with Key B	1 byte
Addr	-	MIFARE Block address (00h to FFh)	1 byte
CRC	-	CRC according to <a href="#">Ref. 4</a>	2 bytes
Token RB	-	Challenge 1 (Random Number)	4 bytes
Token AB	-	Challenge 2 (encrypted data)	8 bytes
Token BA	-	Challenge 2 (encrypted data)	4 bytes
NAK	see <a href="#">Table 10</a>	see <a href="#">Section 9.3</a>	4-bit

**Table 21. MIFARE Classic authentication timing**

	T <sub>ACK min</sub>	T <sub>ACK max</sub>	T <sub>NAK min</sub>	T <sub>NAK max</sub>	T <sub>TimeOut</sub>
Authentication part 1	n=9	T <sub>TimeOut</sub>	n=9	n=9	1 ms
Authentication part 2	n=9	T <sub>TimeOut</sub>			1 ms

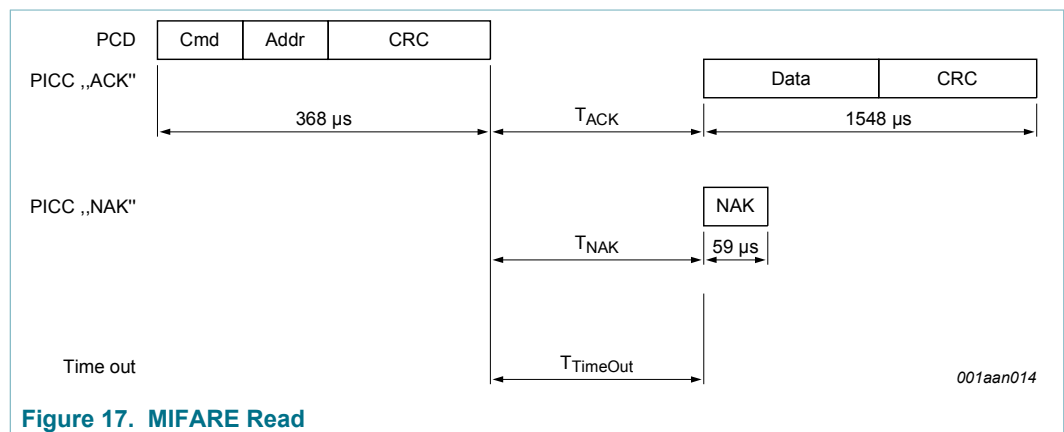
**Remark:** The minimum required time between MIFARE Classic Authentication part 1 and part 2 is the minimum required FDT according to [Ref. 4](#). There is no maximum time specified.

**Remark:** The MIFARE Classic authentication and encryption requires an NFC reader IC for MIFARE products (e.g. the CL RC632). For more details about the authentication command refer to the corresponding data sheet (e.g. [Ref. 5](#)). The 4-byte input parameter for the MIFARE Classic Authentication is detailed in [Section 10.1.3](#) and [Section 10.2.2](#).

## 12.2 MIFARE Read

The MIFARE Read requires a block address, and returns the 16 bytes of one MIFARE Classic block. The command structure is shown in [Figure 17](#) and [Table 22](#).

[Table 23](#) shows the required timing.



**Figure 17. MIFARE Read**

**Table 22. MIFARE Read command**

Name	Code	Description	Length
Cmd	30h	Read one block	1 byte
Addr	-	MIFARE Block address (00h to FFh)	1 byte
CRC	-	CRC according to <a href="#">Ref. 4</a>	2 bytes
Data	-	Data content of the addressed block	16 bytes
NAK	see <a href="#">Table 10</a>	see <a href="#">Section 9.3</a>	4-bit

**Table 23. MIFARE Read timing**

	T <sub>ACK min</sub>	T <sub>ACK max</sub>	T <sub>NAK min</sub>	T <sub>NAK max</sub>	T <sub>TimeOut</sub>
Read	n=9	T <sub>TimeOut</sub>	n=9	T <sub>TimeOut</sub>	5 ms

### 12.3 MIFARE Write

The MIFARE Write requires a block address, and writes 16 bytes of data into the addressed MIFARE Classic EV1 with 1K memory block. It needs two pairs of command-response. These two parts, MIFARE Write part 1 and part 2 are shown in [Figure 18](#) and [Figure 19](#) and [Table 24](#).

[Table 25](#) shows the required timing.

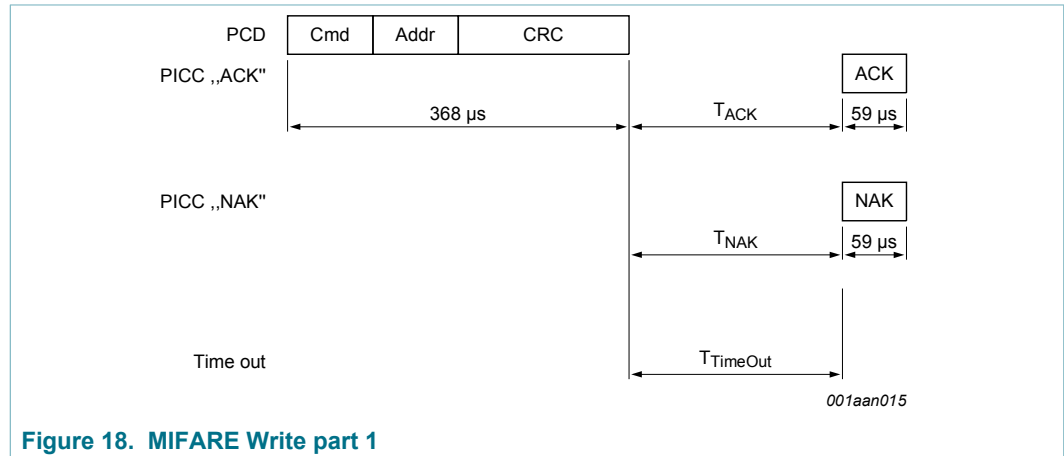


Figure 18. MIFARE Write part 1

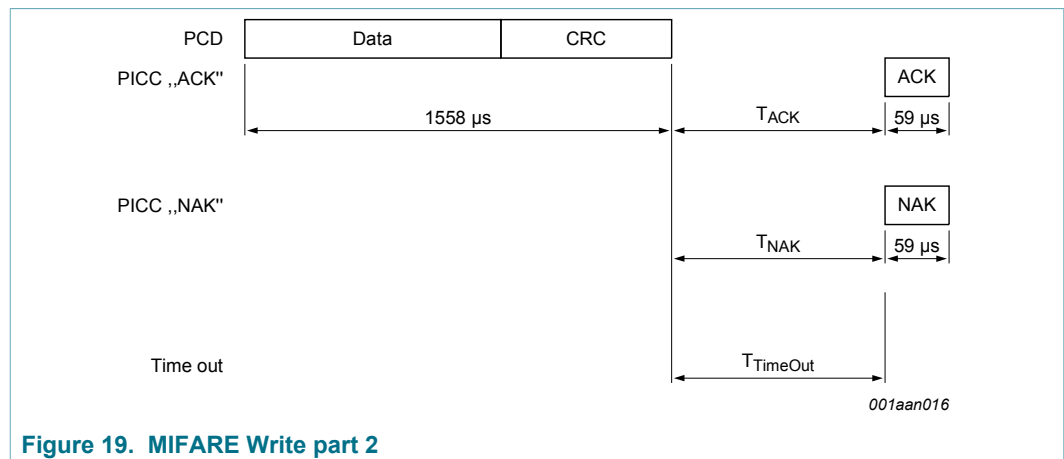


Figure 19. MIFARE Write part 2

Table 24. MIFARE Write command

Name	Code	Description	Length
Cmd	A0h	Write one block	1 byte
Addr	-	MIFARE Block or Page address (00h to FFh)	1 byte
CRC	-	CRC according to <a href="#">Ref. 4</a>	2 bytes
Data	-	Data	16 bytes
NAK	see <a href="#">Table 10</a>	see <a href="#">Section 9.3</a>	4-bit



Table 25. MIFARE Write timing

	T <sub>ACK min</sub>	T <sub>ACK max</sub>	T <sub>NAK min</sub>	T <sub>NAK max</sub>	T <sub>TimeOut</sub>
Write part 1	n=9	T <sub>TimeOut</sub>	n=9	T <sub>TimeOut</sub>	5 ms
Write part 2	n=9	T <sub>TimeOut</sub>	n=9	T <sub>TimeOut</sub>	10 ms

**Remark:** The minimum required time between MIFARE Write part 1 and part 2 is the minimum required FDT according to [Ref. 4](#). There is no maximum time specified.

### 12.4 MIFARE Increment, Decrement and Restore

The MIFARE Increment requires a source block address and an operand. It adds the operand to the value of the addressed block, and stores the result in the Transfer Buffer.

The MIFARE Decrement requires a source block address and an operand. It subtracts the operand from the value of the addressed block, and stores the result in the Transfer Buffer.

The MIFARE Restore requires a source block address. It copies the value of the addressed block into the Transfer Buffer. The 4 byte Operand in the second part of the command is not used and may contain arbitrary values.

All three commands are responding with a NAK to the first command part if the addressed block is not formatted to be a valid value block, see [Section 8.6.2.1](#).

The two parts of each command are shown in [Figure 20](#) and [Figure 21](#) and [Table 26](#).

[Table 27](#) shows the required timing.

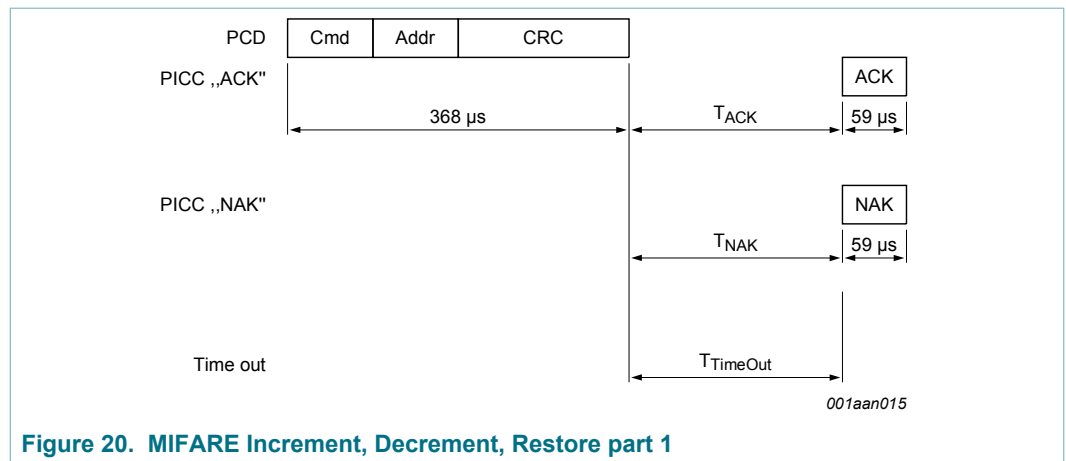
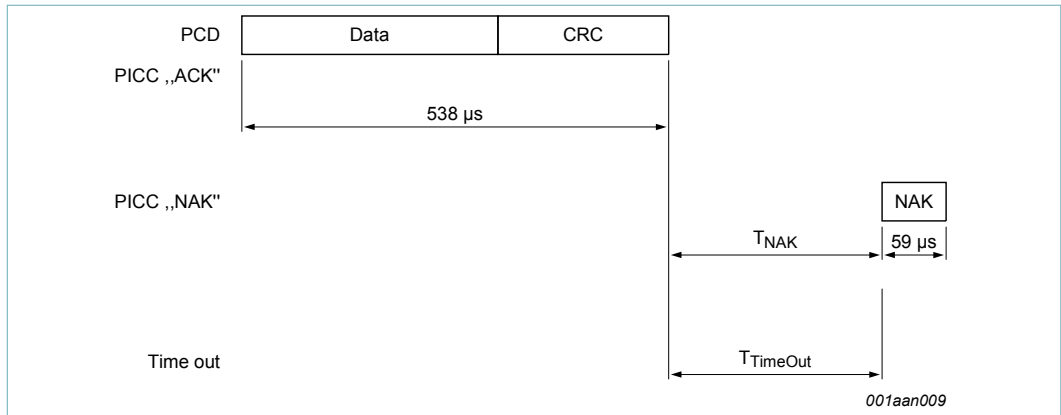


Figure 20. MIFARE Increment, Decrement, Restore part 1



1. Increment, Decrement and Restore part 2 does not acknowledge

Figure 21. MIFARE Increment, Decrement, Restore part 2

Table 26. MIFARE Increment, Decrement and Restore command

Name	Code	Description	Length
Cmd	C1h	Increment	1 byte
Cmd	C0h	Decrement	1 byte
Cmd	C2h	Restore	1 byte
Addr	-	MIFARE source block address (00h to FFh)	1 byte
CRC	-	CRC according to <a href="#">Ref. 4</a>	2 bytes
Data	-	Operand (4 byte signed integer)	4 bytes
NAK	see <a href="#">Table 10</a>	see <a href="#">Section 9.3</a>	4-bit

Table 27. MIFARE Increment, Decrement and Restore timing

	T <sub>ACK min</sub>	T <sub>ACK max</sub>	T <sub>NAK min</sub>	T <sub>NAK max</sub>	T <sub>TimeOut</sub>
Increment, Decrement, and Restore part 1	n=9	T <sub>TimeOut</sub>	n=9	T <sub>TimeOut</sub>	5 ms
Increment, Decrement, and Restore part 2	n=9	T <sub>TimeOut</sub>	n=9	T <sub>TimeOut</sub>	5 ms

**Remark:** The minimum required time between MIFARE Increment, Decrement, and Restore part 1 and part 2 is the minimum required FDT according to [Ref. 4](#). There is no maximum time specified.

**Remark:** The MIFARE Increment, Decrement, and Restore commands require a MIFARE Transfer to store the value into a destination block.

**Remark:** The MIFARE Increment, Decrement, and Restore command part 2 does not provide an acknowledgement, so the regular time out has to be used instead.

12.5 MIFARE Transfer

The MIFARE Transfer requires a destination block address, and writes the value stored in the Transfer Buffer into one MIFARE Classic block. The command structure is shown in Figure 22 and Table 28.

Table 29 shows the required timing.

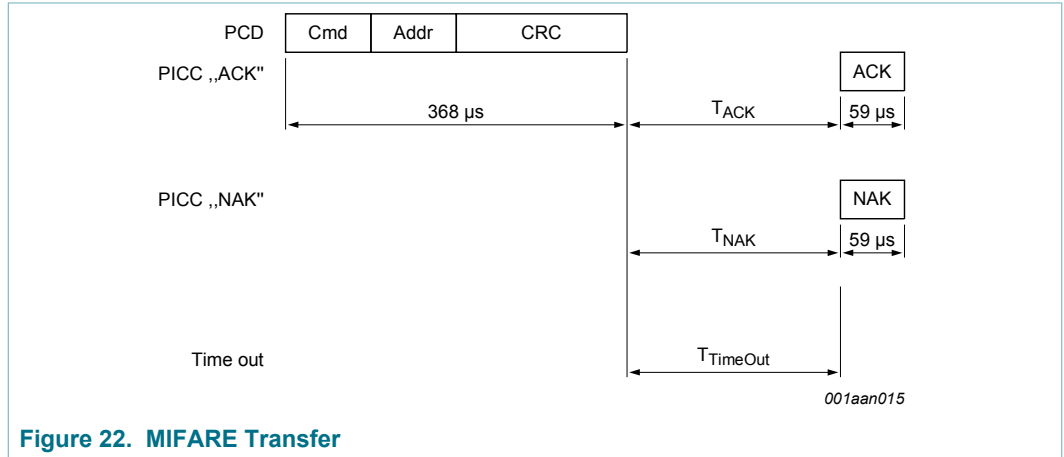


Figure 22. MIFARE Transfer

Table 28. MIFARE Transfer command

Name	Code	Description	Length
Cmd	B0h	Write the value from the Transfer Buffer into destination block	1 byte
Addr	-	MIFARE destination block address (00h to FFh)	1 byte
CRC	-	CRC according to Ref. 4	2 bytes
NAK	see Table 10	see Section 9.3	4-bit

Table 29. MIFARE Transfer timing

	T <sub>ACK min</sub>	T <sub>ACK max</sub>	T <sub>NAK min</sub>	T <sub>NAK max</sub>	T <sub>TimeOut</sub>
Transfer	n=9	T <sub>TimeOut</sub>	n=9	T <sub>TimeOut</sub>	10 ms

13 Limiting values

Stresses above one or more of the limiting values may cause permanent damage to the device. Exposure to limiting values for extended periods may affect device reliability.

Table 30. Limiting values


In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Min	Max	Unit
I <sub>I</sub>	input current	-	30	mA
P <sub>tot</sub> /pack	total power dissipation per package	-	120	mW

Symbol	Parameter	Min	Max	Unit
T <sub>stg</sub>	storage temperature	-55	125	°C
T <sub>amb</sub>	ambient temperature	-25	70	°C
V <sub>ESD</sub>	electrostatic discharge voltage on LA/LB <sup>[1]</sup>	2	-	kV

[1] ANSI/ESDA/JEDEC JS-001; Human body model: C = 100 pF, R = 1.5 kΩ

**CAUTION**



This device has limited built-in ElectroStatic Discharge (ESD) protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the gates.

## 14 Characteristics

Table 31. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
C <sub>i</sub>	input capacitance	[1]	14.9	16.9	19.0	pF
f <sub>i</sub>	input frequency		-	13.56	-	MHz
<b>EEPROM characteristics</b>						
t <sub>ret</sub>	retention time	T <sub>amb</sub> = 22 °C	10	-	-	year
N <sub>endu(W)</sub>	write endurance	T <sub>amb</sub> = 22 °C	100000	200000	-	cycle

[1] T<sub>amb</sub>=22°C, f=13,56MHz, V<sub>LaLb</sub> = 1,5 V RMS

## 15 Wafer specification

For more details on the wafer delivery forms see [Ref. 9](#).

Table 32. Wafer specifications MF1S50yyXDUy

<b>Wafer</b>	
diameter	200 mm typical (8 inches) 300 mm typical (12 inches)
maximum diameter after foil expansion	210 mm (8 inches) not applicable (12 inches)
die separation process	laser dicing (8 inches) blade dicing (12 inches)
thickness MF1S50yyXDUD	120 μm ± 15 μm
MF1S50yyXDUF	75 μm ± 10 μm
flatness	not applicable
Potential Good Dies per Wafer (PGDW)	64727 (8 inches) 147540 (12 inches)
<b>Wafer backside</b>	
material	Si

treatment	ground and stress relieve
roughness	$R_a$ max = 0.5 $\mu\text{m}$
	$R_t$ max = 5 $\mu\text{m}$
<b>Chip dimensions</b>	
step size <sup>[1]</sup>	x = 658 $\mu\text{m}$ (8 inches)
	x = 660 $\mu\text{m}$ (12 inches)
gap between chips <sup>[1]</sup>	y = 713 $\mu\text{m}$ (8 inches)
	y = 715 $\mu\text{m}$ (12 inches)
gap between chips <sup>[1]</sup>	typical = 19 $\mu\text{m}$
	minimum = 5 $\mu\text{m}$ not applicable (12 inches)
<b>Passivation</b>	
type	sandwich structure
material	PSG / nitride
thickness	500 nm / 600 nm
<b>Au bump (substrate connected to VSS)</b>	
material	> 99.9 % pure Au
hardness	35 to 80 HV 0.005
shear strength	> 70 MPa
height	18 $\mu\text{m}$
height uniformity	within a die = $\pm 2 \mu\text{m}$
	within a wafer = $\pm 3 \mu\text{m}$
	wafer to wafer = $\pm 4 \mu\text{m}$
flatness	minimum = $\pm 1.5 \mu\text{m}$
size	LA, LB, VSS, TEST <sup>[2]</sup> = 66 $\mu\text{m} \times 66 \mu\text{m}$
size variation	$\pm 5 \mu\text{m}$
under bump metallization	sputtered TiW

[1] The step size and the gap between chips may vary due to changing foil expansion

[2] Pads VSS and TESTIO are disconnected when wafer is sawn.

## 15.1 Fail die identification

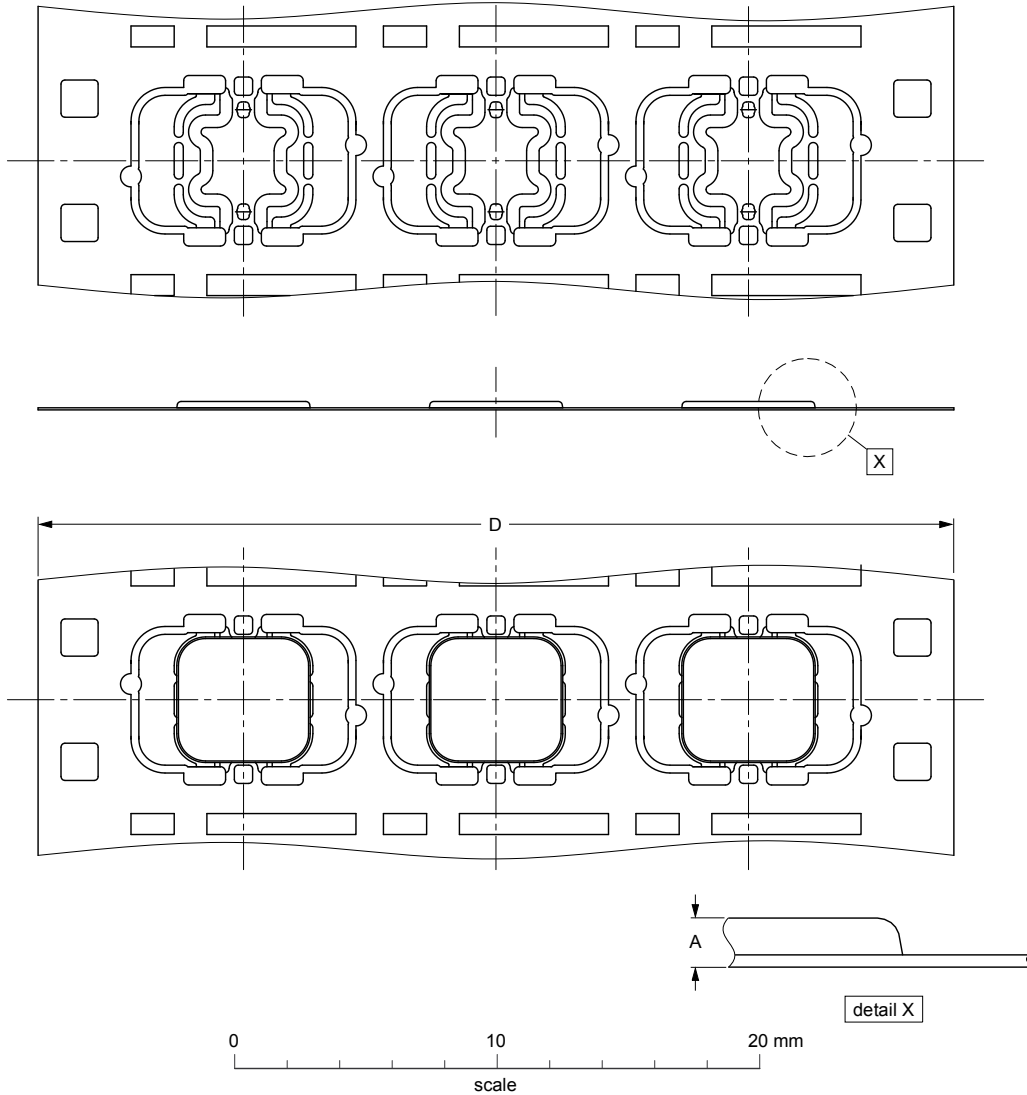
Electronic wafer mapping covers the electrical test results and additionally the results of mechanical/visual inspection. No ink dots are applied.

## 15.2 Package outline

For more details on the contactless modules MOA4 and MOA8 please refer to [Ref. 7](#) and [Ref. 8](#).

PLLMC: plastic leadless module carrier package; 35 mm wide tape

SOT500-2



**DIMENSIONS (mm are the original dimensions)**

UNIT	A <sup>(1)</sup> max.	D	For unspecified dimensions see PLLMC-drawing given in the subpackage code.
mm	0.33	35.05 34.95	

**Note**

1. Total package thickness, exclusive punching burr.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT500-2	---	---	---		03-09-17 06-05-22

Figure 23. Package outline SOT500-2

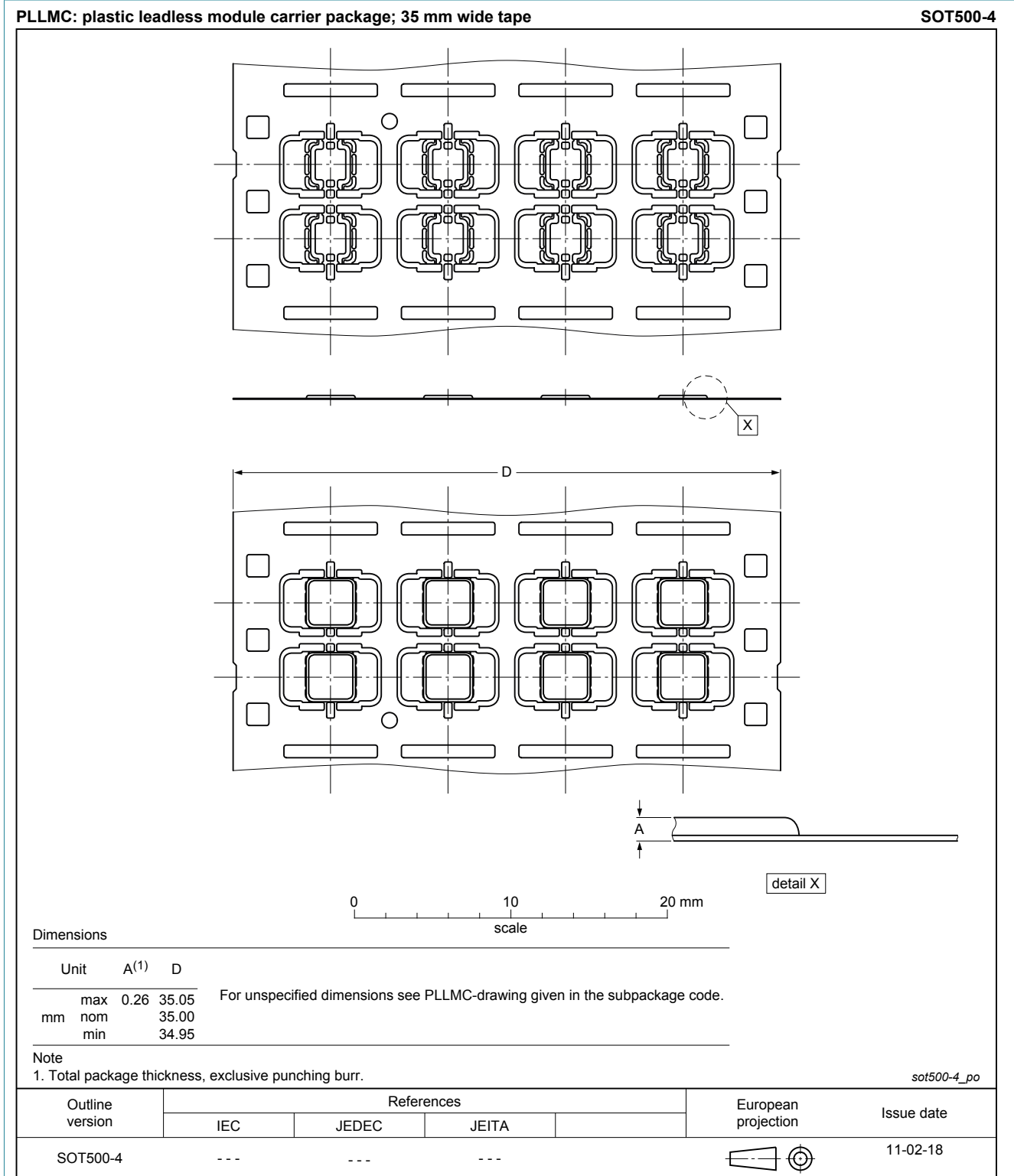
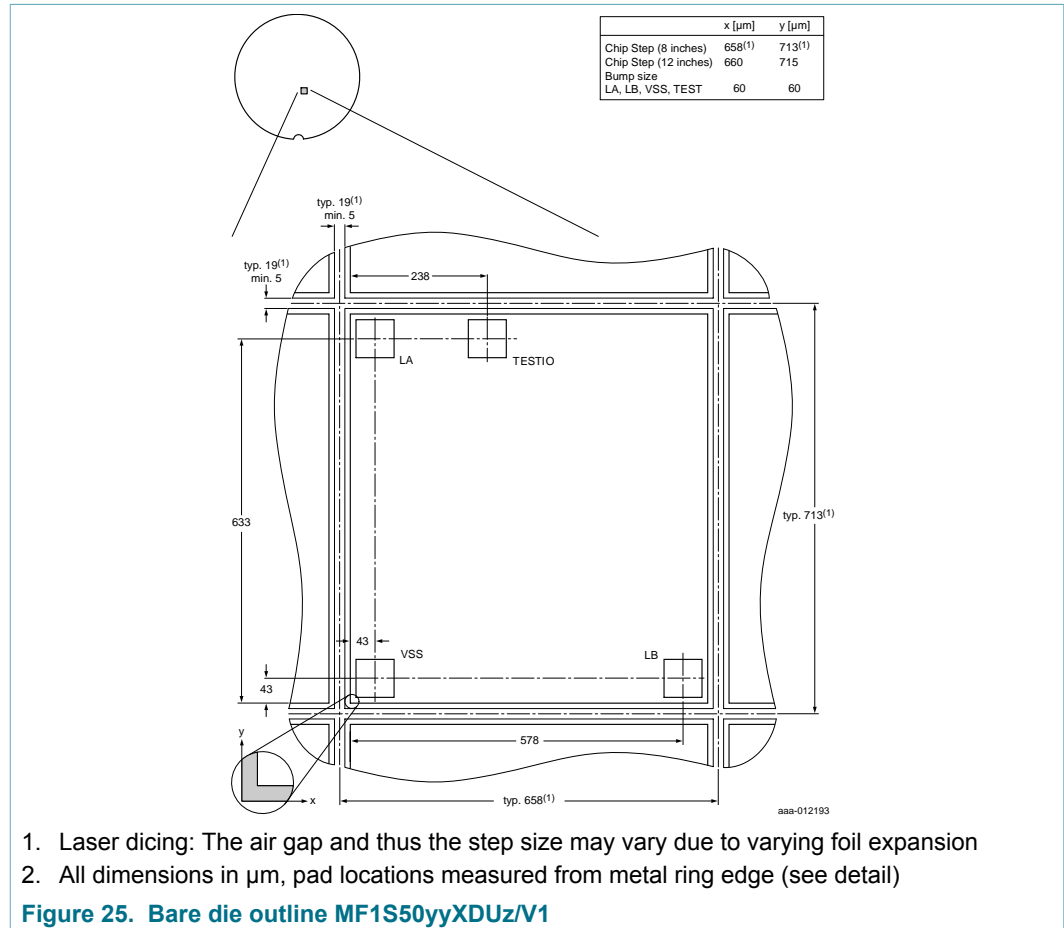


Figure 24. Package outline SOT500-4

## 16 Bare die outline

For more details on the wafer delivery forms, see [Ref. 9](#).



## 17 Abbreviations

Table 33. Abbreviations and symbols

Acronym	Description
ACK	ACKnowledge
ATQA	Answer To reQuest, Type A
CRC	Cyclic Redundancy Check
CT	Cascade Tag (value 88h) as defined in ISO/IEC 14443-3 Type A
EEPROM	Electrically Erasable Programmable Read-Only Memory
FDT	Frame Delay Time
FFC	Film Frame Carrier
IC	Integrated Circuit
LCR	L = inductance, Capacitance, Resistance (LCR meter)
LSB	Least Significant Bit



Acronym	Description
NAK	Not AcKnowledge
NUID	Non-Unique IDentifier
NV	Non-Volatile memory
PCD	Proximity Coupling Device (Contactless Reader)
PICC	Proximity Integrated Circuit Card (Contactless Card)
REQA	REQuest command, Type A
RID	Random ID
RF	Radio Frequency
RMS	Root Mean Square
RNG	Random Number Generator
SAK	Select AcKnowledge, type A
SECS-II	SEMI Equipment Communications Standard part 2
TiW	Titanium Tungsten
UID	Unique IDentifier
WUPA	Wake-Up Protocol type A

## 18 References

[1]

### MIFARE (Card) Coil Design Guide

Application note, BU-ID Document number 0117\*\*<sup>1</sup>

[2]

### MIFARE Type Identification Procedure

Application note, BU-ID Document number 0184\*\*<sup>1</sup>

[3]

### ISO/IEC 14443-2

2001

[4]

### ISO/IEC 14443-3

2001

[5]

### MIFARE & I-CODE CL RC632 Multiple protocol contactless reader IC

Product data sheet

[6]

### MIFARE product and handling of UIDs

<sup>1</sup> \*\* ... document version number

Application note, BU-ID Document number 1907\*\*<sup>1</sup>

[7]

**Contactless smart card module specification MOA4**

Delivery Type Description, BU-ID Document number 0823\*\*<sup>1</sup>

[8]

**Contactless smart card module specification MOA8**

Delivery Type Description, BU-ID Document number 1636\*\*<sup>1</sup>

[9]

**General specification for 8" wafer on UV-tape; delivery types**

Delivery Type Description, BU-ID Document number 1005\*\*<sup>1</sup>

## 19 Revision history

Table 34. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
MF1S50yyX/V1 v.3.2	20180523	Product data sheet	-	MF1S50yyX/V1 v.3.1
Modifications:	<ul style="list-style-type: none"> <li>• Editorial updates.</li> </ul>			
MF1S50yyX/V1 v.3.1	20171121	Product data sheet	-	MF1S50yyX/V1 v.3.0
Modifications:	<ul style="list-style-type: none"> <li>• 12 inch FFC delivery forms added</li> <li>• Format updated</li> </ul>			
MF1S50yyX/V1 v.3.0	20140303	Product data sheet	-	-

## 20 Legal information

### 20.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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**MIFARE Classic EV1 1K - Mainstream contactless smart card IC for fast and easy solution development**

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Date of release: 23 May 2018  
 Document identifier: MF1S50yyX\_V1  
 Document number: 279232

# MF3ICDx21\_41\_81

## MIFARE DESFire EV1 contactless multi-application IC

Rev. 3.2 — 9 December 2015  
145632

Product short data sheet  
COMPANY PUBLIC

### 1. General description

---

MIFARE DESFire EV1 (MF3ICD(H) 21/41/81), a Common Criteria (EAL4+) certified product, is ideal for service providers wanting to use secure multi-application smart cards in public transport schemes, access management or closed-loop e-payment applications. It fully complies with the requirements for fast and highly secure data transmission, flexible memory organization and interoperability with existing infrastructure.

MIFARE DESFire EV1 is based on open global standards for both air interface and cryptographic methods. It is compliant to all 4 levels of ISO/IEC 14443A and uses optional ISO/IEC 7816-4 commands.

Featuring an on-chip backup management system and the mutual three-pass authentication, a MIFARE DESFire EV1 card can hold up to 28 different applications and 32 files per application. The size of each file is defined at the moment of its creation, making MIFARE DESFire EV1 a truly flexible and convenient product.

Additionally, an automatic anti-tear mechanism is available for all file types, which guarantees transaction-oriented data integrity. With MIFARE DESFire EV1, data transfer rates up to 848 kbit/s can be achieved, allowing fast data transmission.

The main characteristics of this device are denoted by its name “DESFire”: DES indicates the high level of security using a 3DES or AES hardware cryptographic engine for enciphering transmission data and Fire indicates its outstanding position as a fast, innovative, reliable and secure IC in the contactless proximity transaction market. Hence, MIFARE DESFire EV1 brings many benefits to end users. Cardholders can experience convenient contactless ticketing while also having the possibility to use the same device for related applications such as payment at vending machines, access control or event ticketing. In other words, the MIFARE DESFire EV1 silicon solution offers enhanced consumer-friendly system design, in combination with security and reliability.

MIFARE DESFire EV1 delivers the perfect balance of speed, performance and cost efficiency. Its open concept allows future seamless integration of other ticketing media such as smart paper tickets, key fobs, and mobile ticketing based on Near Field Communication (NFC) technology. It is also fully compatible with the existing MIFARE reader hardware platform. MIFARE DESFire EV1 is your ticket to contactless systems worldwide.



## 2. Features and benefits

### 2.1 RF interface: ISO/IEC 14443 Type A

- Contactless transmission of data and powered by the RF-field (no battery needed)
- Operating distance: up to 100 mm (depending on power provided by the PCD and antenna geometry)
- Operating frequency: 13.56 MHz
- Fast data transfer: 106 kbit/s, 212 kbit/s, 424 kbit/s, 848 kbit/s
- High data integrity: 16/32 bit CRC, parity, bit coding, bit counting
- True deterministic anticollision
- 7 bytes unique identifier (cascade level 2 according to ISO/IEC 14443-3 and option for random ID)
- Uses ISO/IEC 14443-4 protocol

### 2.2 ISO/IEC 7816 compatibility

- Supports ISO/IEC 7816-3 APDU message structure
- Supports ISO/IEC 7816-4 INS code 'A4' for SELECT FILE
- Supports ISO/IEC 7816-4 INS code 'B0' for READ BINARY
- Supports ISO/IEC 7816-4 INS code 'D6' for UPDATE BINARY
- Supports ISO/IEC 7816-4 INS code 'B2' for READ RECORDS
- Supports ISO/IEC 7816-4 INS code 'E2' for APPEND RECORD
- Supports ISO/IEC 7816-4 INS code '84' for GET CHALLENGE
- Supports ISO/IEC 7816-4 INS code '88' for INTERNAL AUTHENTICATE
- Supports ISO/IEC 7816-4 INS code '82' for EXTERNAL AUTHENTICATE

### 2.3 Non-volatile memory

- 2 kB or 4 kB or 8 kB NV-Memory
- Data retention of 10 years
- Write endurance typical 500 000 cycles

### 2.4 NV-memory organization

- Flexible file system
- Up to 28 applications simultaneously on one PICC
- Up to 32 files in each application (standard data file, back-up data file, value file, linear record file and cyclic record file)
- File size is determined during creation

### 2.5 Security

- Common Criteria Certification: EAL4+ (Hardware and Software)
- Unique 7 bytes serial number for each device
- Optional "RANDOM" ID for enhance security and privacy
- Mutual three-pass authentication
- Mutual authentication according to ISO/IEC 7816-4



- 1 card master key and up to 14 keys per application
- Hardware DES using 56/112/168 bit keys featuring key version, data authenticity by 8 byte CMAC
- Hardware AES using 128-bit keys featuring key version, data authenticity by 8 byte CMAC
- Data encryption on RF-channel
- Authentication on application level
- Hardware exception sensors
- Self-securing file system
- Backward compatibility to MF3ICD40: 4 byte MAC, CRC 16

## 2.6 Special features

- Transaction-oriented automatic anti-tear mechanism
- Configurable ATS information for card personalization
- Backward compatibility mode to MF3ICD40
- Optional high input capacitance (70 pF) for small form factor design (MF3ICDH 21/41/81)

## 3. Applications

---

- Advanced public transportation schema
- Highly secure access management
- Closed-loop e-payment scheme
- Event ticketing
- eGovernment applications

## 4. Quick reference data

Table 1. Quick reference data [1][2]

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$f_i$	input frequency		-	13.56	-	MHz
$C_i$	input capacitance for MF3ICD21/41/81	$T_{amb} = 22\text{ °C}$ ; $f_i = 13.56\text{ MHz}$ ; 2.8 V RMS	[3] 14.96	17.0	19.04	pF
	input capacitance for MF3ICDH21/41/81		64	69	74	pF
<b>EEPROM characteristics</b>						
$t_{ret}$	retention time	$T_{amb} = 22\text{ °C}$	10	-	-	year
$N_{endu(W)}$	write endurance	$T_{amb} = 22\text{ °C}$	200000	500000	-	cycle
$t_{cy(W)}$	write cycle time	$T_{amb} = 22\text{ °C}$	-	2.9	-	ms

[1] Stresses above one or more of the values may cause permanent damage to the device.

[2] Exposure to limiting values for extended periods may affect device reliability.

[3] Measured with LCR meter.

## 5. Ordering information

Table 2. Ordering information

Type number	Package		Version
	Name	Description	
MF3ICD8101DUD/05	FFC	8 inch wafer (sawn; 120 $\mu\text{m}$ thickness, on film frame carrier; electronic fail die marking according to SECSII format); see <a href="#">Ref. 4</a> , 8K EEPROM, 17pF input capacitance	-
MF3ICD4101DUD/05	FFC	8 inch wafer (sawn; 120 $\mu\text{m}$ thickness, on film frame carrier; electronic fail die marking according to SECSII format); see <a href="#">Ref. 4</a> , 4K EEPROM, 17pF input capacitance	-
MF3ICD2101DUD/05	FFC	8 inch wafer (sawn; 120 $\mu\text{m}$ thickness, on film frame carrier; electronic fail die marking according to SECSII format); see <a href="#">Ref. 4</a> , 2K EEPROM, 17pF input capacitance	-
MF3ICDH8101DUD/05	FFC	8 inch wafer (sawn; 120 $\mu\text{m}$ thickness, on film frame carrier; electronic fail die marking according to SECSII format); see <a href="#">Ref. 5</a> , 8K EEPROM, 70pF input capacitance	-
MF3ICDH4101DUD/05	FFC	8 inch wafer (sawn; 120 $\mu\text{m}$ thickness, on film frame carrier; electronic fail die marking according to SECSII format); see <a href="#">Ref. 5</a> , 4K EEPROM, 70pF input capacitance	-
MF3ICDH2101DUD/05	FFC	8 inch wafer (sawn; 120 $\mu\text{m}$ thickness, on film frame carrier; electronic fail die marking according to SECSII format); see <a href="#">Ref. 5</a> , 2K EEPROM, 70pF input capacitance	-
MF3MOD8101DA4/05	PLLMC[1]	plastic leadless module carrier package; 35 mm wide tape; see <a href="#">Ref. 6</a> , 8K EEPROM, 17pF input capacitance	SOT500-2
MF3MOD4101DA4/05	PLLMC[1]	plastic leadless module carrier package; 35 mm wide tape; see <a href="#">Ref. 6</a> , 4K EEPROM, 17pF input capacitance	SOT500-2
MF3MOD2101DA4/05	PLLMC[1]	plastic leadless module carrier package; 35 mm wide tape; see <a href="#">Ref. 6</a> , 2K EEPROM, 17pF input capacitance	SOT500-2
MF3MODH8101DA4/05	PLLMC[1]	plastic leadless module carrier package; 35 mm wide tape; see <a href="#">Ref. 6</a> , 8K EEPROM, 70pF input capacitance	SOT500-2

Table 2. Ordering information *?continued*

Type number	Package		Version
	Name	Description	
MF3MODH4101DA4/05	PLLMC <sup>[1]</sup>	plastic leadless module carrier package; 35 mm wide tape; see <a href="#">Ref. 6</a> , 4K EEPROM, 70pF input capacitance	SOT500-2
MF3MODH2101DA4/05	PLLMC <sup>[1]</sup>	plastic leadless module carrier package; 35 mm wide tape; see <a href="#">Ref. 6</a> , 2K EEPROM, 70pF input capacitance	SOT500-2
MF3MOD8101DA8/05	PLLMC <sup>[2]</sup>	plastic leadless module carrier package; 35 mm wide tape; see <a href="#">Ref. 6</a> , 8K EEPROM, 17pF input capacitance	SOT500-4
MF3MOD4101DA8/05	PLLMC <sup>[2]</sup>	plastic leadless module carrier package; 35 mm wide tape; see <a href="#">Ref. 6</a> , 4K EEPROM, 17pF input capacitance	SOT500-4
MF3MOD2101DA8/05	PLLMC <sup>[2]</sup>	plastic leadless module carrier package; 35 mm wide tape; see <a href="#">Ref. 6</a> , 2K EEPROM, 17pF input capacitance	SOT500-4
MF3MODH8101DA8/05	PLLMC <sup>[2]</sup>	plastic leadless module carrier package; 35 mm wide tape; see <a href="#">Ref. 6</a> , 8K EEPROM, 70pF input capacitance	SOT500-4
MF3MODH4101DA8/05	PLLMC <sup>[2]</sup>	plastic leadless module carrier package; 35 mm wide tape; see <a href="#">Ref. 6</a> , 4K EEPROM, 70pF input capacitance	SOT500-4
MF3MODH2101DA8/05	PLLMC <sup>[2]</sup>	plastic leadless module carrier package; 35 mm wide tape; see <a href="#">Ref. 6</a> , 2K EEPROM, 70pF input capacitance	SOT500-4

- [1] This package is also known as MOA4.
- [2] This package is also known as MOA8

## 6. Block diagram

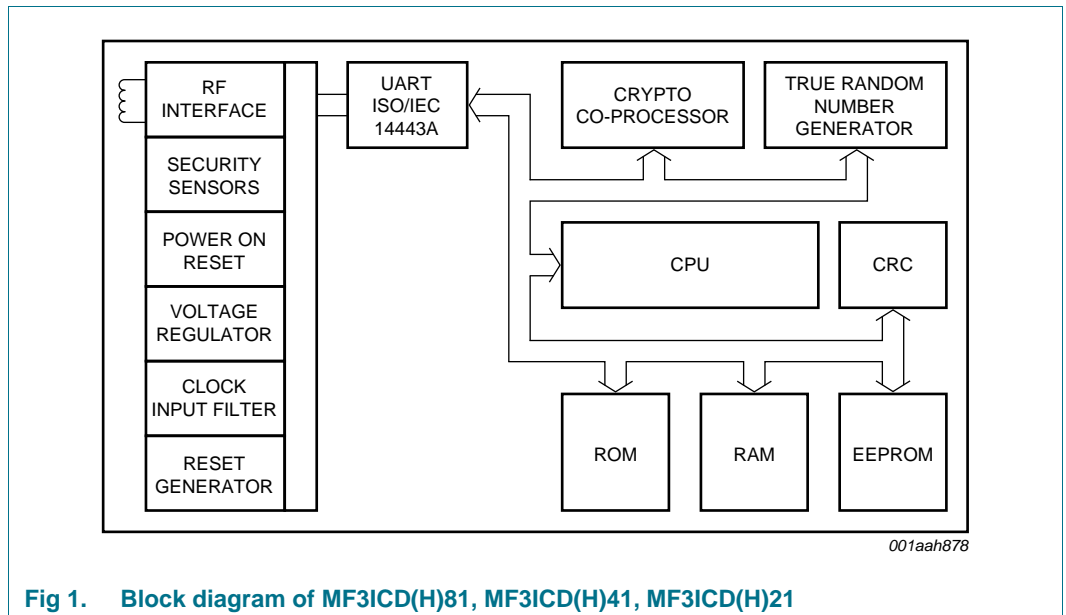


Fig 1. Block diagram of MF3ICD(H)81, MF3ICD(H)41, MF3ICD(H)21

## 7. Limiting values

**Table 3. Limiting values** [\[1\]](#)[\[2\]](#)

*In accordance with the Absolute Maximum Rating System (IEC 60134).*

Symbol	Parameter	Conditions	Min	Max	Unit
$I_I$	input current		-	30	mA
$P_{tot}/pack$	total power dissipation per package		-	200	mW
$T_{stg}$	storage temperature		-55	125	°C
$T_{amb}$	ambient temperature		-25	70	°C
$V_{ESD}$	electrostatic discharge voltage		<a href="#">[3]</a> 2	-	kV
$I_{lu}$	latch-up current		±100	-	mA

[1] Stresses above one or more of the limiting values may cause permanent damage to the device.

[2] Exposure to limiting values for extended periods may affect device reliability.

[3] MIL Standard 883-C method 3015; human body model: C = 100 pF, R = 1.5 kΩ.

## 8. Functional description

### 8.1 Contactless energy and data transfer

In the MIFARE system, the MIFARE DESFire EV1 is connected to a coil consisting of a few turns embedded in a standard ISO/IEC smart card (see [Ref. 8](#)). A battery is not needed. When the card is positioned in the proximity of the PCD antenna, the high-speed RF communication interface allows data to be transmitted up to 848 kbit/s.

### 8.2 Anti-collision

An intelligent anti-collision mechanism allows more than one MIFARE DESFire EV1 in the field to be handled simultaneously. The anti-collision algorithm selects each MIFARE DESFire EV1 individually and ensures that the execution of a transaction with a selected MIFARE DESFire EV1 is performed correctly without data corruption resulting from other MIFARE DESFire EV1s in the field.

### 8.3 UID/serial number

The unique 7 byte (UID) is programmed into a locked part of the NV memory which is reserved for the manufacturer. Due to security and system requirements these bytes are write-protected after being programmed by the IC manufacturer at production time. According to ISO/IEC 14443-3 (see [Ref. 12](#)) during the first anti-collision loop the cascade tag returns a value of 88h and also the first 3 bytes of the UID, UID0 to UID2 and BCC. The second anti-collision loop returns bytes UID3 to UID6 and BCC.

UID0 holds the manufacturer ID for NXP (04h) according to ISO/IEC 14443-3 and ISO/IEC 7816-6 AMD 1.

MIFARE DESFire EV1 also allows Random ID to be used. In this case MIFARE DESFire EV1 only uses a single anti-collision loop. The 3 byte random number is generated after RF reset of the MIFARE DESFire EV1.

### 8.4 Memory organization

The 2/4/8 KB NV memory is organized using a flexible file system. This file system allows a maximum of 28 different applications on one MIFARE DESFire EV1. Each application provides up to 32 files. Every application is represented by its 3 bytes Application Identifier (AID).

Five different file types are supported; see [Section 8.5](#).

A guideline to assign MIFARE DESFire AIDs can be found in the application note *MIFARE Application Directory (MAD)*; see [Ref. 9](#).

Each file can be created either at MIFARE DESFire EV1 initialization (card production/card printing), at MIFARE DESFire EV1 personalization (vending machine) or in the field.

If a file or application becomes obsolete in operation, it can be permanently invalidated.

Commands which have impact on the file structure itself (e.g. creation or deletion of applications, change of keys) activate an automatic rollback mechanism, which protects the file structure from being corrupted.

If this rollback is necessary, it is done without user interaction before carrying out further commands. To ensure data integrity on application level, a transaction-oriented backup is implemented for all file types with backup. It is possible to mix file types with and without backup within one application.

As the commands are the same for MF3ICD(H)81, MF3ICD(H)41 and MF3ICD(H)21, the command details are available in [Ref. 1](#). Only the memory size and input capacitance are different between the devices.

## 8.5 Available file types

The files within an application can be any of the following types:

- Standard data files
- Backup data files
- Value files with backup
- Linear record files with backup
- Cyclic record files with backup

## 8.6 Security

The 7 byte UID is fixed, programmed into each device during production. It cannot be altered and ensures the uniqueness of each device.

The UID may be used to derive diversified keys for each ticket. Diversified MIFARE DESFire EV1 keys contribute to gain an effective anti-cloning mechanism and increase the security of the original key; see [Ref. 7](#).

Prior to data transmission a mutual three-pass authentication can be done between MIFARE DESFire EV1 and PCD depending on the configuration employing either 56-bit DES (single DES, DES), 112-bit 3DES (triple DES, 2K3DES), 168-bit 3DES (3 key triple DES, 3K3DES) or AES. During the authentication the level of security of all further commands during the session is set. In addition, the communication settings of the file/application result in the following options of secure communication between MIFARE DESFire EV1 and PCD:

- Plain data transfer (only possible within the backwards-compatible mode to MF3ICD40)
- Plain data transfer with cryptographic checksum (MAC): Authentication with backwards-compatible mode to MF3ICD40: 4 byte MAC, all other authentications based on DES/3DES/AES: 8 byte CMAC
- Encrypted data transfer (secured by CRC before encryption): Authentication with backwards-compatible mode to MF3ICD40: A 16-bit CRC is calculated over the stream and attached. The resulting stream is encrypted using the chosen cryptographic method. All other authentications-based DES/3DES/AES: A 32-bit CRC is calculated over the stream and attached. The resulting stream is encrypted using the chosen cryptographic method.

Find more information on the security concept of the product in [Ref. 1](#). Be aware not all levels of security are recommended. The recommended secure handling of the product can be seen in [Ref. 2](#) and in [Ref. 11](#).

## 9. DESFire command set

A detailed description of all commands is provided in [Ref. 1](#).

### 9.1 ISO/IEC 14443-3

Table 4. ISO/IEC 14443-3

Command	Description
REQA	REQA and ATQA are implemented fully according to ISO/IEC 14443-3
WUPA	WUPA is implemented fully according to ISO/IEC 14443-3
ANTICOLLISION/SELECT Cascade Level 1	ANTICOLLISION and SELECT commands are implemented fully according to ISO/IEC 14443-3; the response is part 1 of the UID
ANTICOLLISION/SELECT Cascade Level 2	ANTICOLLISION and SELECT commands are implemented fully according to ISO/IEC 14443-3; the response is part 2 of the UID
HALT	brings MIFARE DESFire EV1 to the HALT state

### 9.2 ISO/IEC 14443-4

Table 5. ISO/IEC 14443-4

Command	Description
RATS	identifies the MIFARE DESFire EV1 type to the PCD
PPS	allows individual selection of the communication baud rate between PCD and MIFARE DESFire EV1; for DESFire it is possible to set different communication baud rates for each direction i.e. DESFire allows a non-symmetrical information interchange speed.
WTX	if the MIFARE DESFire EV1 needs more time than the defined FWT to respond to a PCD command it requests a Waiting Time eXtension (WTX)
DESELECT	allows MIFARE DESFire EV1 to be brought to the HALT state

### 9.3 MIFARE DESFire EV1 command set overview – security related commands

Table 6. Security related commands

Command	Description
Authenticate	MIFARE DESFire EV1 and the reader device show in an encrypted way that they possess the same secret which especially means the same key; this not only confirms that both entities are permitted to perform operations on each other but also creates a session key which can be used to keep the further communication path secure; as the name “session key” implicitly indicates, each time a new authentication procedure is successfully completed a new key for further cryptographic operations is generated
Change KeySettings	changes the master key settings on MIFARE DESFire EV1 and application level
Set Configuration	configures the card and pre-personalizes the card with a key, defines if the UID or the random ID is sent back during communication setup and configures the ATS string
Change Key	changes any key stored on the MIFARE DESFire EV1
Get Key Version	reads out the current key version of any key stored on the MIFARE DESFire EV1

**Remark:** All command and data frames are exchanged between MIFARE DESFire EV1 and PCD by using block format as defined in ISO/IEC 14443-4.

### 9.4 MIFARE DESFire EV1 command set overview – MIFARE DESFire EV1 level commands

Table 7. Level commands

Command	Description
Create Application	creates new applications on the MIFARE DESFire EV1
Delete Application	permanently deactivates applications on the MIFARE DESFire EV1
Get Applications IDs	returns the Application IDentifiers of all applications on a MIFARE DESFire EV1
Free Memory	returns the free memory available on the card
GetDFNames	returns the DF names
Get KeySettings	gets information on the MIFARE DESFire EV1 and application master key settings; in addition it returns the maximum number of keys which are configured for the selected application
Select Application	selects one specific application for further access
FormatMF3ICD81	releases the MF3ICD81 user memory
Get Version	returns manufacturing related data of the MIFARE DESFire EV1
GetCardUID	returns the UID

**Remark:** All command and data frames are exchanged between MIFARE DESFire EV1 and PCD by using block format as defined in ISO/IEC 14443-4.



### 9.5 MIFARE DESFire EV1 command set overview – application level commands

Table 8. Application level commands

Command	Description
Get FileIDs	returns the File IDentifiers of all active files within the currently selected application
Get FileSettings	gets information on the properties of a specific file
Change FileSettings	changes the access parameters of an existing file
Create StdDataFile	creates files for the storage of plain unformatted user data within an existing application on the MIFARE DESFire EV1
Create BackupDataFile	creates files for the storage of plain unformatted user data within an existing application on the MIFARE DESFire EV1, additionally supporting the feature of an integrated backup mechanism
Create ValueFile	creates files for the storage and manipulation of 32-bit signed integer values within an existing application on the MIFARE DESFire EV1
Create LinearRecordFile	creates files for multiple storage of similar structural data, for example, loyalty programs within an existing application on the MIFARE DESFire EV1; once the file is filled completely with data records, further writing to the file is not possible unless it is cleared
Create CyclicRecordFile	creates files for multiple storage of similar structural data, for example, logging transactions within an existing application on the MIFARE DESFire EV1; once the file is filled completely with data records, the MIFARE DESFire EV1 automatically overwrites the oldest record with the latest written one (this wrap is fully transparent for the PCD)
DeleteFile	permanently deactivates a file within the file directory of the currently selected application

**Remark:** All command and data frames are exchanged between MIFARE DESFire EV1 and PCD by using block format as defined in ISO/IEC 14443-4.

### 9.6 MIFARE DESFire EV1 command set overview – data manipulation commands

Table 9. Data manipulation commands

Command	Description
Read Data	reads data from Standard Data files or Backup Data files
Write Data	writes data to Standard Data files or Backup Data files
Get Value	reads the currently stored value from Value files
Credit	increases a value stored in a Value file
Debit	decreases a value stored in a Value file
Limited Credit	allows a limited increase of a value stored in a Value file without having full Credit permissions to the file
Write Record	writes data to a record in a Cyclic or Linear Record file
Read Records	reads out a set of complete records from a Cyclic or Linear Record file

**Table 9. Data manipulation commands** *?continued*

Command	Description
Clear RecordFile	resets a Cyclic or Linear Record file to empty state
Commit Transaction	validates all previous write accesses on Backup Data files, Value files and Record files within one application
Abort Transaction	invalidates all previous write accesses on Backup Data files, Value files and Record files within one application

**Remark:** All command and data frames are exchanged between MIFARE DESFire EV1 and PCD by using block format as defined in ISO/IEC 14443-4.

## 9.7 MIFARE DESFire EV1 command set - ISO/IEC 7816 APDU commands

The MIFARE DESFire EV1 provides the following commands according to ISO/IEC 7816-4:

- INS code 'A4' SELECT
- INS code 'B0' READ BINARY
- INS code 'D6' UPDATE BINARY
- INS code 'B2' READ RECORDS
- INS code 'E2' APPEND RECORD
- INS code '84' GET CHALLENGE
- INS code '88' INTERNAL AUTHENTICATE
- INS code '82' EXTERNAL AUTHENTICATE

### 9.7.1 ISO/IEC 7816-4 APDU message structure

MIFARE DESFire EV1 supports the APDU message structure according to ISO/IEC 7816-4 for:

- an optional wrapping of the native MIFARE DESFire EV1 APDU format
- additionally implemented ISO/IEC 7816-4 commands

Find more information on the ISO/IEC 7816-4 commands in [Ref. 1](#).

## 10. Abbreviations

Table 10. Abbreviations

Acronym	Description
AES	Advanced Encryption Standard
AID	Application Identifier
APDU	Application Protocol Data Unit
ATS	Answer to Select
CC	Common Criteria
CMAC	Cryptic Message Authentication Code
CRC	Cyclic Redundancy Check
DES	Digital Encryption Standard
DF	Dedicated File
EAL	Evaluation Assurance Level
EEPROM	Electrically Erasable Programmable Read-Only Memory
FWT	Frame Waiting Time
ID	Identifier
INS	Instructions
LCR	inductance, Capacitance, Resistance
MAC	Message Authentication Code
MAD	MIFARE Application Directory
NV	Non-Volatile Memory
PCD	Proximity Coupling Device
PPS	Protocol Parameter Selection
RATS	Request Answer To Select
REQA	Request Answer
RF	Radio Frequency
UID	Unique Identifier
WTX	Waiting Time eXtension
WUPA	Wake Up Protocol A

## 11. References

- [1] **Data sheet** — *MF3ICD81 MIFARE DESFire EV1*, document number: 13403\*\*1.
- [2] **Data sheet** — *MF3ICD81 Guidance, Delivery and Operation Manual*, document number: 1469\*\*.
- [3] **Data sheet** — *Specification addendum MF3ICD81*, document number: 1673\*\*.
- [4] **Data sheet** — *MF3ICD8101 Sawn bumped 120  $\mu$ m wafer addendum*, document number: 1318\*\*.
- [5] **Data sheet** — *MF3ICDH8101 Sawn bumped 120  $\mu$ m wafer addendum*, document number: 1970\*\*.
- [6] **Data sheet** — *MF3MODx21\_41\_81 Contactless chip card module*, document number: 1439\*\*.
- [7] **Application note** — *MIFARE DESFire - Implementation hints and examples*, document number: 0945\*\*.
- [8] **Application note** — *Card Coil Design Notes for MIFARE DESFire EV1*, document number: 1713\*\*.
- [9] **Application note** — *MIFARE Application Directory*, document number: 0018\*\*.
- [10] **Application note** — *MIFARE ISO/IEC 14443 PICC Selection*, document number: 1308\*\*.
- [11] **Application note** — *End to end system security risk considerations for implementing contactless cards*, document number: 1550\*\*.
- [12] **ISO/IEC Standard** — *ISO/IEC 14443 Identification cards - Contactless integrated circuit cards - Proximity cards*.

1. \*\* ... BU-ID document version number

## 12. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
MF3ICDX21_41_81_SDS v3.2	20151209	Product short data sheet	-	MF3ICDX21_41_81_SDS v3.1
Modifications:	<ul style="list-style-type: none"> <li>• <a href="#">Section 5</a>: MOA8 types added</li> </ul>			
MF3ICDX21_41_81_SDS v3.1	20101221	Product short data sheet	-	MF3ICD21_41_81_SDS_2
Modifications:	<ul style="list-style-type: none"> <li>• Data sheet title updated</li> <li>• <a href="#">Section 1</a>, <a href="#">Section 2</a>, <a href="#">Section 3</a>, <a href="#">Section 11</a>, <a href="#">Section 13</a>: updated</li> <li>• <a href="#">Section 5</a>: type number MF3ICD801DUD/04 changed to MF3ICD8101DUD/05</li> </ul>			
MF3ICD21_41_81_SDS_2	20090306	Product short data sheet	-	MF3ICD8101_SDS_N_1
Modifications:	<ul style="list-style-type: none"> <li>• Section 5 "Ordering information": type number MF3ICD8101DUD/01 changed to MF3ICD8101DUD/04</li> <li>• Section 5 "Ordering information": added root type numbers MF3ICD41 and MF3ICD21</li> <li>• Section 1 "General description", Section 2 "Features and benefits" and Section 3 "Applications": updated</li> <li>• Section 11 "References": added</li> </ul>			
MF3ICD8101_SDS_N_1	20071213	Objective short data sheet	-	-

## 13. Legal information

### 13.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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15. Tables

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Please be aware that important notices concerning this document and the product(s) described herein, have been included in section 'Legal information'.



# MF1S70YYX\_V1

## MIFARE Classic EV1 4K - Mainstream contactless smart card IC for fast and easy solution development

Rev. 3.2 — 23 November 2017  
279332

Product data sheet  
COMPANY PUBLIC

## 1 General description

NXP Semiconductors has developed the MIFARE Classic MF1S70yyX/V1 to be used in a contactless smart card according to ISO/IEC 14443 Type A.

The MIFARE Classic EV1 4K MF1S70yyX/V1 IC is used in applications like public transport ticketing and can also be used for various other applications.

### 1.1 Anticollision

An intelligent anticollision function allows to operate more than one card in the field simultaneously. The anticollision algorithm selects each card individually and ensures that the execution of a transaction with a selected card is performed correctly without interference from another card in the field.

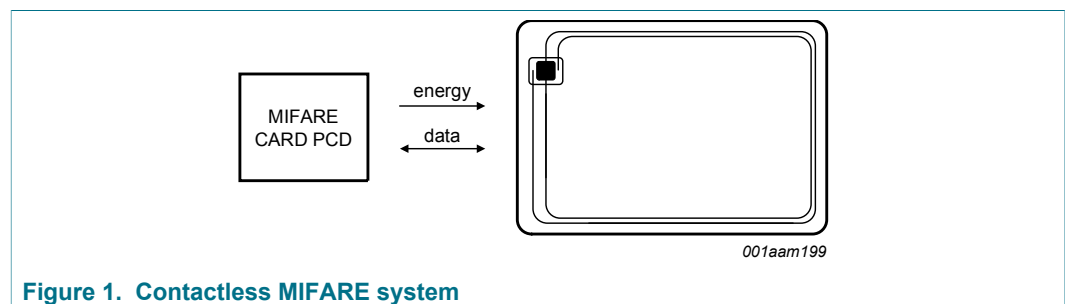


Figure 1. Contactless MIFARE system

### 1.2 Simple integration and user convenience

The MF1S70yyX/V1 is designed for simple integration and user convenience which allows complete ticketing transactions to be handled in less than 100 ms.

### 1.3 Security and privacy

- Manufacturer programmed 7-byte UID or 4-byte NUID identifier for each device
- Random ID support
- Mutual three pass authentication (ISO/IEC DIS 9798-2)
- Individual set of two keys per sector to support multi-application with key hierarchy

### 1.4 Delivery options

- 7-byte UID, 4-byte NUID
- Bumped die on sawn wafer
- MOA4 and MOA8 contactless module



## 2 Features and benefits

- Contactless transmission of data and energy supply
- Operating frequency of 13.56 MHz
- Data integrity of 16-bit CRC, parity, bit coding, bit counting
- Typical ticketing transaction time of < 100 ms (including backup management)
- Random ID support (7 Byte UID version)
- Operating distance up to 100 mm depending on antenna geometry and reader configuration
- Data transfer of 106 kbit/s
- Anticollision
- 7 Byte UID or 4 Byte NUID

### 2.1 EEPROM

- 4 kB, organized in 32 sectors of 4 blocks and 8 sectors of 16 blocks (one block consists of 16 byte)
- Data retention time of 10 years
- User definable access conditions for each memory block
- Write endurance 200000 cycles

## 3 Applications

- Public transportation
- Electronic toll collection
- School and campus cards
- Internet cafés
- Access management
- Car parking
- Employee cards
- Loyalty

## 4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$C_i$	input capacitance		[1]	14.9	16.9	19.0	pF
$f_i$	input frequency			-	13.56	-	MHz
<b>EEPROM characteristics</b>							
$t_{ret}$	retention time	$T_{amb} = 22\text{ °C}$		10	-	-	year
$N_{endu(W)}$	write endurance	$T_{amb} = 22\text{ °C}$		100000	200000	-	cycle

[1]  $T_{amb}=22\text{°C}$ ,  $f=13,56\text{MHz}$ ,  $V_{LaLb} = 1,5\text{ V RMS}$

## 5 Ordering information

Table 2. Ordering information

Type number	Package		Version
	Name	Description	
MF1S7001XDUD/V1	FFC Bump	8 inch wafer, 120 µm thickness, on film frame carrier, electronic fail die marking according to SECS-II format), Au bumps, 7-byte UID	-
MF1S7001XDUD2/V1	FFC Bump	12 inch wafer, 120 µm thickness, on film frame carrier, electronic fail die marking according to SECS-II format), Au bumps, 7-byte UID	-
MF1S7001XDUF/V1	FFC Bump	8 inch wafer, 75 µm thickness, on film frame carrier, electronic fail die marking according to SECS-II format), Au bumps, 7-byte UID	-
MF1S7000XDA4/V1	MOA4	plastic leadless module carrier package; 35 mm wide tape, 7-byte UID	SOT500-2
MF1S7000XDA8/V1	MOA8	plastic leadless module carrier package; 35 mm wide tape, 7-byte UID	SOT500-4
MF1S7031XDUD/V1	FFC Bump	8 inch wafer, 120 µm thickness, on film frame carrier, electronic fail die marking according to SECS-II format), Au bumps, 4-byte non-unique ID	-
MF1S7031XDUD2/V1	FFC Bump	12 inch wafer, 120 µm thickness, on film frame carrier, electronic fail die marking according to SECS-II format), Au bumps, 4-byte non-unique ID	-
MF1S7031XDUF/V1	FFC Bump	8 inch wafer, 75 µm thickness, on film frame carrier, electronic fail die marking according to SECS-II format), Au bumps, 4-byte non-unique ID	-
MF1S7030XDA4/V1	MOA4	plastic leadless module carrier package; 35 mm wide tape, 4-byte non-unique ID	SOT500-2
MF1S7030XDA8/V1	MOA8	plastic leadless module carrier package; 35 mm wide tape, 4-byte non-unique ID	SOT500-4

## 6 Block diagram

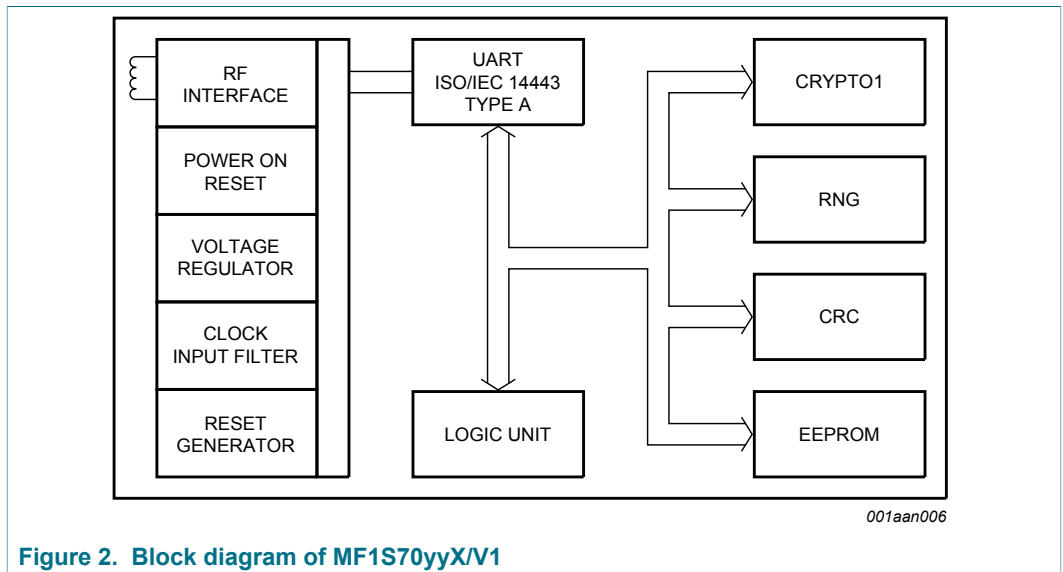


Figure 2. Block diagram of MF1S70yyX/V1

## 7 Pinning information

### 7.1 Pinning

The pinning for the MF1S70yyX/V1Dax is shown as an example in [Figure 3](#) for the MOA4 contactless module. For the contactless module MOA8, the pinning is analogous and not explicitly shown.

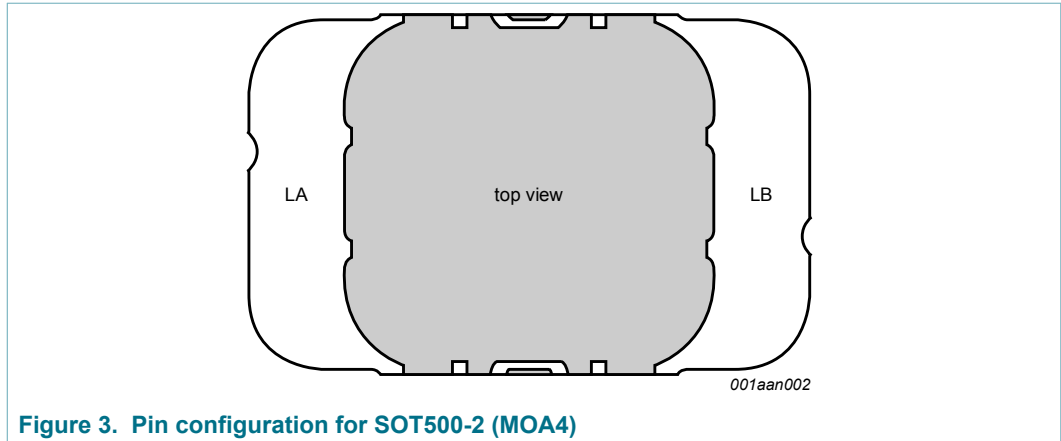


Figure 3. Pin configuration for SOT500-2 (MOA4)

Table 3. Pin allocation table

Pin	Symbol	
LA	LA	Antenna coil connection LA
LB	LB	Antenna coil connection LB

## 8 Functional description

### 8.1 Block description

The MF1S70yyX/V1 chip consists of a 4 kB EEPROM, RF interface and Digital Control Unit. Energy and data are transferred via an antenna consisting of a coil with a small number of turns which is directly connected to the MF1S70yyX/V1. No further external components are necessary. Refer to the document [Ref. 1](#) for details on antenna design.

- RF interface:
  - Modulator/demodulator
  - Rectifier
  - Clock regenerator
  - Power-On Reset (POR)
  - Voltage regulator
- Anticollision: Multiple cards in the field may be selected and managed in sequence
- Authentication: Preceding any memory operation the authentication procedure ensures that access to a block is only possible via the two keys specified for each block

- Control and Arithmetic Logic Unit: Values are stored in a special redundant format and can be incremented and decremented
- EEPROM interface
- Crypto unit: The CRYPTO1 stream cipher of the MF1S70yyX/V1 is used for authentication and encryption of data exchange.
- EEPROM: 4 kB is organized in 32 sectors of 4 blocks and 8 sectors of 16 blocks. One block contains 16 bytes. The last block of each sector is called "trailer", which contains two secret keys and programmable access conditions for each block in this sector.

## 8.2 Communication principle

The commands are initiated by the reader and controlled by the Digital Control Unit of the MF1S70yyX/V1. The command response is depending on the state of the IC and for memory operations also on the access conditions valid for the corresponding sector.

### 8.2.1 Request standard / all

After Power-On Reset (POR) the card answers to a request REQA or wakeup WUPA command with the answer to request code (see [Section 9.4](#), ATQA according to ISO/IEC 14443A).

### 8.2.2 Anticollision loop

In the anticollision loop the identifier of a card is read. If there are several cards in the operating field of the reader, they can be distinguished by their identifier and one can be selected (select card) for further transactions. The unselected cards return to the idle state and wait for a new request command. If the 7-byte UID is used for anticollision and selection, two cascade levels need to be processed as defined in ISO/IEC 14443-3.

**Remark:** For the 4-byte non-unique ID product versions, the identifier retrieved from the card is not defined to be unique. For further information regarding handling of non-unique identifiers see [Ref. 6](#).

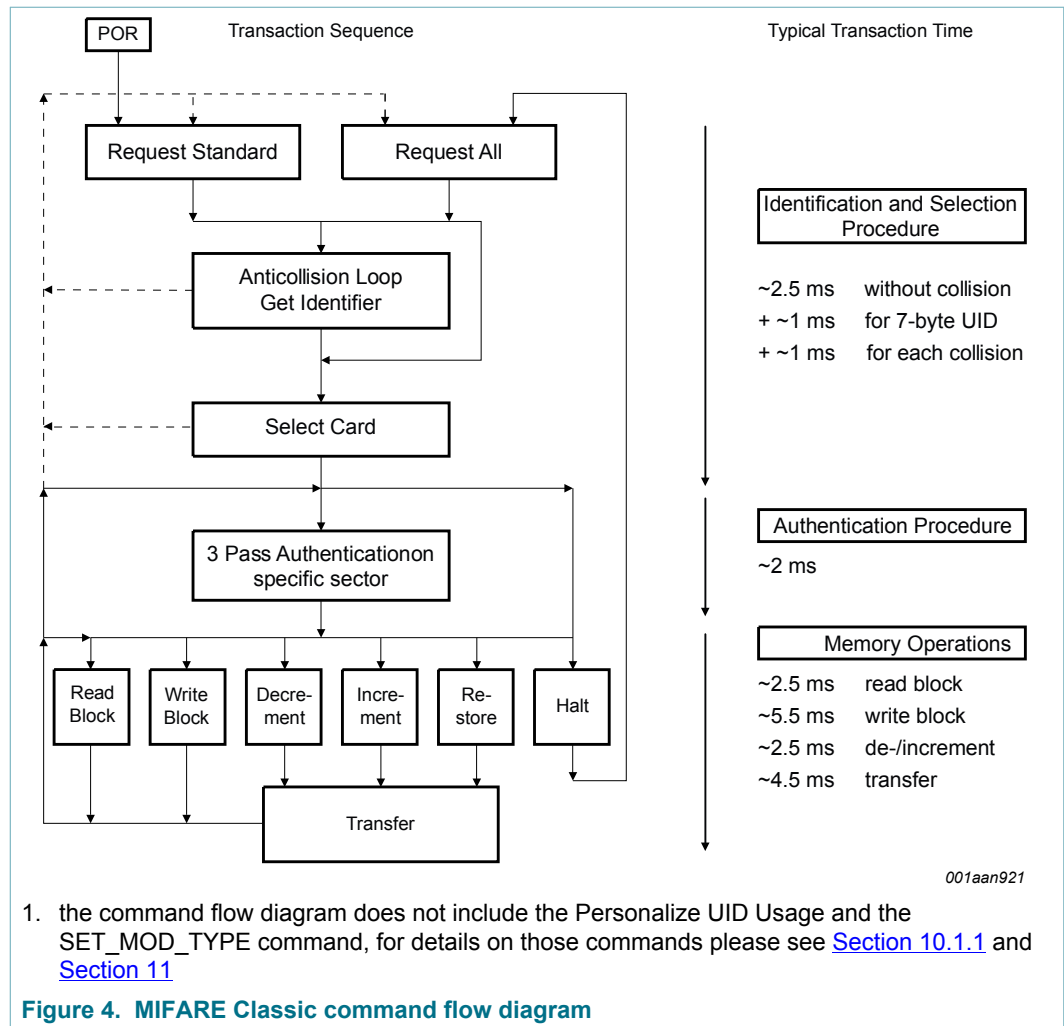
### 8.2.3 Select card

With the select card command the reader selects one individual card for authentication and memory related operations. The card returns the Select Acknowledge (SAK) code which determines the type of the selected card, see [Section 9.4](#). For further details refer to the document [Ref. 2](#).

### 8.2.4 Three pass authentication

After selection of a card the reader specifies the memory location of the following memory access and uses the corresponding key for the three pass authentication procedure. After a successful authentication all commands and responses are encrypted.

**Remark:** The HLTA command needs to be sent encrypted to the PICC after a successful authentication in order to be accepted.



### 8.2.5 Memory operations

After authentication any of the following operations may be performed:

- Read block
- Write block
- Decrement: Decrements the contents of a block and stores the result in the internal Transfer Buffer
- Increment: Increments the contents of a block and stores the result in the internal Transfer Buffer
- Restore: Moves the contents of a block into the internal Transfer Buffer
- Transfer: Writes the contents of the internal Transfer Buffer to a value block

### 8.3 Data integrity

Following mechanisms are implemented in the contactless communication link between reader and card to ensure very reliable data transmission:

- 16 bits CRC per block
- Parity bits for each byte

- Bit count checking
- Bit coding to distinguish between "1", "0" and "no information"
- Channel monitoring (protocol sequence and bit stream analysis)

#### 8.4 Three pass authentication sequence

1. The reader specifies the sector to be accessed and chooses key A or B.
2. The card reads the secret key and the access conditions from the sector trailer. Then the card sends a number as the challenge to the reader (pass one).
3. The reader calculates the response using the secret key and additional input. The response, together with a random challenge from the reader, is then transmitted to the card (pass two).
4. The card verifies the response of the reader by comparing it with its own challenge and then it calculates the response to the challenge and transmits it (pass three).
5. The reader verifies the response of the card by comparing it to its own challenge.

After transmission of the first random challenge the communication between card and reader is encrypted.

#### 8.5 RF interface

The RF-interface is according to the standard for contactless smart cards ISO/IEC 14443A.

For operation, the carrier field from the reader always needs to be present (with short pauses when transmitting), as it is used for the power supply of the card.

For both directions of data communication there is only one start bit at the beginning of each frame. Each byte is transmitted with a parity bit (odd parity) at the end. The LSB of the byte with the lowest address of the selected block is transmitted first. The maximum frame length is 163 bits (16 data bytes + 2 CRC bytes =  $16 \times 9 + 2 \times 9 + 1$  start bit).

#### 8.6 Memory organization

The  $4096 \times 8$  bit EEPROM memory is organized in 32 sectors of 4 blocks and 8 sectors of 16 blocks. One block contains 16 bytes.

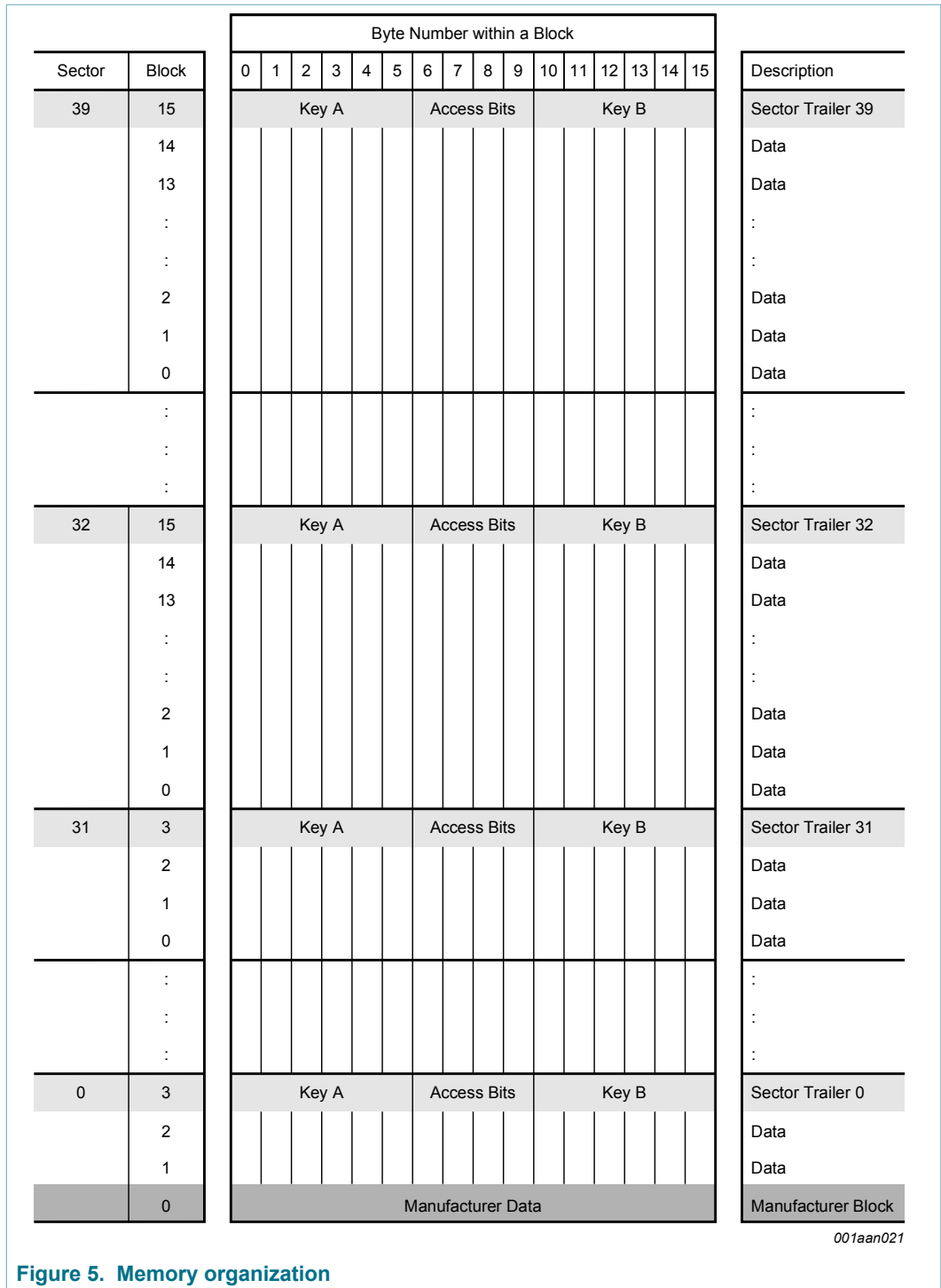


Figure 5. Memory organization

8.6.1 Manufacturer block

This is the first data block (block 0) of the first sector (sector 0). It contains the IC manufacturer data. This block is programmed and write protected in the production test. The manufacturer block is shown in Figure 6 and Figure 7 for the 4-byte NUID and 7-byte UID version respectively.



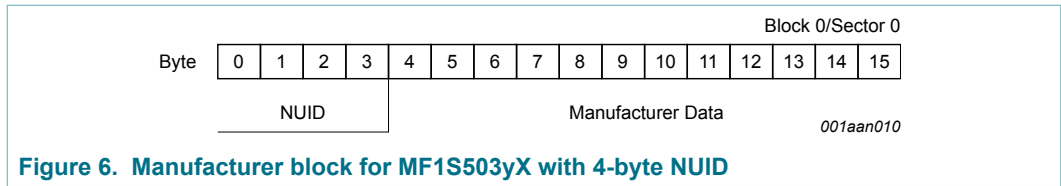


Figure 6. Manufacturer block for MF1S503yX with 4-byte NUID

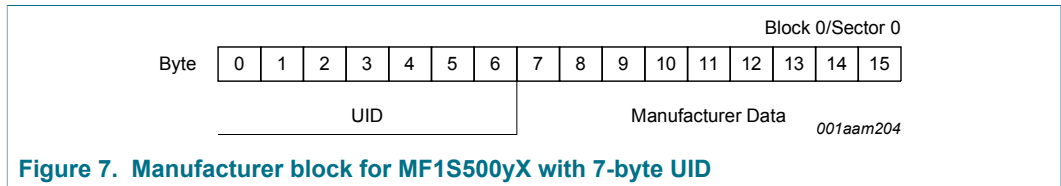


Figure 7. Manufacturer block for MF1S500yX with 7-byte UID

### 8.6.2 Data blocks

One block consists of 16 bytes. The first 32 sectors contain 3 blocks and the last 8 sectors contain 15 blocks for storing data (Sector 0 contains only two data blocks and the read-only manufacturer block).

The data blocks can be configured by the access bits as

- read/write blocks
- value blocks

Value blocks can be used for e.g. electronic purse applications, where additional commands like increment and decrement for direct control of the stored value are provided

A successful authentication has to be performed to allow any memory operation.

**Remark:** The default content of the data blocks at delivery is not defined.

#### 8.6.2.1 Value blocks

Value blocks allow performing electronic purse functions (valid commands are: read, write, increment, decrement, restore, transfer). Value blocks have a fixed data format which permits error detection and correction and a backup management.

A value block can only be generated through a write operation in value block format:

- Value: Signifies a signed 4-byte value. The lowest significant byte of a value is stored in the lowest address byte. Negative values are stored in standard 2's complement format. For reasons of data integrity and security, a value is stored three times, twice non-inverted and once inverted.
- Adr: Signifies a 1-byte address, which can be used to save the storage address of a block, when implementing a powerful backup management. The address byte is stored four times, twice inverted and non-inverted. During increment, decrement, restore and transfer operations the address remains unchanged. It can only be altered via a write command.

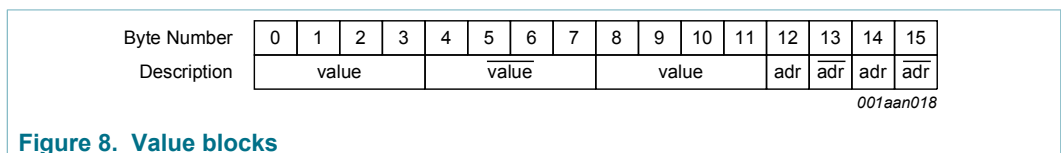


Figure 8. Value blocks

An example of a valid value block format for the decimal value 1234567d and the block address 17d is shown in Table 4. First, the decimal value has to be converted to the hexadecimal representation of 0012D687h. The LSByte of the hexadecimal value is stored in Byte 0, the MSByte in Byte 3. The bit inverted hexadecimal representation of the value is FFED2978h where the LSByte is stored in Byte 4 and the MSByte in Byte 7.

The hexadecimal value of the address in the example is 11h, the bit inverted hexadecimal value is EEh.

Table 4. Value block format example

Byte Number	0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15
Description	value				value				value				adr	adr	adr	adr
Values [hex]	87	D6	12	00	78	29	ED	FF	87	D6	12	00	11	EE	11	EE

### 8.6.3 Sector trailer

The sector trailer is always the last block in one sector. For the first 32 sectors this is block 3 and for the remaining 8 sectors it is block 15. Each sector has a sector trailer containing the

- secret keys A (mandatory) and B (optional), which return logical "0"s when read and
- the access conditions for the blocks of that sector, which are stored in bytes 6...9. The access bits also specify the type (data or value) of the data blocks.

If key B is not needed, the last 6 bytes of the sector trailer can be used as data bytes. The access bits for the sector trailer have to be configured accordingly, see Section 8.7.2.

Byte 9 of the sector trailer is available for user data. For this byte the same access rights as for byte 6, 7 and 8 apply.

When the sector trailer is read, the key bytes are blanked out by returning logical zeros. If key B is configured to be readable, the data stored in bytes 10 to 15 is returned, see Section 8.7.2.

All keys are set to FFFF FFFF FFFFh at chip delivery and the bytes 6, 7 and 8 are set to FF0780h.

Byte Number	0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15
Description	Key A						Access Bits			Key B (optional)						

*001aan013*

**Figure 9. Sector trailer**

## 8.7 Memory access

Before any memory operation can be done, the card has to be selected and authenticated as described in Section 8.2. The possible memory operations for an addressed block depend on the key used during authentication and the access conditions stored in the associated sector trailer.

Table 5. Memory operations

Operation	Description	Valid for Block Type
Read	reads one memory block	read/write, value and sector trailer

Operation	Description	Valid for Block Type
Write	writes one memory block	read/write, value and sector trailer
Increment	increments the contents of a block and stores the result in the internal Transfer Buffer	value
Decrement	decrements the contents of a block and stores the result in the internal Transfer Buffer	value
Transfer	writes the contents of the internal Transfer Buffer to a block	value and read/write
Restore	reads the contents of a block into the internal Transfer Buffer	value

**8.7.1 Access conditions**

The access conditions for every data block and sector trailer are defined by 3 bits, which are stored non-inverted and inverted in the sector trailer of the specified sector.

The access bits control the rights of memory access using the secret keys A and B. The access conditions may be altered, provided one knows the relevant key and the current access condition allows this operation.

**Remark:** With each memory access the internal logic verifies the format of the access conditions. If it detects a format violation the whole sector is irreversibly blocked.

**Remark:** In the following description the access bits are mentioned in the non-inverted mode only.

The internal logic of the MF1S70yyX/V1 ensures that the commands are executed only after a successful authentication.

**Table 6. Access conditions**

Access Bits	Valid Commands		Block (sectors 0 - 31)	Block(s) (sectors 32-39)	Description
C13 C23 C33	read, write	→	3	15	sector trailer
C12 C22 C32	read, write, increment, decrement, transfer, restore	→	2	10-14	data block(s)
C11 C21 C31	read, write, increment, decrement, transfer, restore	→	1	5-9	data block(s)
C10 C20 C30	read, write, increment, decrement, transfer, restore	→	0	0-4	data block(s)

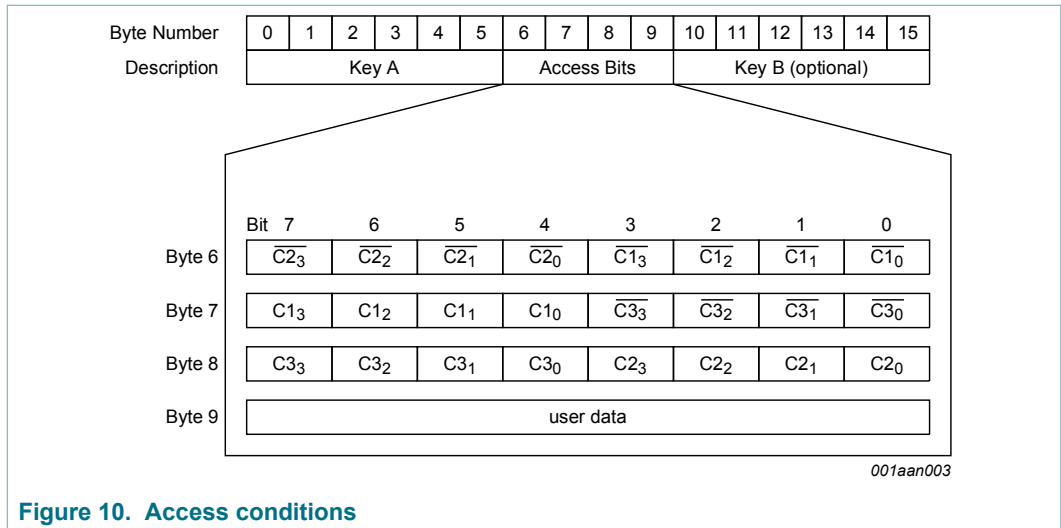


Figure 10. Access conditions

### 8.7.2 Access conditions for the sector trailer

Depending on the access bits for the sector trailer (block 3, respectively block 15) the read/write access to the keys and the access bits is specified as ‘never’, ‘key A’, ‘key B’ or key A|B’ (key A or key B).

On chip delivery the access conditions for the sector trailers and key A are predefined as transport configuration. Since key B may be read in the transport configuration, new cards must be authenticated with key A. Since the access bits themselves can also be blocked, special care has to be taken during the personalization of cards.

Table 7. Access conditions for the sector trailer

Access bits			Access condition for						Remark
C1	C2	C3	KEYA		Access bits		KEYB		
			read	write	read	write	read	write	
0	0	0	never	key A	key A	never	key A	key A	Key B may be read <sup>[1]</sup>
0	1	0	never	never	key A	never	key A	never	Key B may be read <sup>[1]</sup>
1	0	0	never	key B	key A B	never	never	key B	
1	1	0	never	never	key A B	never	never	never	
0	0	1	never	key A	key A	key A	key A	key A	Key B may be read, transport configuration <sup>[1]</sup>
0	1	1	never	key B	key A B	key B	never	key B	
1	0	1	never	never	key A B	key B	never	never	
1	1	1	never	never	key A B	never	never	never	

[1] For this access condition key B is readable and may be used for data

### 8.7.3 Access conditions for data blocks

Depending on the access bits for data blocks (blocks 0...2) the read/write access is specified as ‘never’, ‘key A’, ‘key B’ or ‘key A|B’ (key A or key B). The setting of the relevant access bits defines the application and the corresponding applicable commands.

- Read/write block: the operations read and write are allowed.
- Value block: Allows the additional value operations increment, decrement, transfer and restore. With access condition '001' only read and decrement are possible which reflects a non-rechargeable card. For access condition '110' recharging is possible by using key B.
- Manufacturer block: the read-only condition is not affected by the access bits setting!
- Key management: in transport configuration key A must be used for authentication

Table 8. Access conditions for data blocks

Access bits			Access condition for				Application
C1	C2	C3	read	write	increment	decrement, transfer, restore	
0	0	0	key A B	key A B	key A B	key A B	transport configuration <sup>[1]</sup>
0	1	0	key A B	never	never	never	read/write block <sup>[1]</sup>
1	0	0	key A B	key B	never	never	read/write block <sup>[1]</sup>
1	1	0	key A B	key B	key B	key A B	value block <sup>[1]</sup>
0	0	1	key A B	never	never	key A B	value block <sup>[1]</sup>
0	1	1	key B	key B	never	never	read/write block <sup>[1]</sup>
1	0	1	key B	never	never	never	read/write block <sup>[1]</sup>
1	1	1	never	never	never	never	read/write block

[1] If key B may be read in the corresponding Sector Trailer it cannot serve for authentication (see grey marked lines in [Table 7](#)). As a consequence, if the reader authenticates any block of a sector which uses such access conditions for the Sector Trailer and using key B, the card will refuse any subsequent memory access after authentication.

## 9 Command overview

The MIFARE Classic card activation follows the ISO/IEC 14443 Type A. After the MIFARE Classic card has been selected, it can either be deactivated using the ISO/IEC 14443 Halt command, or the MIFARE Classic commands can be performed. For more details about the card activation refer to [Ref. 4](#).

### 9.1 MIFARE Classic command overview

All MIFARE Classic commands typically use the MIFARE CRYPTO1 and require an authentication.

All available commands for the MIFARE Classic EV1 4K are shown in [Table 9](#).

Table 9. Command overview

Command	ISO/IEC 14443	Command code (hexadecimal)
Request	REQA	26h (7 bit)
Wake-up	WUPA	52h (7 bit)
Anticollision CL1	Anticollision CL1	93h 20h
Select CL1	Select CL1	93h 70h

Command	ISO/IEC 14443	Command code (hexadecimal)
Anticollision CL2	Anticollision CL2	95h 20h
Select CL2	Select CL2	95h 70h
Halt	Halt	50h 00h
Authentication with Key A	-	60h
Authentication with Key B	-	61h
Personalize UID Usage	-	40h
SET_MOD_TYPE	-	43h
MIFARE Read	-	30h
MIFARE Write	-	A0h
MIFARE Decrement	-	C0h
MIFARE Increment	-	C1h
MIFARE Restore	-	C2h
MIFARE Transfer	-	B0h

All commands use the coding and framing as described in [Ref. 3](#) and [Ref. 4](#) if not otherwise specified.

## 9.2 Timings

The timing shown in this document are not to scale and values are rounded to 1  $\mu$ s.

All given times refer to the data frames including start of communication and end of communication. A PCD data frame contains the start of communication (1 "start bit") and the end of communication (one logic 0 + 1 bit length of unmodulated carrier). A PICC data frame contains the start of communication (1 "start bit") and the end of communication (1 bit length of no subcarrier).

The minimum command response time is specified according to [Ref. 4](#) as an integer  $n$  which specifies the PCD to PICC frame delay time. The frame delay time from PICC to PCD is at least 87  $\mu$ s. The maximum command response time is specified as a time-out value. Depending on the command, the  $T_{ACK}$  value specified for command responses defines the PCD to PICC frame delay time. It does it for either the 4-bit ACK value specified in [Section 9.3](#) or for a data frame.

All command timings are according to ISO/IEC 14443-3 frame specification as shown for the Frame Delay Time in [Figure 11](#). For more details refer to [Ref. 3](#) and [Ref. 4](#).

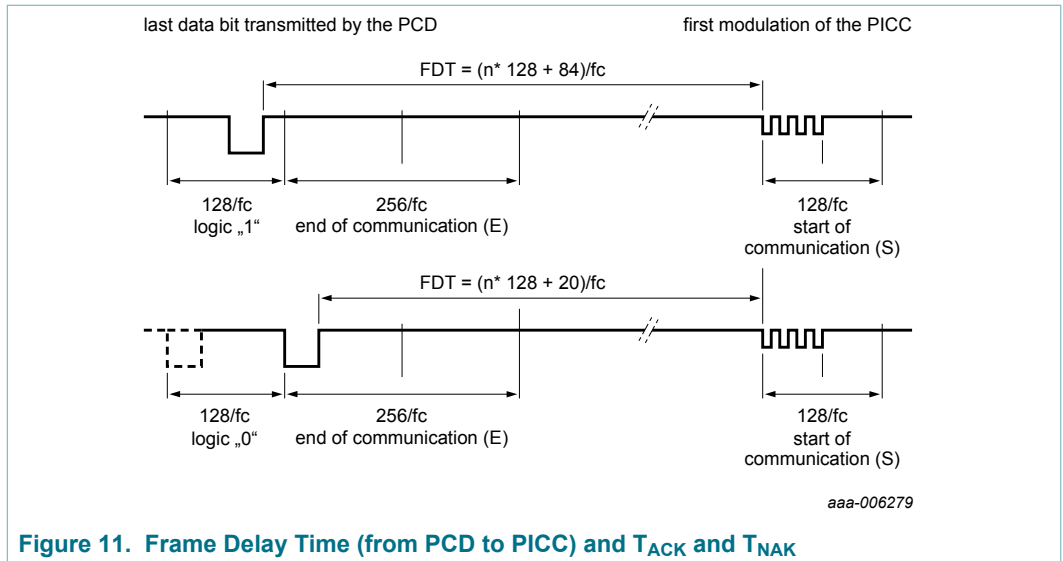


Figure 11. Frame Delay Time (from PCD to PICC) and  $T_{ACK}$  and  $T_{NAK}$

**Remark:** Due to the coding of commands, the measured timings usually excludes (a part of) the end of communication. Consider this factor when comparing the specified with the measured times.

### 9.3 MIFARE Classic ACK and NAK

The MIFARE Classic uses a 4 bit ACK / NAK as shown in [Table 10](#).

Table 10. MIFARE ACK and NAK

Code (4-bit)	Transfer Buffer Validity	Description
Ah		Acknowledge (ACK)
0h	valid	invalid operation
1h	valid	parity or CRC error
4h	invalid	invalid operation
5h	invalid	parity or CRC error

### 9.4 ATQA and SAK responses

For details on the type identification procedure please refer to [Ref. 2](#).

The MF1S70yyX/V1 answers to a REQA or WUPA command with the ATQA value shown in [Table 11](#) and to a Select CL1 command (CL2 for the 7-byte UID variant) with the SAK value shown in [Table 12](#).

**Table 11. ATQA response of the MF1S70yyX/V1**

Sales Type	Hex Value	Bit Number																
		16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	
MF1S00yX	00 44h	0	0	0	0	0	0	0	0	0	0	1	0	0	0	1	0	0
MF1S03yX	00 04h	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	0
MF1S700yX	00 42 <sub>h</sub>	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	1	0
MF1S703yX	00 02 <sub>h</sub>	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0

**Table 12. SAK response of the MF1S70yyX/V1**

Sales Type	Hex Value	Bit Number							
		8	7	6	5	4	3	2	1
MF1S70yyX/V1	18	0	0	0	1	1	0	0	0

**Remark:** The ATQA coding in bits 7 and 8 indicate the UID size according to ISO/IEC 14443 independent from the settings of the UID usage.

**Remark:** The bit numbering in the ISO/IEC 14443 starts with LSBit = bit 1, but not LSBit = bit 0. So one byte counts bit 1 to 8 instead of bit 0 to 7.

## 10 UID Options and Handling

The MF1S70yyX/V1 product family offers two delivery options for the UID which is stored in block 0 of sector 0.

- 7-byte UID
- 4-byte NUID (Non-Unique ID)

This section describes the MIFARE Classic MF1S70yyX/V1 operation when using one of the 2 UID options with respect to card selection, authentication and personalization. See also [Ref. 6](#) for details on how to handle UIDs and NUIDs with MIFARE Classic products.

### 10.1 7-byte UID Operation

All MF1S70yXDyy products are featuring a 7-byte UID. This 7-byte UID is stored in block 0 of sector 0 as shown in [Figure 7](#). The behaviour during anti-collision, selection and authentication can be configured during personalization for this UID variant.

#### 10.1.1 Personalization Options

The 7-byte UID variants of the MF1S70yyX/V1 can be operated with four different functionalities, denoted as UIDFn (UID Functionality n).



1. UIDF0: anti-collision and selection with the double size UID according to ISO/IEC 14443-3
2. UIDF1: anti-collision and selection with the double size UID according to ISO/IEC 14443-3 and optional usage of a selection process shortcut
3. UIDF2: anti-collision and selection with a single size random ID according to ISO/IEC 14443-3
4. UIDF3: anti-collision and selection with a single size NUID according to ISO/IEC 14443-3 where the NUID is calculated out of the 7-byte UID

The anti-collision and selection procedure and the implications on the authentication process are detailed in [Section 10.1.2](#) and [Section 10.1.3](#).

The default configuration at delivery is option 1 which enables the ISO/IEC 14443-3 compliant anti-collision and selection. This configuration can be changed using the 'Personalize UID Usage' command. The execution of this command requires an authentication to sector 0. Once this command has been issued and accepted by the PICC, the configuration is automatically locked. A subsequently issued 'Personalize UID Usage' command is not executed and a NAK is replied by the PICC.

**Remark:** As the configuration is changeable at delivery, it is strongly recommended to send this command at personalization of the card to prevent unwanted changes in the field. This should also be done if the default configuration is used.

**Remark:** The configuration becomes effective only after PICC unselect or PICC field reset.

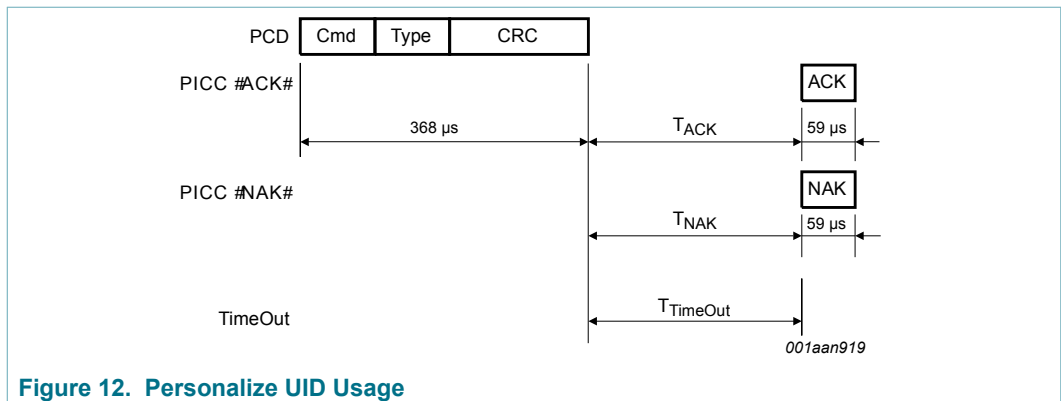


Figure 12. Personalize UID Usage

Table 13. Personalize UID Usage command

Name	Code	Description	Length
Cmd	40h	Set anti-collision, selection and authentication behaviour	1 byte
Type	-	Encoded type of UID usage: UIDF0: 00h UIDF1: 40h UIDF2: 20h UIDF3: 60h	1 byte
CRC	-	CRC according to <a href="#">Ref. 4</a>	2 bytes
ACK, NAK	see <a href="#">Table 10</a>	see <a href="#">Section 9.3</a>	4-bit

**Table 14. Personalize UID Usage timing**

	T <sub>ACK min</sub>	T <sub>ACK max</sub>	T <sub>NAK min</sub>	T <sub>NAK max</sub>	T <sub>TimeOut</sub>
Personalize UID Usage	n=9	T <sub>TimeOut</sub>	n=9	T <sub>TimeOut</sub>	10 ms

**10.1.2 Anti-collision and Selection**

Depending on the chosen personalization option there are certain possibilities to perform anti-collision and selection. To bring the MIFARE Classic into the ACTIVE state according to ISO/IEC 14443-3, the following sequences are available.

Sequence 1: ISO/IEC 14443-3 compliant anti-collision and selection using the cascade level 1 followed by the cascade level 2 SEL command

Sequence 2: using cascade level 1 anti-collision and selection procedure followed by a Read command from block 0

Sequence 3: ISO/IEC 14443-3 compliant anti-collision and selection using the cascade level 1 SEL command

**Remark:** The Read from Block 0 in Sequence 2 does not require a prior authentication to Sector 0 and is transmitted in plain data. For all other sequences, the readout from Block 0 in Sector 0 is encrypted and requires an authentication to that sector.

**Remark:** The settings done with Personalize UID Usage do not change the ATQA coding.

**Table 15. Available activation sequences for 7-byte UID options**

UID Functionality	Available Activation Sequences
UIDF0	Sequence 1
UIDF1	Sequence 1, Sequence 2
UIDF2	Sequence 3
UIDF3	Sequence 3

**10.1.3 Authentication**

During the authentication process, 4-byte of the UID are passed on to the MIFARE Classic Authenticate command of the contactless reader IC. Depending on the activation sequence, those 4-byte are chosen differently. In general, the input parameter to the MIFARE Classic Authenticate command is the set of 4 bytes retrieved during the last cascade level from the ISO/IEC 14443-3 Type A anticollision.

**Table 16. Input parameter to MIFARE Classic Authenticate**

UID Functionality	Input to MIFARE Classic Authenticate Command
Sequence 1	CL2 bytes (UID3...UID6)
Sequence 2	CL1 bytes (CT, UID0...UID2)
Sequence 3	4-byte NUID/RID (UID0...UID3)

**10.2 4-byte UID Operation**

All MF1S703yXDyy products are featuring a 4-byte NUID. This 4-byte NUID is stored in block 0 of sector 0 as shown in [Figure 6](#).

10.2.1 Anti-collision and Selection

The anti-collision and selection process for the product variants featuring 4-byte NUIDs is done according to ISO/IEC 14443-3 Type A using cascade level 1 only.

10.2.2 Authentication

The input parameter to the MIFARE Classic Authenticate command is the full 4-byte UID retrieved during the anti-collision procedure. This is the same as for the activation Sequence 3 in the 7-byte UID variant.

11 Load Modulation Strength Option

The MIFARE Classic EV1 4K features the possibility to set the load modulation strength to high or normal. The default level is set to a high modulation strength and it is recommended for optimal performance to maintain this level and only switch to the low load modulation strength if the contactless system requires it.

**Remark:** The configuration becomes effective only after a PICC unselect or a PICC field reset. The configuration can be changed multiple times by asserting the command.

**Remark:** The MIFARE Classic EV1 4K needs to be authenticated to sector 0 with Key A to perform the SET\_MOD\_TYPE command. The Access Bits for sector 0 are irrelevant.

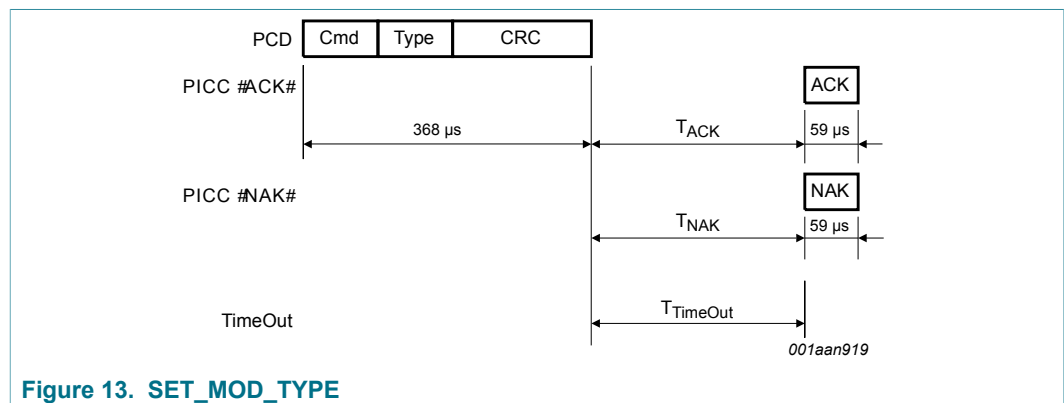


Figure 13. SET\_MOD\_TYPE

Table 17. SET\_MOD\_TYPE command

Name	Code	Description	Length
Cmd	43h	Set load modulation strength	1 byte
Type	-	Encoded load modulation strength: strong modulation: 01h (default) normal modulation: 00h	1 byte
CRC	-	CRC according to <a href="#">Ref. 4</a>	2 bytes
ACK, NAK	see <a href="#">Table 10</a>	see <a href="#">Section 9.3</a>	4-bit

Table 18. SET\_MOD\_TYPE timing

	T <sub>ACK min</sub>	T <sub>ACK max</sub>	T <sub>NAK min</sub>	T <sub>NAK max</sub>	T <sub>TimeOut</sub>
SET_MOD_TYPE	n=9	T <sub>TimeOut</sub>	n=9	T <sub>TimeOut</sub>	5 ms

The configured load modulation is shown in the manufacturer data of block 0 in sector 0. The exact location is shown below in [Figure 14](#) and [Table 19](#).

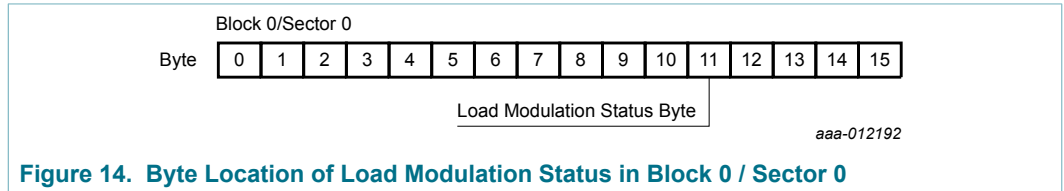


Figure 14. Byte Location of Load Modulation Status in Block 0 / Sector 0

Table 19. Load Modulation Status Indication

Load Modulation Type	Hex Value	Bit Number							
		7	6	5	4	3	2	1	0
strong load modulation	20h (default)	0	0	1	0	0	0	0	0
normal load modulation	00h	0	0	0	0	0	0	0	0

## 12 MIFARE Classic commands

### 12.1 MIFARE Authentication

The MIFARE authentication is a 3-pass mutual authentication which needs two pairs of command-response. These two parts, MIFARE authentication part 1 and part 2 are shown in [Figure 15](#), [Figure 16](#) and [Table 20](#).

[Table 21](#) shows the required timing.

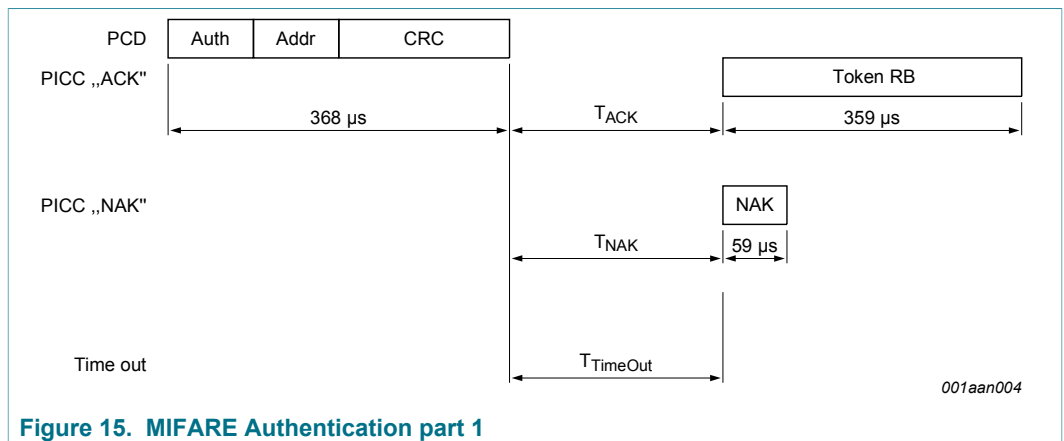


Figure 15. MIFARE Authentication part 1

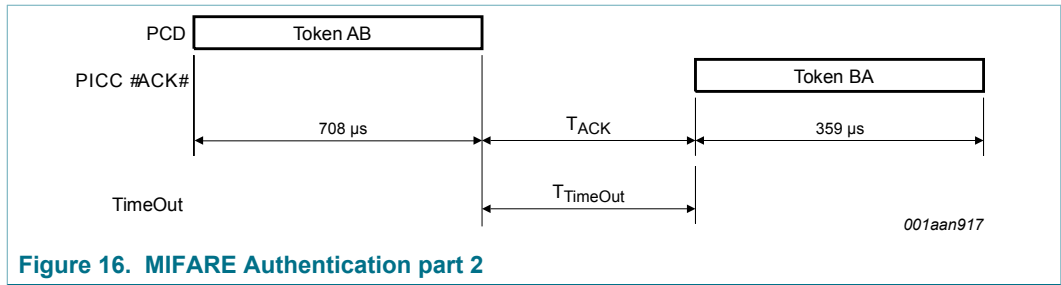


Figure 16. MIFARE Authentication part 2

Table 20. MIFARE authentication command

Name	Code	Description	Length
Auth (with Key A)	60h	Authentication with Key A	1 byte
Auth (with Key B)	61h	Authentication with Key B	1 byte
Addr	-	MIFARE Block address (00h to FFh)	1 byte
CRC	-	CRC according to <a href="#">Ref. 4</a>	2 bytes
Token RB	-	Challenge 1 (Random Number)	4 bytes
Token AB	-	Challenge 2 (encrypted data)	8 bytes
Token BA	-	Challenge 2 (encrypted data)	4 bytes
NAK	see <a href="#">Table 10</a>	see <a href="#">Section 9.3</a>	4-bit

Table 21. MIFARE authentication timing

	T <sub>ACK min</sub>	T <sub>ACK max</sub>	T <sub>NAK min</sub>	T <sub>NAK max</sub>	T <sub>TimeOut</sub>
Authentication part 1	n=9	T <sub>TimeOut</sub>	n=9	n=9	1 ms
Authentication part 2	n=9	T <sub>TimeOut</sub>			1 ms

**Remark:** The minimum required time between MIFARE Authentication part 1 and part 2 is the minimum required FDT according to [Ref. 4](#). There is no maximum time specified.

**Remark:** The MIFARE authentication and encryption requires an MIFARE reader IC (e.g. the CL RC632). For more details about the authentication command refer to the corresponding data sheet (e.g. [Ref. 5](#)). The 4-byte input parameter for the MIFARE Classic Authentication is detailed in [Section 10.1.3](#) and [Section 10.2.2](#).

## 12.2 MIFARE Read

The MIFARE Read requires a block address, and returns the 16 bytes of one MIFARE Classic block. The command structure is shown in [Figure 17](#) and [Table 22](#).

[Table 23](#) shows the required timing.

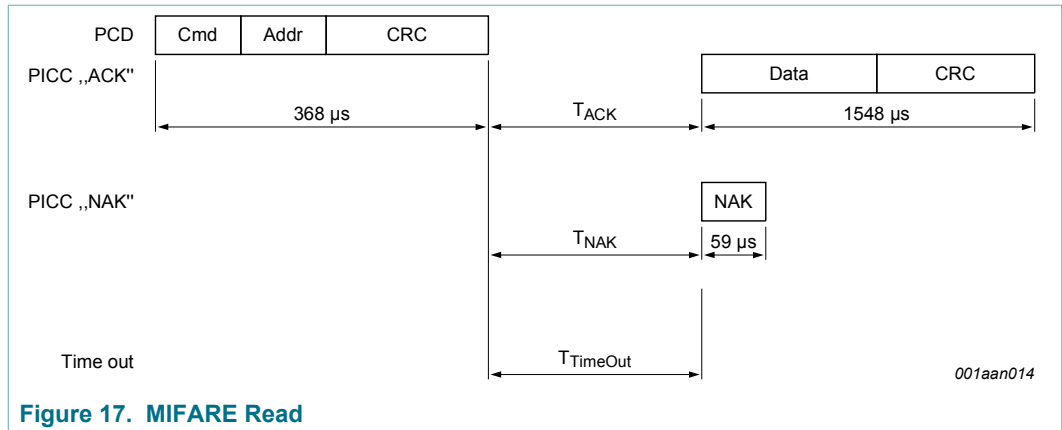


Figure 17. MIFARE Read

Table 22. MIFARE Read command

Name	Code	Description	Length
Cmd	30h	Read one block	1 byte
Addr	-	MIFARE Block address (00h to FFh)	1 byte
CRC	-	CRC according to <a href="#">Ref. 4</a>	2 bytes
Data	-	Data content of the addressed block	16 bytes
NAK	see <a href="#">Table 10</a>	see <a href="#">Section 9.3</a>	4-bit

Table 23. MIFARE Read timing

	T <sub>ACK min</sub>	T <sub>ACK max</sub>	T <sub>NAK min</sub>	T <sub>NAK max</sub>	T <sub>TimeOut</sub>
Read	n=9	T <sub>TimeOut</sub>	n=9	T <sub>TimeOut</sub>	5 ms

### 12.3 MIFARE Write

The MIFARE Write requires a block address, and writes 16 bytes of data into the addressed MIFARE Classic EV1 4K block. It needs two pairs of command-response. These two parts, MIFARE Write part 1 and part 2 are shown in [Figure 18](#) and [Figure 19](#) and [Table 24](#).

[Table 25](#) shows the required timing.

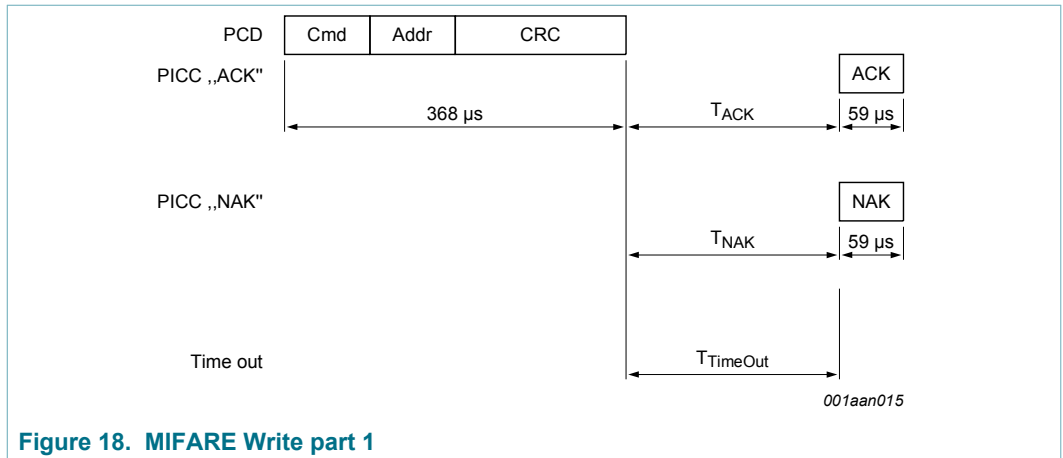


Figure 18. MIFARE Write part 1

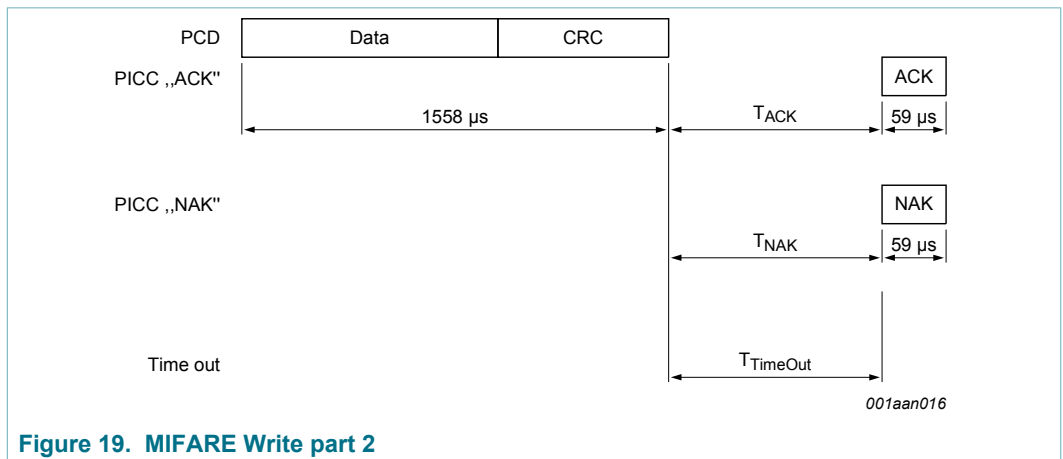


Figure 19. MIFARE Write part 2

Table 24. MIFARE Write command

Name	Code	Description	Length
Cmd	A0h	Write one block	1 byte
Addr	-	MIFARE Block or Page address (00h to FFh)	1 byte
CRC	-	CRC according to <a href="#">Ref. 4</a>	2 bytes
Data	-	Data	16 bytes
NAK	see <a href="#">Table 10</a>	see <a href="#">Section 9.3</a>	4-bit

Table 25. MIFARE Write timing

	$T_{ACK\ min}$	$T_{ACK\ max}$	$T_{NAK\ min}$	$T_{NAK\ max}$	$T_{TimeOut}$
Write part 1	n=9	$T_{TimeOut}$	n=9	$T_{TimeOut}$	5 ms
Write part 2	n=9	$T_{TimeOut}$	n=9	$T_{TimeOut}$	10 ms

**Remark:** The minimum required time between MIFARE Write part 1 and part 2 is the minimum required FDT according to [Ref. 4](#). There is no maximum time specified.

### 12.4 MIFARE Increment, Decrement and Restore

The MIFARE Increment requires a source block address and an operand. It adds the operand to the value of the addressed block, and stores the result in the Transfer Buffer.

The MIFARE Decrement requires a source block address and an operand. It subtracts the operand from the value of the addressed block, and stores the result in the Transfer Buffer.

The MIFARE Restore requires a source block address. It copies the value of the addressed block into the Transfer Buffer. The 4 byte Operand in the second part of the command is not used and may contain arbitrary values.

All three commands are responding with a NAK to the first command part if the addressed block is not formatted to be a valid value block, see [Section 8.6.2.1](#).

The two parts of each command are shown in [Figure 20](#) and [Figure 21](#) and [Table 26](#).

[Table 27](#) shows the required timing.

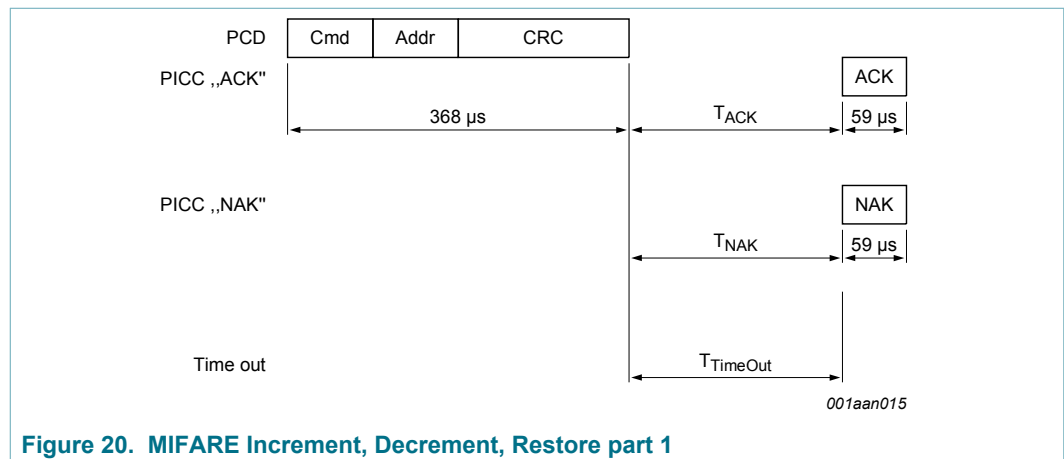
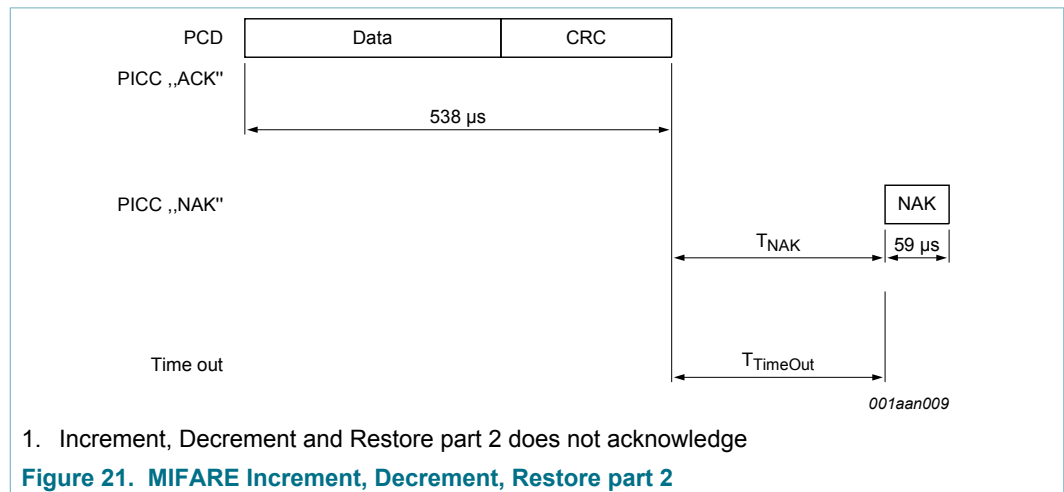


Figure 20. MIFARE Increment, Decrement, Restore part 1



1. Increment, Decrement and Restore part 2 does not acknowledge

Figure 21. MIFARE Increment, Decrement, Restore part 2



Table 26. MIFARE Increment, Decrement and Restore command

Name	Code	Description	Length
Cmd	C1h	Increment	1 byte
Cmd	C0h	Decrement	1 byte
Cmd	C2h	Restore	1 byte
Addr	-	MIFARE source block address (00h to FFh)	1 byte
CRC	-	CRC according to <a href="#">Ref. 4</a>	2 bytes
Data	-	Operand (4 byte signed integer)	4 bytes
NAK	see <a href="#">Table 10</a>	see <a href="#">Section 9.3</a>	4-bit

Table 27. MIFARE Increment, Decrement and Restore timing

	T <sub>ACK min</sub>	T <sub>ACK max</sub>	T <sub>NAK min</sub>	T <sub>NAK max</sub>	T <sub>TimeOut</sub>
Increment, Decrement, and Restore part 1	n=9	T <sub>TimeOut</sub>	n=9	T <sub>TimeOut</sub>	5 ms
Increment, Decrement, and Restore part 2	n=9	T <sub>TimeOut</sub>	n=9	T <sub>TimeOut</sub>	5 ms

**Remark:** The minimum required time between MIFARE Increment, Decrement, and Restore part 1 and part 2 is the minimum required FDT according to [Ref. 4](#). There is no maximum time specified.

**Remark:** The MIFARE Increment, Decrement, and Restore commands require a MIFARE Transfer to store the value into a destination block.

**Remark:** The MIFARE Increment, Decrement, and Restore command part 2 does not provide an acknowledgement, so the regular time out has to be used instead.

## 12.5 MIFARE Transfer

The MIFARE Transfer requires a destination block address, and writes the value stored in the Transfer Buffer into one MIFARE Classic block. The command structure is shown in [Figure 22](#) and [Table 28](#).

[Table 29](#) shows the required timing.

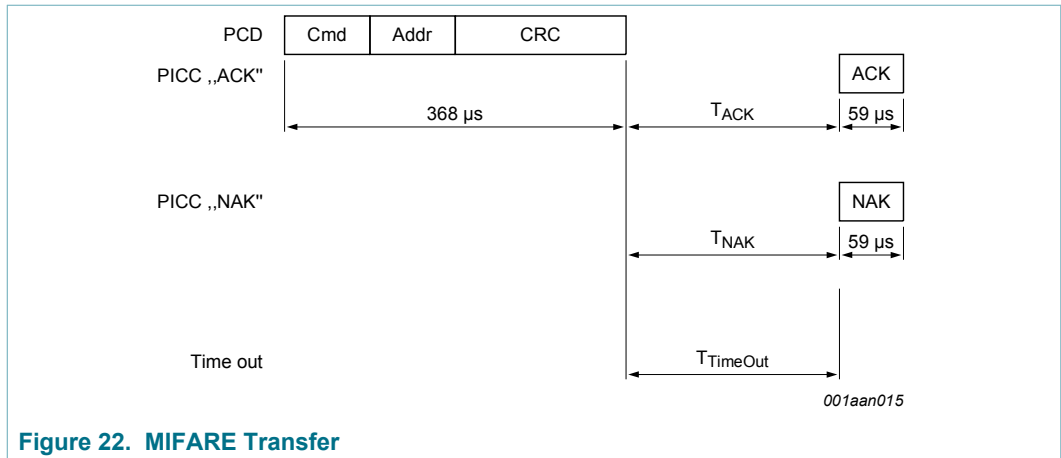


Figure 22. MIFARE Transfer

Table 28. MIFARE Transfer command

Name	Code	Description	Length
Cmd	B0h	Write the value from the Transfer Buffer into destination block	1 byte
Addr	-	MIFARE destination block address (00h to FFh)	1 byte
CRC	-	CRC according to <a href="#">Ref. 4</a>	2 bytes
NAK	see <a href="#">Table 10</a>	see <a href="#">Section 9.3</a>	4-bit

Table 29. MIFARE Transfer timing

	T <sub>ACK min</sub>	T <sub>ACK max</sub>	T <sub>NAK min</sub>	T <sub>NAK max</sub>	T <sub>TimeOut</sub>
Transfer	n=9	T <sub>TimeOut</sub>	n=9	T <sub>TimeOut</sub>	10 ms

### 13 Limiting values

Stresses above one or more of the limiting values may cause permanent damage to the device. Exposure to limiting values for extended periods may affect device reliability.

Table 30. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Min	Max	Unit
I <sub>I</sub>	input current	-	30	mA
P <sub>tot</sub> /pack	total power dissipation per package	-	120	mW
T <sub>stg</sub>	storage temperature	-55	125	°C
T <sub>amb</sub>	ambient temperature	-25	70	°C
V <sub>ESD</sub>	electrostatic discharge voltage on LA/LB <sup>[1]</sup>	2	-	kV

[1] ANSI/ESDA/JEDEC JS-001; Human body model: C = 100 pF, R = 1.5 kΩ

**CAUTION**

This device has limited built-in ElectroStatic Discharge (ESD) protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the gates.

## 14 Characteristics

Table 31. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$C_i$	input capacitance		[1]	14.9	16.9	19.0	pF
$f_i$	input frequency			-	13.56	-	MHz
<b>EEPROM characteristics</b>							
$t_{ret}$	retention time	$T_{amb} = 22\text{ °C}$		10	-	-	year
$N_{endu(W)}$	write endurance	$T_{amb} = 22\text{ °C}$		100000	200000	-	cycle

[1]  $T_{amb}=22\text{ °C}$ ,  $f=13,56\text{MHz}$ ,  $V_{LaLb} = 1,5\text{ V RMS}$

## 15 Wafer specification

For more details on the wafer delivery forms see [Ref. 9](#).

Table 32. Wafer specifications MF1S70yyXDUy

<b>Wafer</b>	
diameter	200 mm typical (8 inches) 300 mm typical (12 inches)
maximum diameter after foil expansion	210 mm (8 inches) not applicable (12 inches)
die separation process	laser dicing (8 inches) blade dicing (12 inches)
thickness MF1S70yyXDUD	120 $\mu\text{m} \pm 15\ \mu\text{m}$
MF1S70yyXDUF	75 $\mu\text{m} \pm 10\ \mu\text{m}$
flatness	not applicable
Potential Good Dies per Wafer (PGDW)	64727 (8 inches) 147540 (12 inches)
<b>Wafer backside</b>	
material	Si
treatment	ground and stress relieve
roughness	$R_a$ max = 0.5 $\mu\text{m}$ $R_t$ max = 5 $\mu\text{m}$
<b>Chip dimensions</b>	
step size <sup>[1]</sup>	x = 658 $\mu\text{m}$ (8 inches) x = 660 $\mu\text{m}$ (12 inches)

	y = 713 $\mu\text{m}$ (8 inches) y = 715 $\mu\text{m}$ (12 inches)
gap between chips <sup>[1]</sup>	typical = 19 $\mu\text{m}$ minimum = 5 $\mu\text{m}$ not applicable (12 inches)
<b>Passivation</b>	
type	sandwich structure
material	PSG / nitride
thickness	500 nm / 600 nm
<b>Au bump (substrate connected to VSS)</b>	
material	> 99.9 % pure Au
hardness	35 to 80 HV 0.005
shear strength	> 70 MPa
height	18 $\mu\text{m}$
height uniformity	within a die = $\pm 2 \mu\text{m}$
	within a wafer = $\pm 3 \mu\text{m}$
	wafer to wafer = $\pm 4 \mu\text{m}$
flatness	minimum = $\pm 1.5 \mu\text{m}$
size	LA, LB, VSS, TEST <sup>[2]</sup> = 66 $\mu\text{m}$ $\times$ 66 $\mu\text{m}$
size variation	$\pm 5 \mu\text{m}$
under bump metallization	sputtered TiW

[1] The step size and the gap between chips may vary due to changing foil expansion

[2] Pads VSS and TESTIO are disconnected when wafer is sawn.

## 15.1 Fail die identification

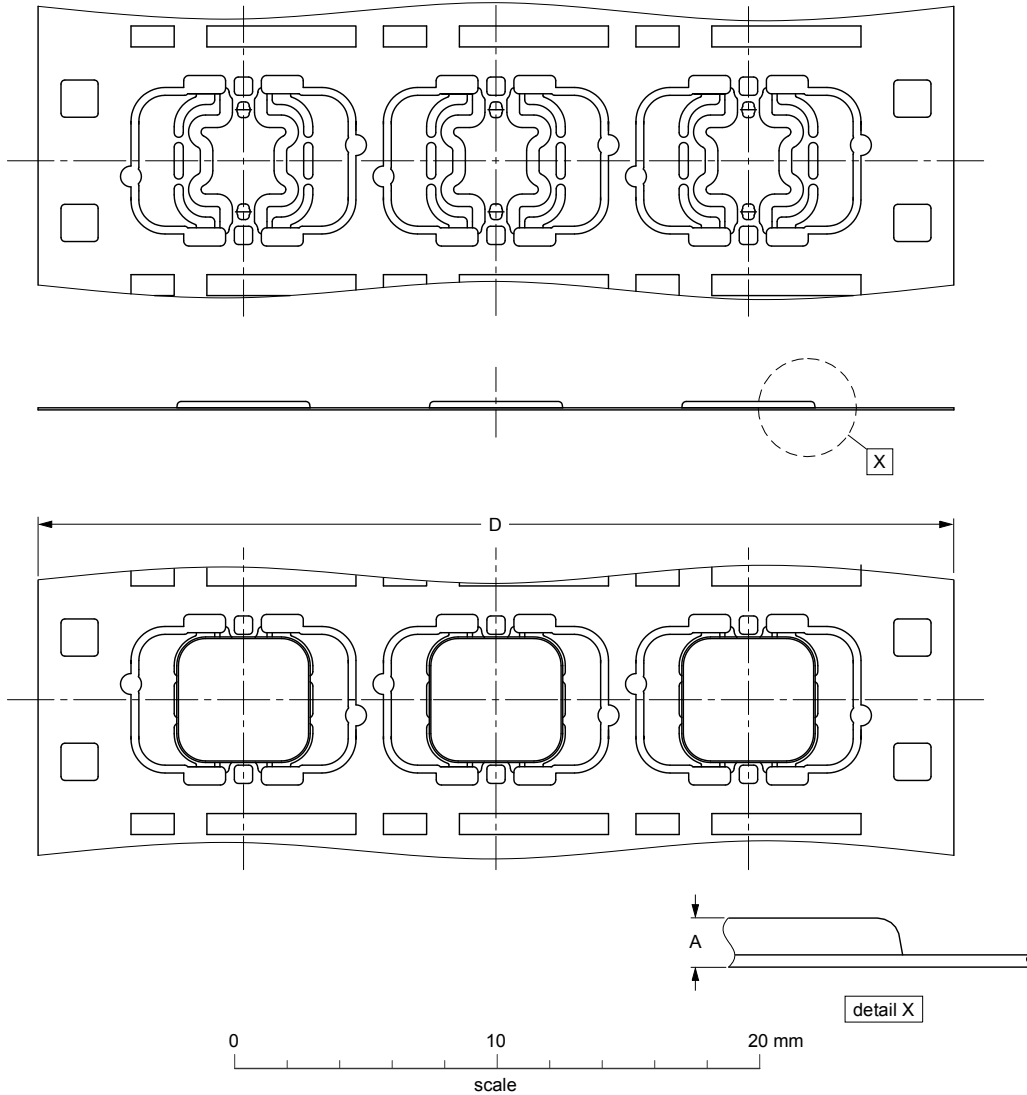
Electronic wafer mapping covers the electrical test results and additionally the results of mechanical/visual inspection. No ink dots are applied.

## 15.2 Package outline

For more details on the contactless modules MOA4 and MOA8 please refer to [Ref. 7](#) and [Ref. 8](#).

PLLMC: plastic leadless module carrier package; 35 mm wide tape

SOT500-2



**DIMENSIONS (mm are the original dimensions)**

UNIT	A <sup>(1)</sup> max.	D	For unspecified dimensions see PLLMC-drawing given in the subpackage code.
mm	0.33	35.05 34.95	

**Note**

1. Total package thickness, exclusive punching burr.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT500-2	---	---	---		03-09-17 06-05-22

Figure 23. Package outline SOT500-2

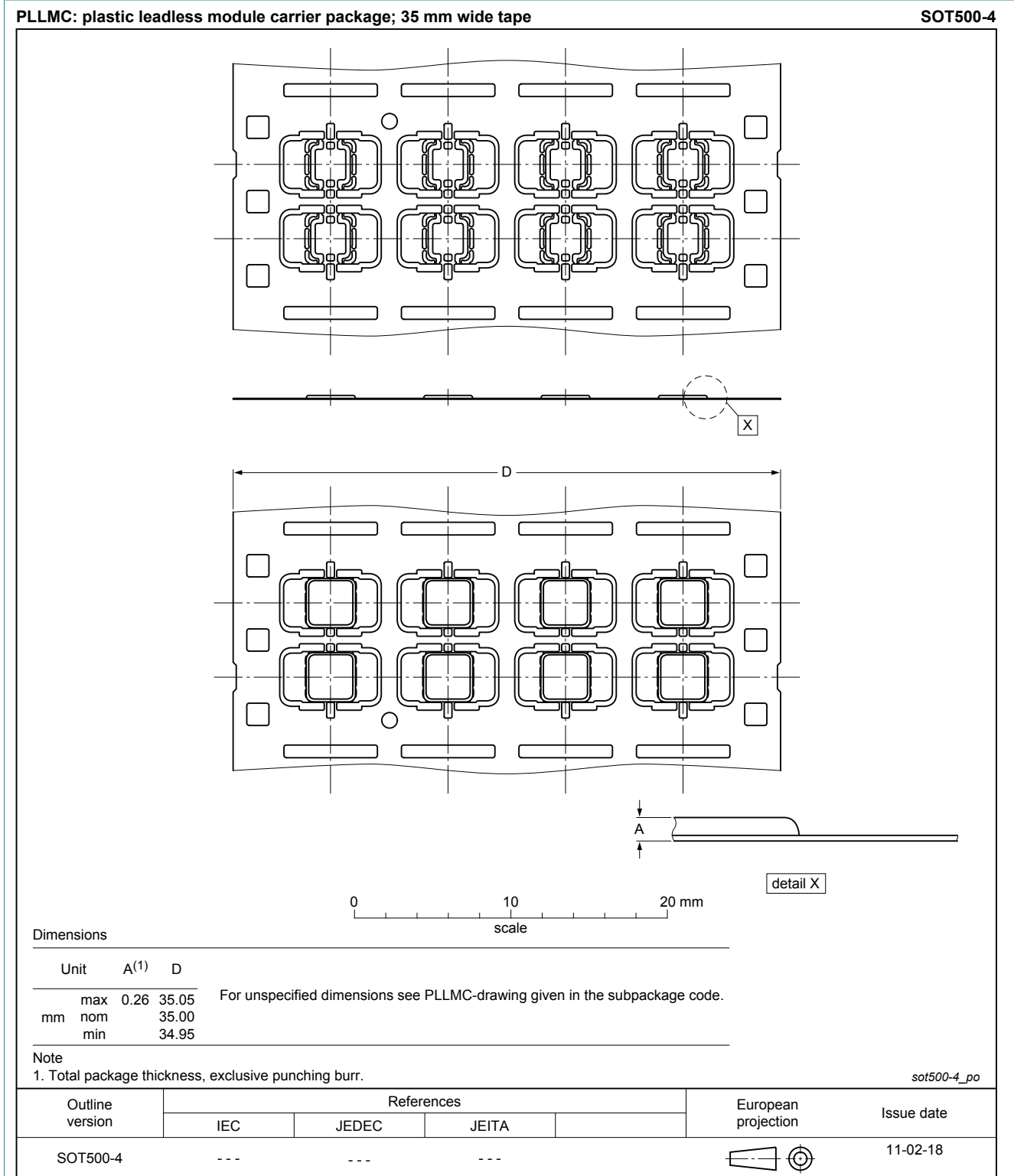
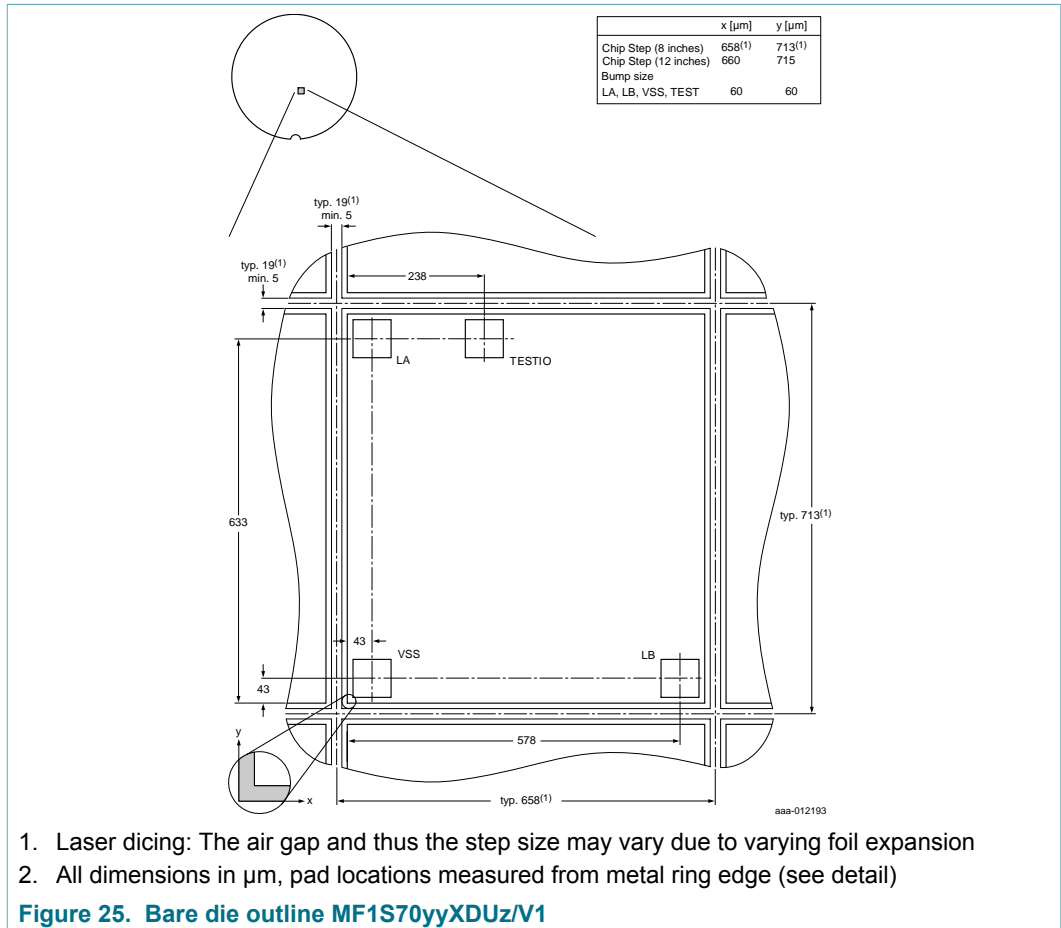


Figure 24. Package outline SOT500-4

## 16 Bare die outline

For more details on the wafer delivery forms, see [Ref. 9](#).



## 17 Abbreviations

Table 33. Abbreviations and symbols

Acronym	Description
ACK	ACKnowledge
ATQA	Answer To reQuest, Type A
CRC	Cyclic Redundancy Check
CT	Cascade Tag (value 88h) as defined in ISO/IEC 14443-3 Type A
EEPROM	Electrically Erasable Programmable Read-Only Memory
FDT	Frame Delay Time
FFC	Film Frame Carrier
IC	Integrated Circuit
LCR	L = inductance, Capacitance, Resistance (LCR meter)
LSB	Least Significant Bit

Acronym	Description
NAK	Not AcKnowledge
NUID	Non-Unique IDentifier
NV	Non-Volatile memory
PCD	Proximity Coupling Device (Contactless Reader)
PICC	Proximity Integrated Circuit Card (Contactless Card)
REQA	REQuest command, Type A
RID	Random ID
RF	Radio Frequency
RMS	Root Mean Square
RNG	Random Number Generator
SAK	Select AcKnowledge, type A
SECS-II	SEMI Equipment Communications Standard part 2
TiW	Titanium Tungsten
UID	Unique IDentifier
WUPA	Wake-Up Protocol type A

## 18 References

[1]

### MIFARE (Card) Coil Design Guide

Application note, BU-ID Document number 0117\*\*<sup>1</sup>

[2]

### MIFARE Type Identification Procedure

Application note, BU-ID Document number 0184\*\*<sup>1</sup>

[3]

### ISO/IEC 14443-2

2001

[4]

### ISO/IEC 14443-3

2001

[5]

### MIFARE & I-CODE CLRC632 Multiple protocol contactless reader IC

Product data sheet

[6]

### MIFARE and handling of UIDs

<sup>1</sup> \*\* ... document version number



Application note, BU-ID Document number 1907\*\*<sup>1</sup>

[7]

**Contactless smart card module specification MOA4**

Delivery Type Description, BU-ID Document number 0823\*\*<sup>1</sup>

[8]

**Contactless smart card module specification MOA8**

Delivery Type Description, BU-ID Document number 1636\*\*<sup>1</sup>

[9]

**General specification for 8" wafer on UV-tape with electronic fail die marking; delivery types**

Delivery Type Description, BU-ID Document number 1093\*\*<sup>1</sup>

## 19 Revision history

Table 34. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
MF1S70yyX_V1 v.3.2	20171127	Product data sheet	-	MF1S70yyX_V1 v.3.1
Modifications:	<ul style="list-style-type: none"> <li>• 12 inch FFC delivery forms added</li> <li>• Format updated</li> </ul>			
MF1S70yyX_V1 v.3.1	20140908	Product data sheet	-	MF1S70yyX_V1 v.3.0
Modifications:	<ul style="list-style-type: none"> <li>• NXP originality check support only for 1 kB memory version</li> <li>• Wafer delivery specification reference corrected</li> </ul>			
MF1S70yyX_V1 v.3.0	20140303	Product data sheet	-	-

## 20 Legal information

### 20.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions".
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**MIFARE Classic EV1 4K - Mainstream contactless smart card IC for fast and easy solution development**

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